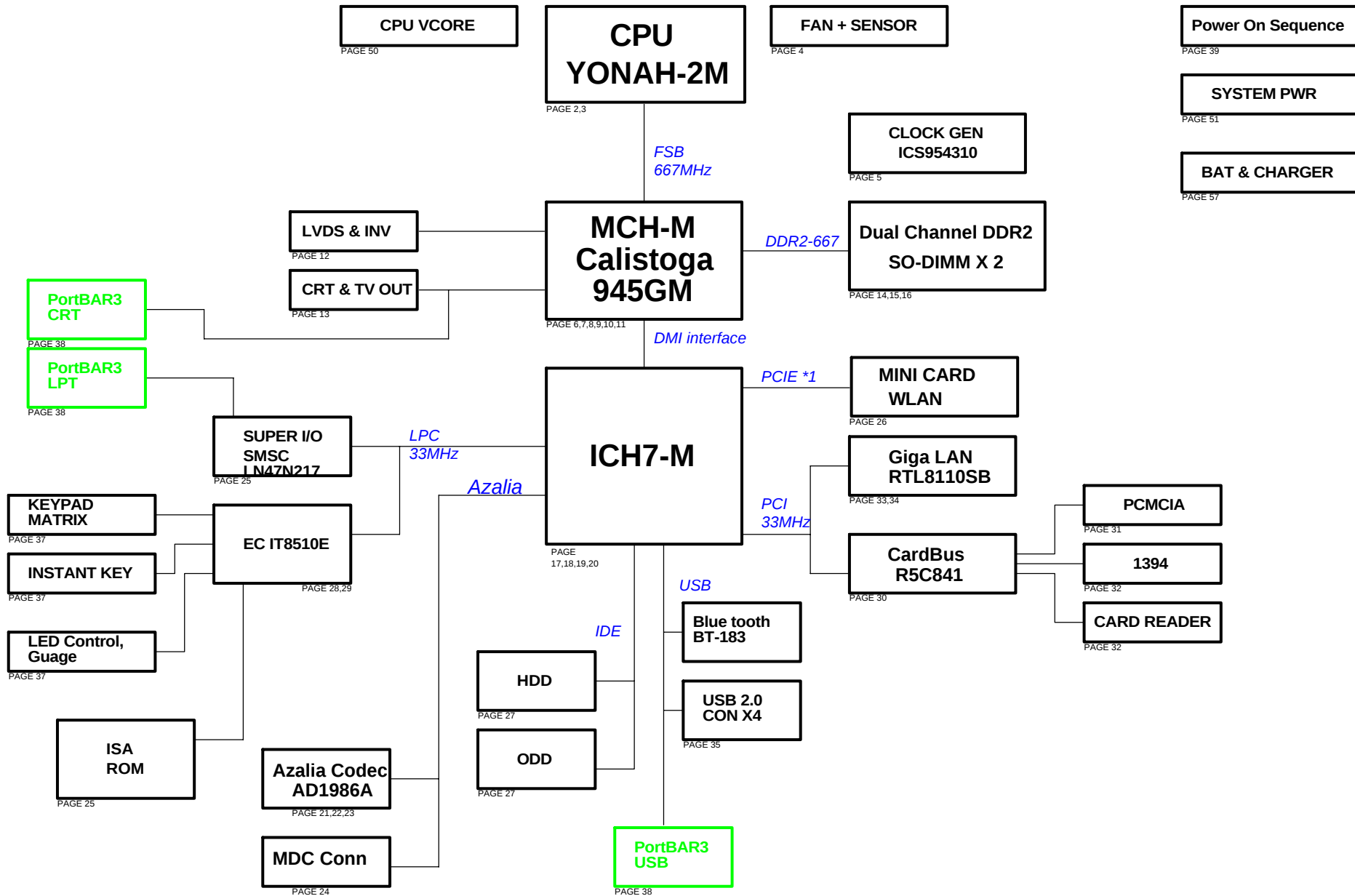
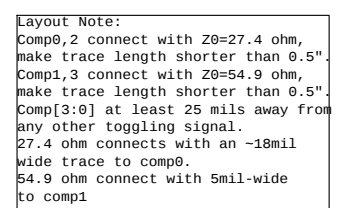
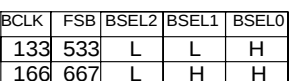


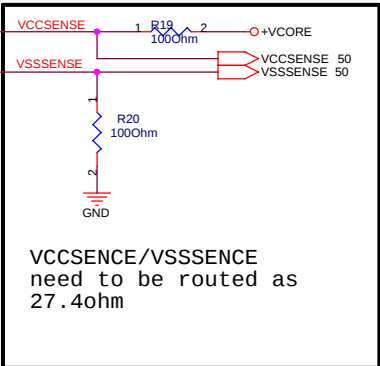
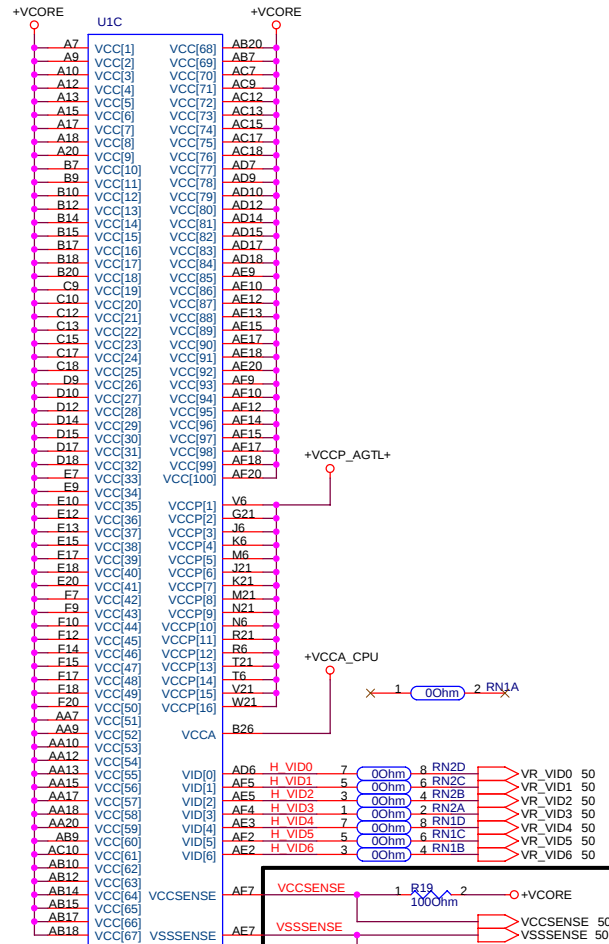
Z62FM Block Diagram





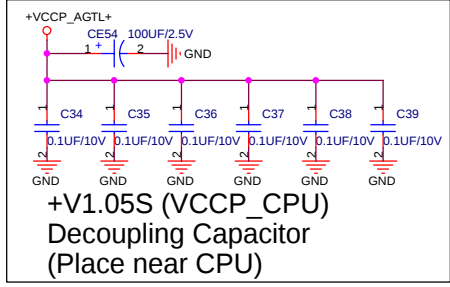
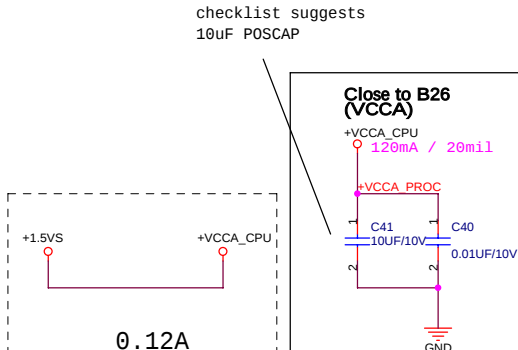
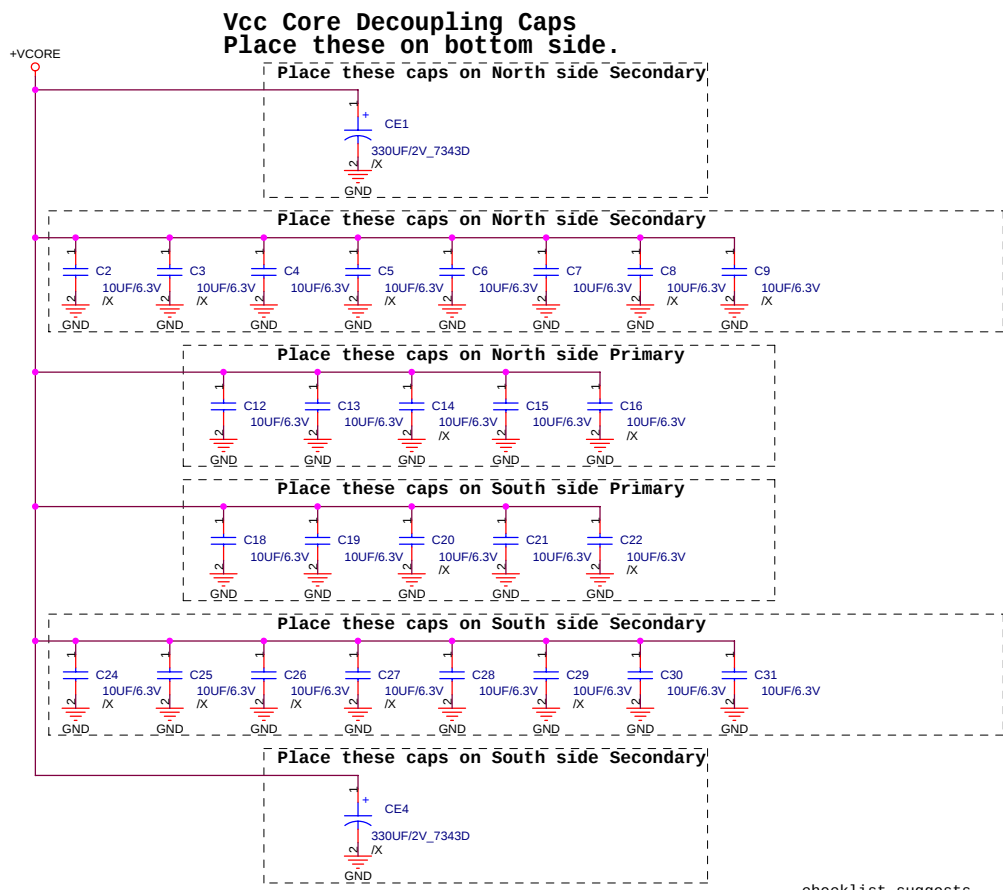
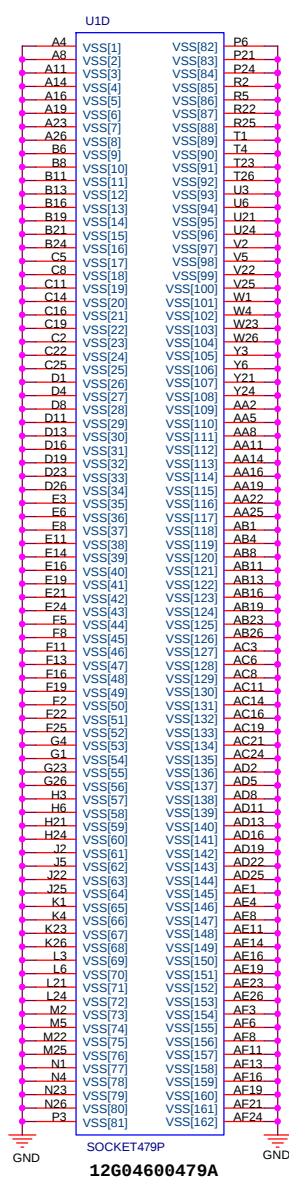
YUNAH	FSB667	LFM	TYP	HFM
VCC	1.14V	1.2V	1.356V	
C4		C3	C0	
ICC	0.9A	7.59A	27A	

YUNAH	FSB667	Min	Typ	Max
VCCP	0.997V	1.05V	1.102V	
ICCP				2.5A



Layout note:Route VCCSENSE and VSSSENSE trace at 27.4 ohm with 25 mils spacing mismatch and 18mils trace on 7mils spacing.

Place pull-up/down resistors within 1 inch of CPU.



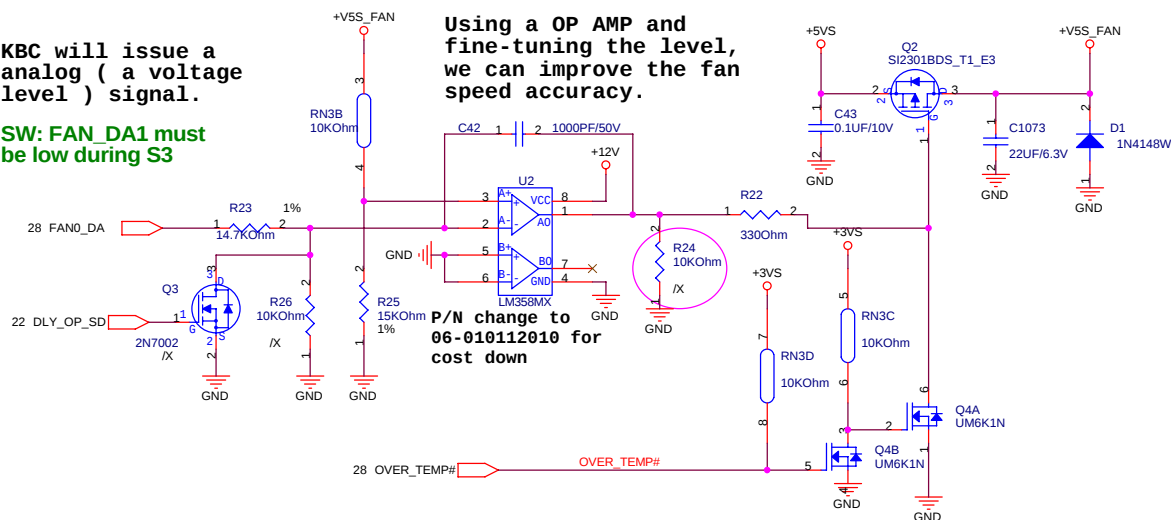
Fan Speed Control

KBC will issue a analog (a voltage level) signal.

SW: FAN_DA1 must be low during S3

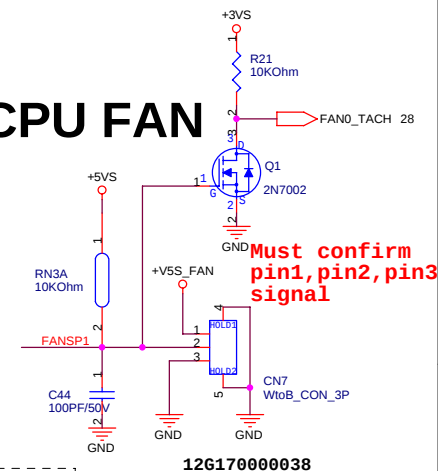
Using a OP AMP and fine-tuning the level, we can improve the fan speed accuracy.

P/N change to 06-010112010 for cost down



When fan speed is very slow, after RC integrator the level of FANSP1 will be very low that may make south bridge do the wrong detection.

CPU FAN

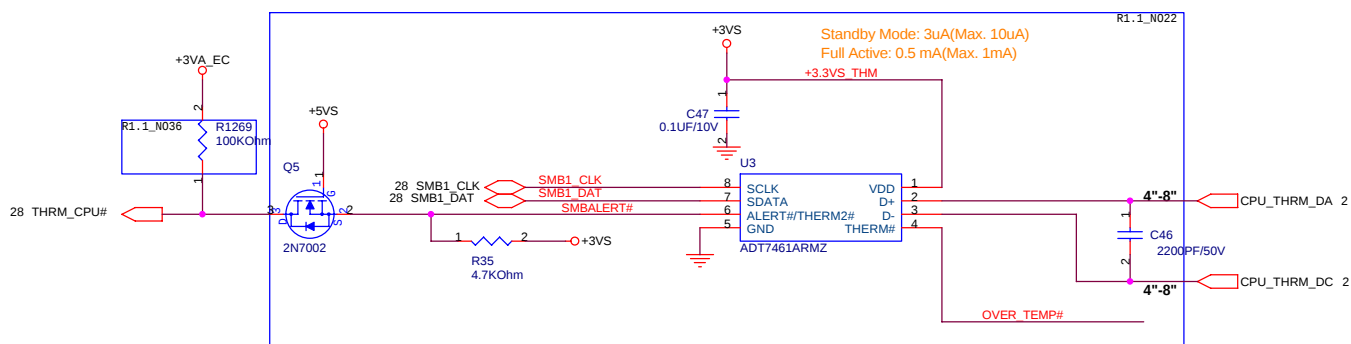
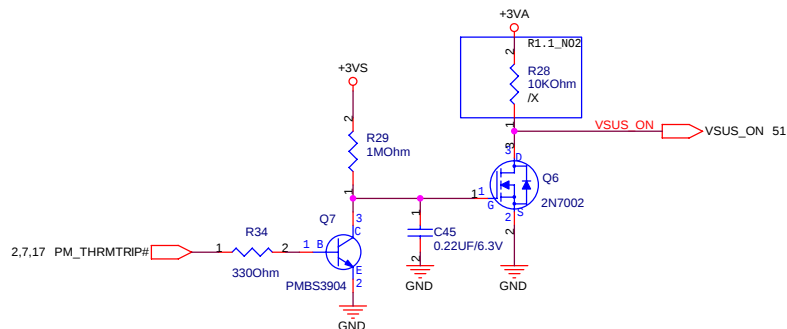


Must confirm pin1, pin2, pin3 signal

12G170000038

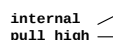
+V CORE	+V CORE	3.50
+12V	+12V	35,36,61
+5VS	+5VS	13,19,20,21,22,27,36,37,38,50,61
+3VS	+3VS	5,7,9,11,12,13,14,15,19,20,21,22,24,25,26,27,28,30,36,39,50,52,60,61
+3VA	+3VA	12,20,22,24,25,28,29,39,54,59,63

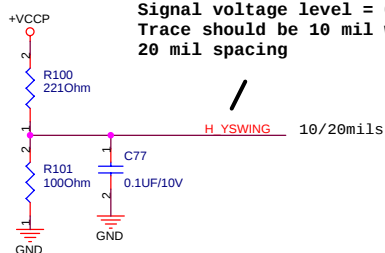
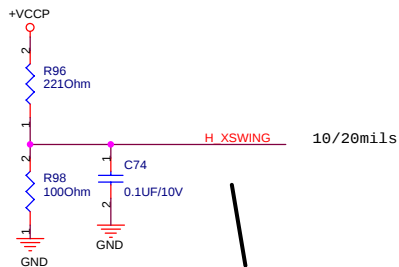
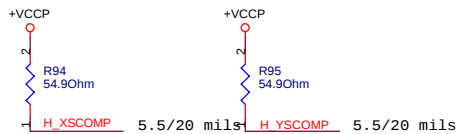
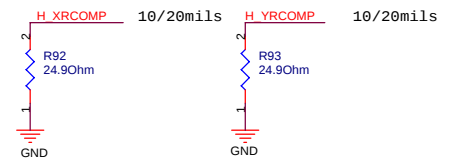
U6 output maximum will be 10.5V (VCC-1.5V) which will damage south bridge. Add a MOS to transfer it to +3V level.



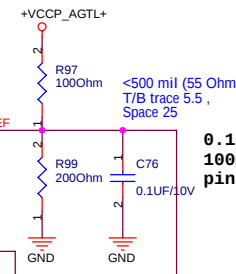
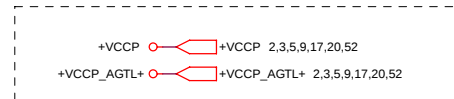
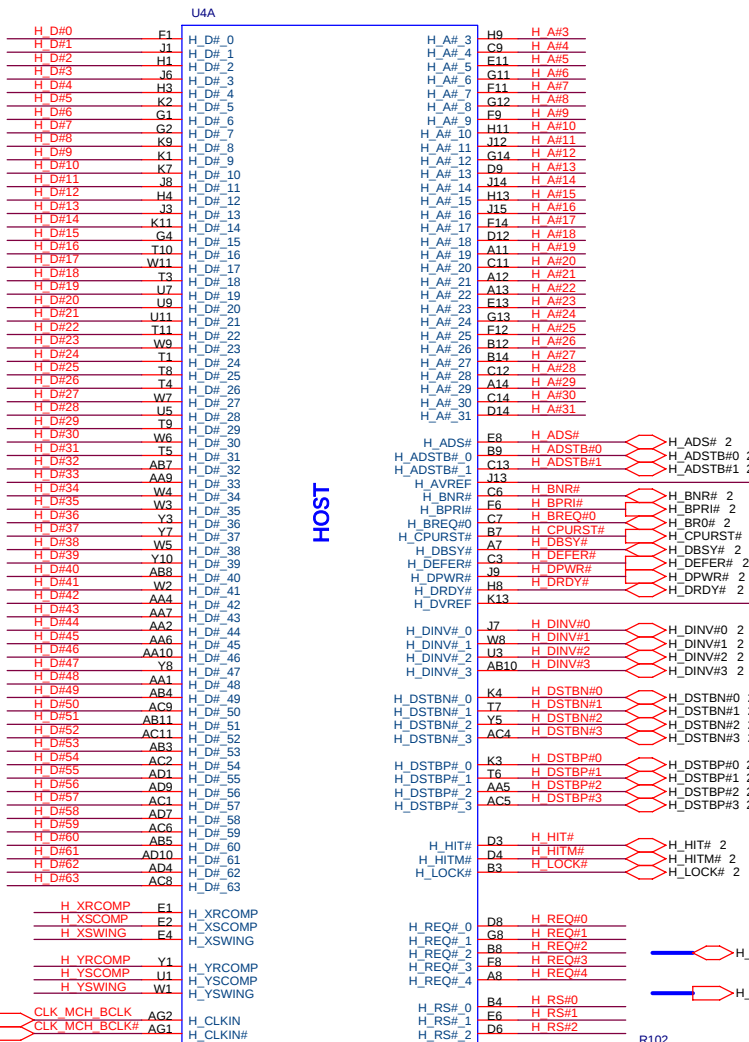
Route H_THERMDA and H_THERMDC on the same layer

-----OTHER SIGNALS
12 mils
=====GND
10 mils
=====H_THERMDA(10 mils)
10 mils
=====H_THERMDC(10 mils)
10 mils
=====GND
12 mils
-----OTHER SIGNALS
Avoid BPSB,Power

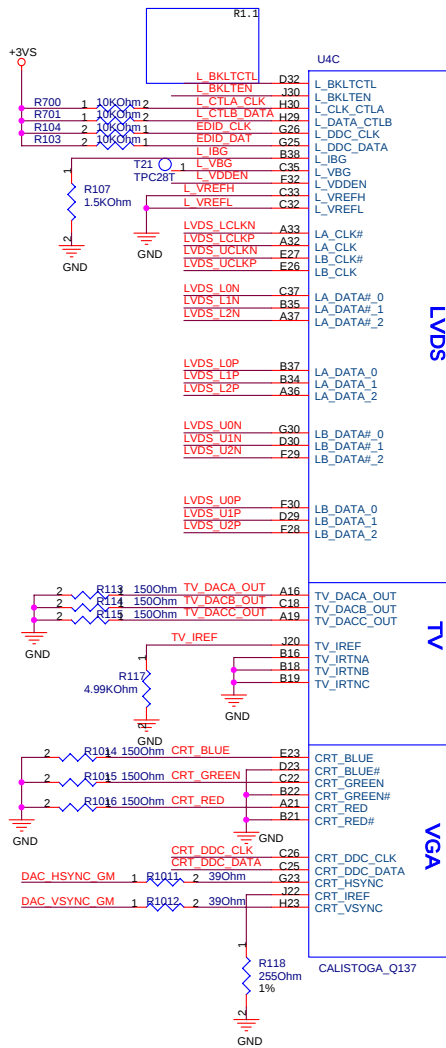




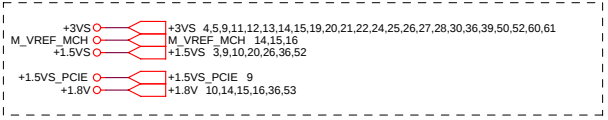
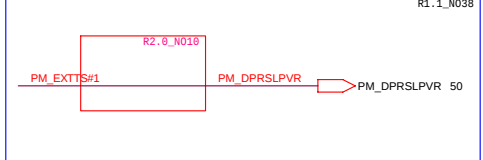
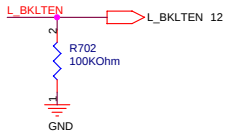
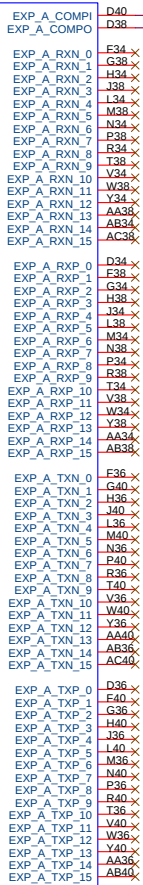
2 H_D#[0..63] H_A#[31..3] 2



0.1uF should be placed 100mils or less from GMCH pin.



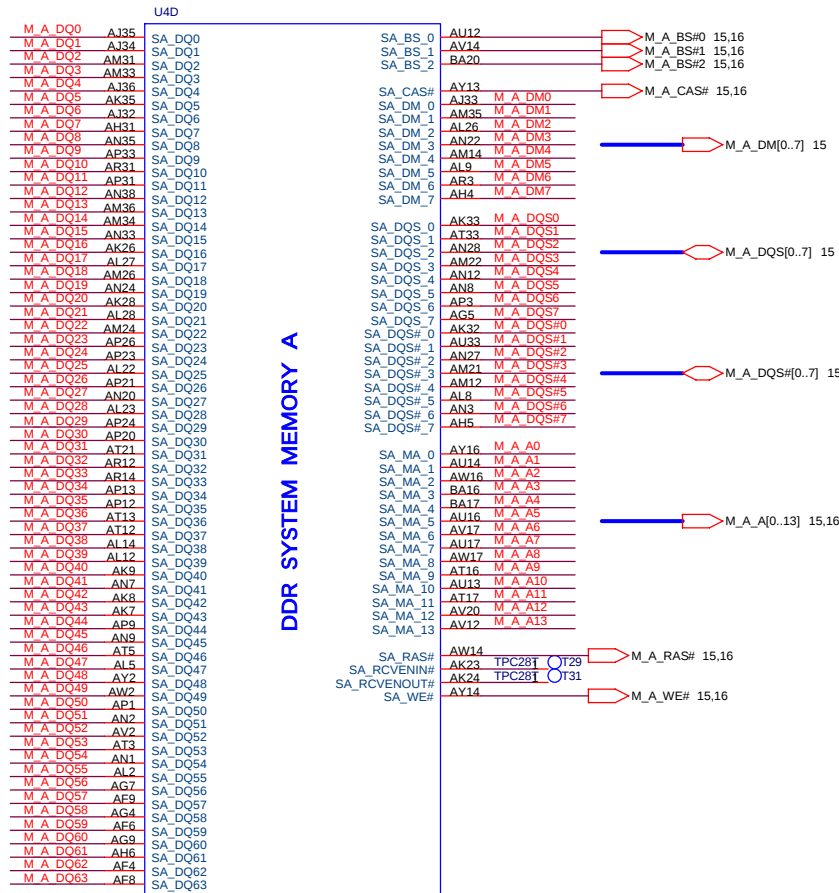
PCI-EXPRESS GRAPHICS



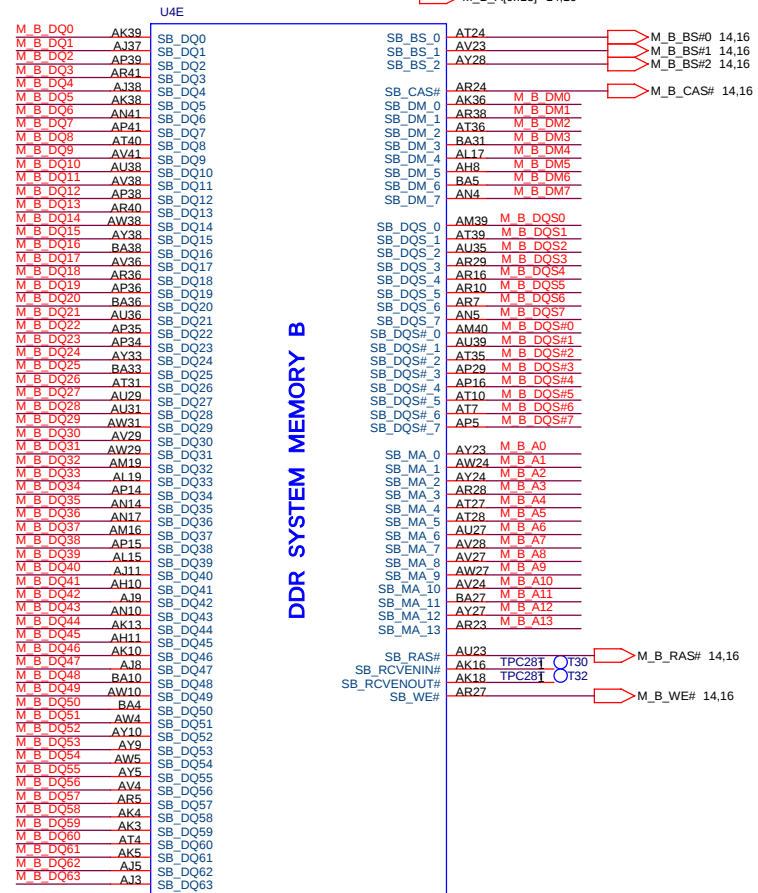
14 M_B_DQ[0..63]

15 M_A_DQ[0..63]

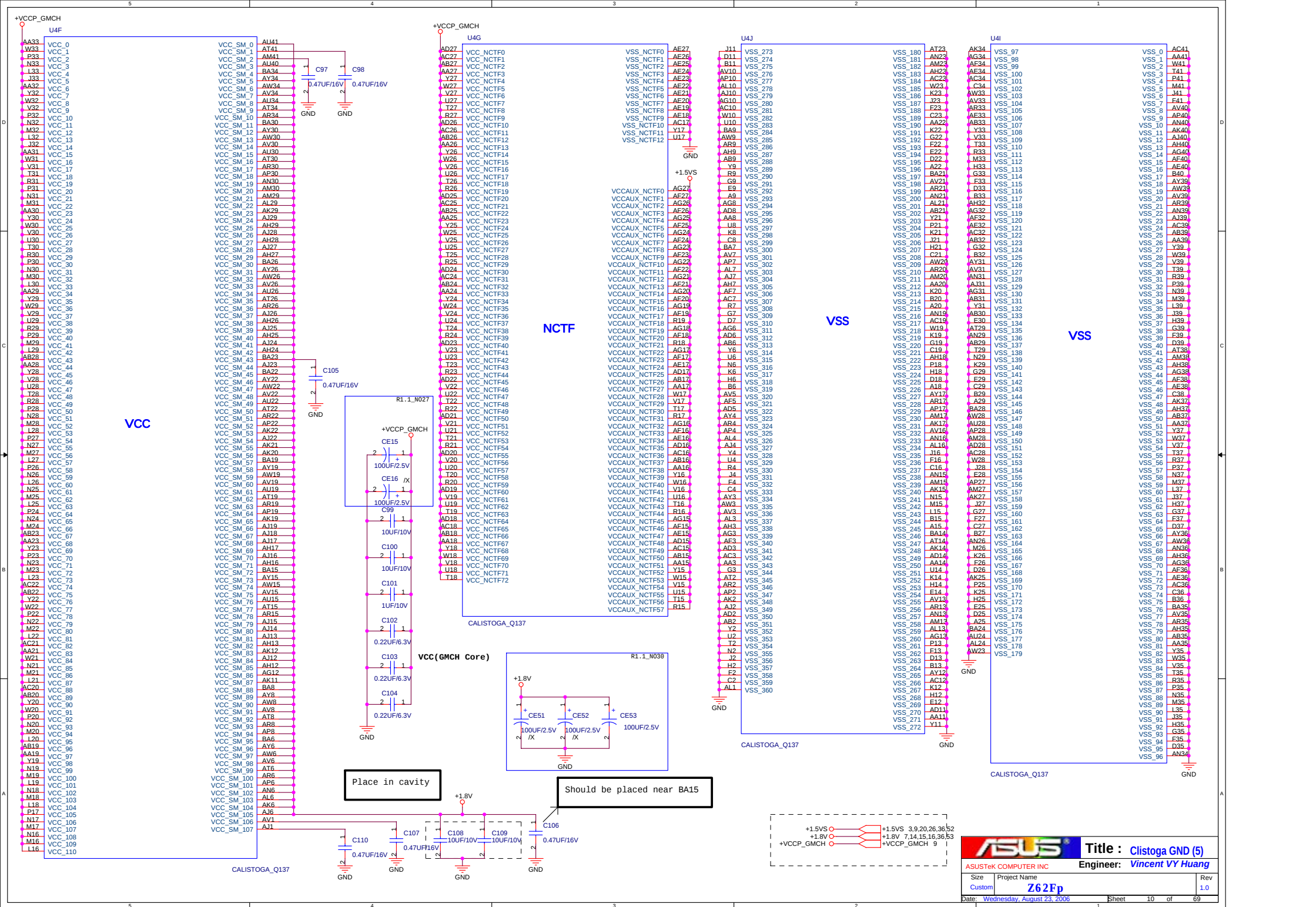
M_B_DM[0..7] 14
M_B_DQS[0..7] 14
M_B_DQS#0..7 14
M_B_A[0..13] 14,16

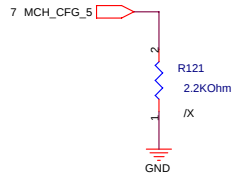


CALISTOGA_Q137



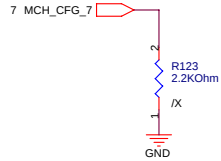
CALISTOGA_Q137





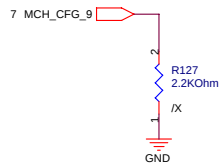
CFG5 : DMI X2 Select

LOW = DMI X 2
HIGH = DMI X 4 (Default)



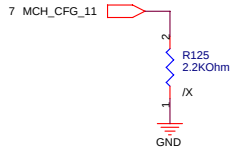
CFG7 : CPU STRAP

LOW = Reserved
HIGH = Mobility CPU (Default)

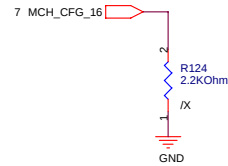


CFG9 : PCIE GRAPHIC LANE

LOW = REVERSE LANES
HIGH = NORMAL OPERATION (Default)

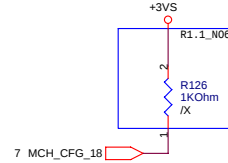


CFG11 : Reserved but need to be pull low



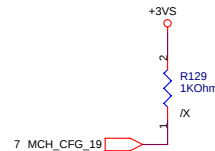
CFG16 : FSB DYNAMIC ODT

LOW = Dynamic ODT Disabled
HIGH = Dynamic ODT Enabled (Default)



CFG18 : GMCH Core Voltage Level

LOW = 1.05V (Default)
HIGH = 1.5V



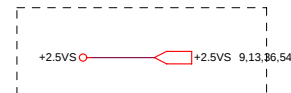
CFG19 : DMI LANE REVERSAL

LOW = NORMAL
HIGH = LANES REVERSED

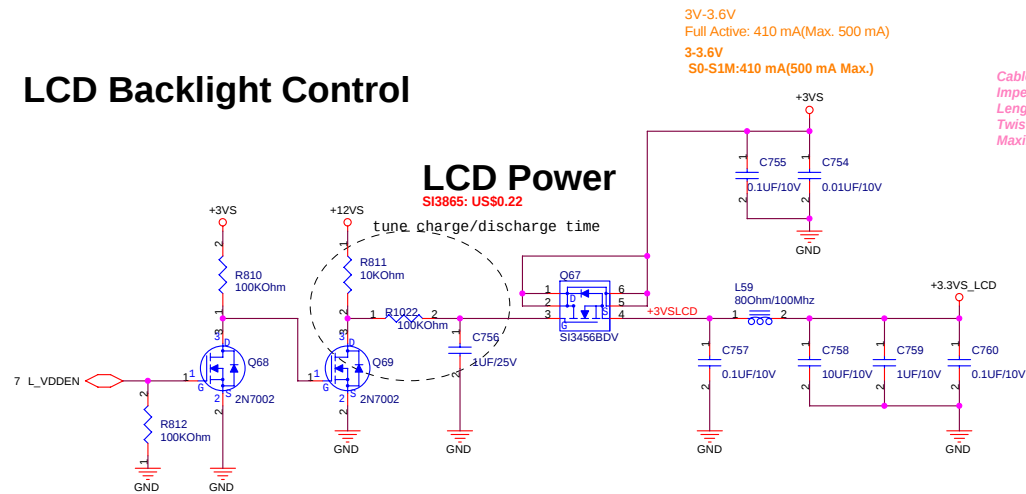
CFG[17..3] have internal pullup resistors.
CFG[19..18] have internal pulldown resistors.
SDVOCRTL_DATA has internal pulldown resistors.

CFG All are sampled with respect to the leading edge of the GMCH PWR0K

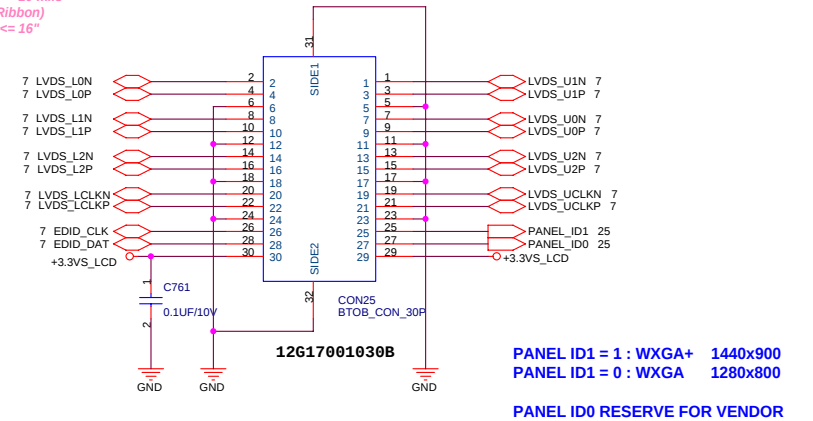
2:0	FSB Freq select	001 = FSB533 011 = FSB667
4:3		
5	DMI X 2 Select	0 = DMI X 2 1 = DMI X 4 (Default)
6		
7	CPU Strap	0 = Reserved 1 = Mobile CPU (Default)
8		
9	PCIE Graphics Lane Reversal	0 = Reverse Lanes 1 = Normal (Default)
11:10		
13:12	XOR/ALLZ	00 = Partial Clock Gating Disable 01 = XOR Mode Enabled 10 = All-Z Mode Enabled 11 = Normal operation (Default)
15:14		
16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
17		
SDVO_C TRLDATA	SDVO Present	0 = No SDVO Card Present (Default) 1 = SDVO Card Present
18	VCC select	0 = 1.05V (Default) 1 = 1.5V
19	DMI Lane Reversal	0 = Normal (Default) 1 = Reverse Lanes
20	SDVO/PCIE concurrent	0 = Only SDVO or PCIE x1 is operational(Default) 1 = SDVO and PCIE x1 are operating simultaneously via the PEG port



LCD Backlight Control

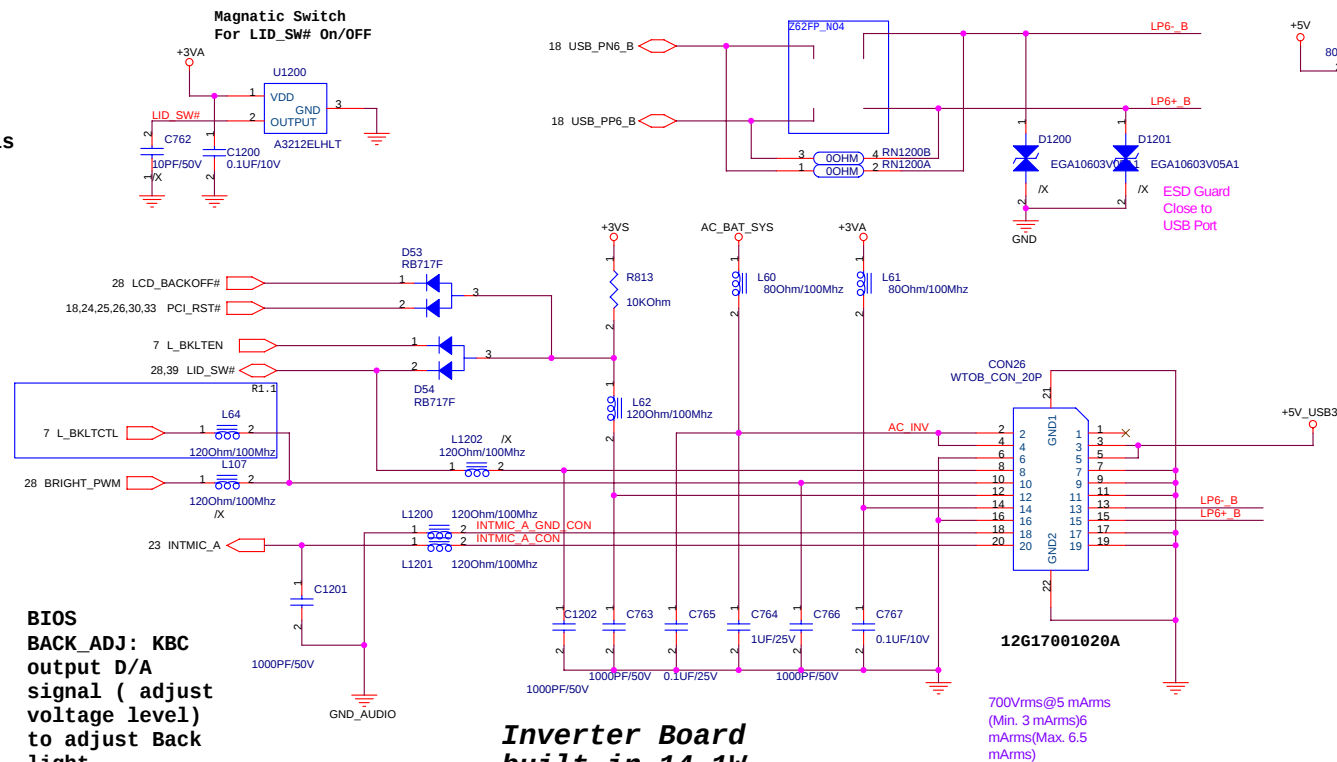


LCD LVDS Interface



INVERTER Interface

BIOS
LCD_BACKOFF#:When user push
"Fn+F7" button, BIOS active this
pin to turn off back light.



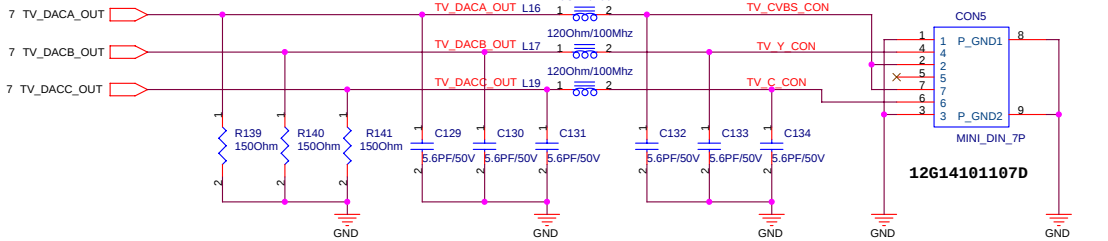
***Inverter Board
built in 14.1W
LCD Panel***

TV OUT

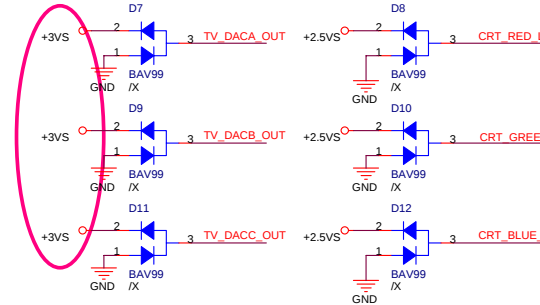
CRT OUT

checklist suggests
150ohm/100MHz & 6pF

checklist suggests 47ohm/100MHz

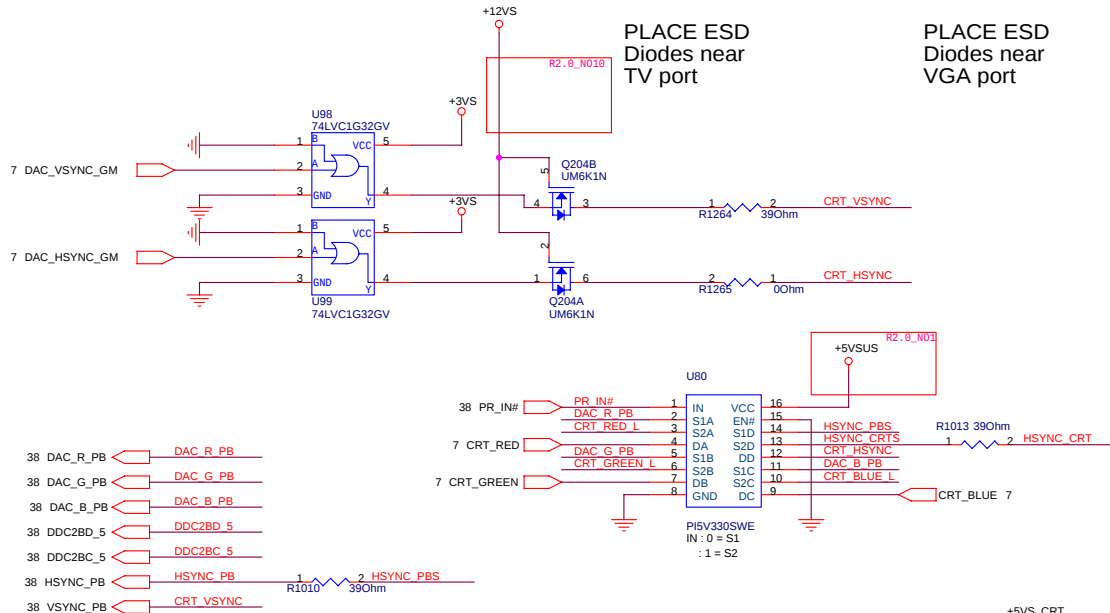


Place Terminator
close to
Connector

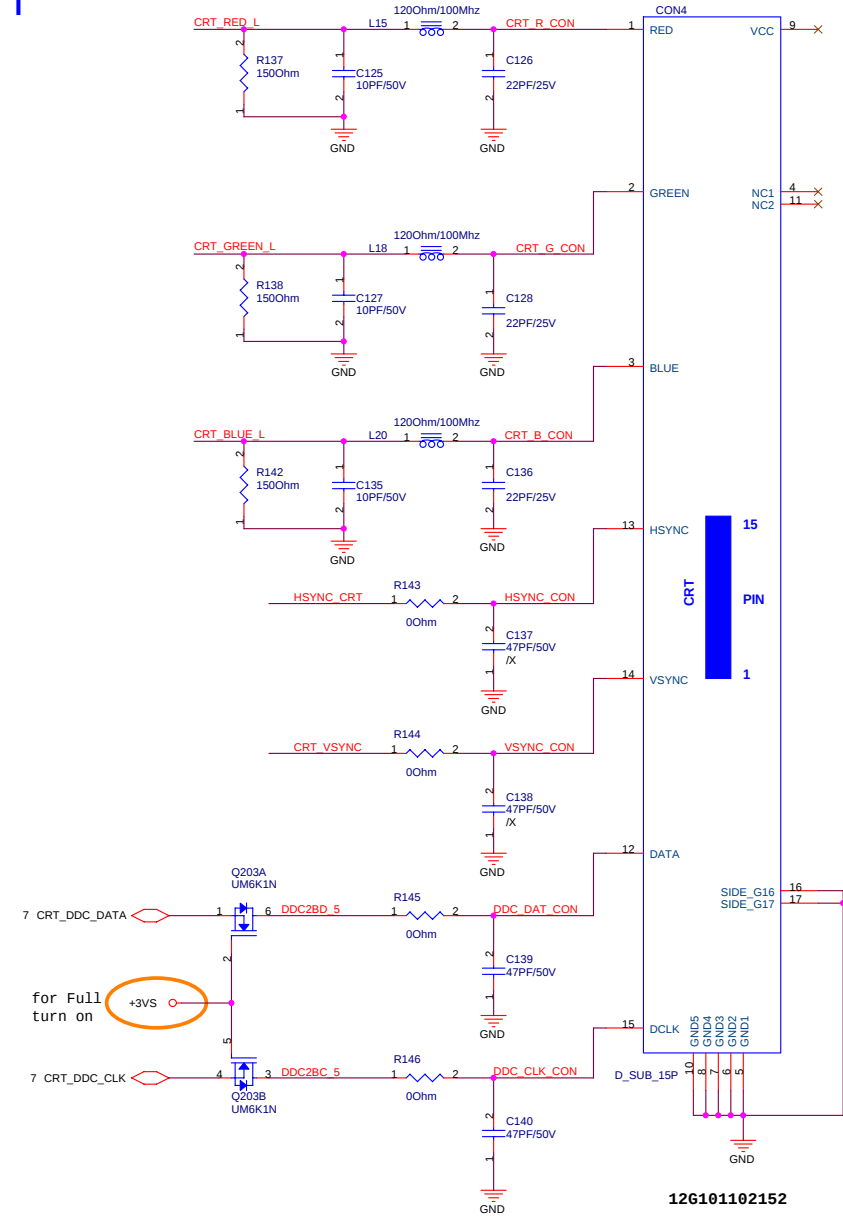


PLACE ESD
Diodes near
TV port

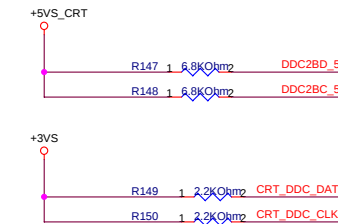
PLACE ESD
Diodes near
VGA port

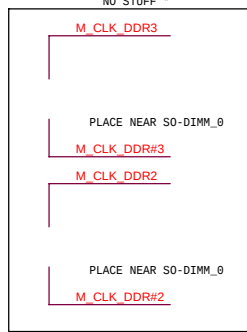


To PortBar III

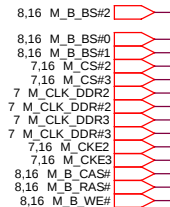
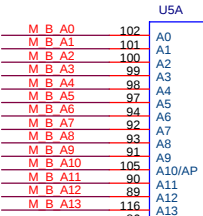


126101102152

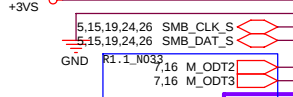




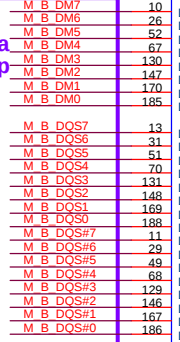
8.16 M_B_A[0..13]



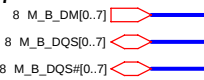
SMBus
address A2h



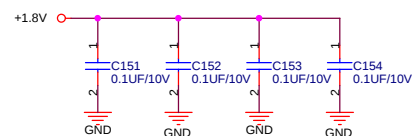
For Data Swap



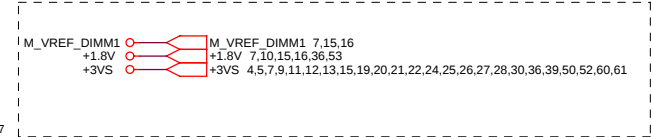
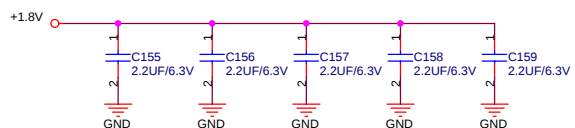
12G025122007



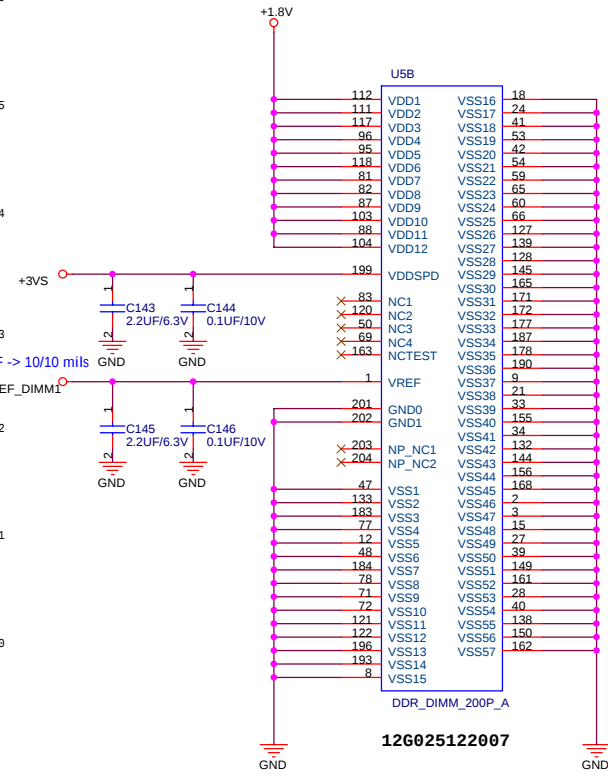
Layout Note: Place these High-Freq decoupling Caps near the GMCH



Layout Note: Place these resistors near the GMCH

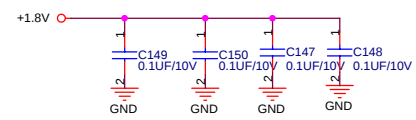


M_B_DQ[0..63] 8

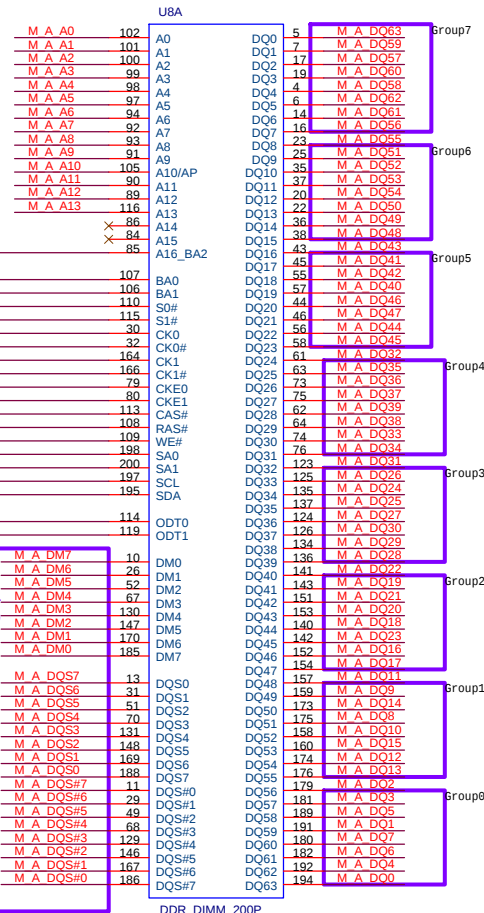
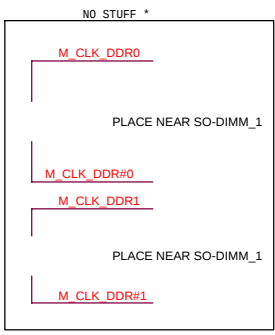


Layout Note: Place these Caps near SO DIMM 1

Layout Note: Place these Caps near SO DIMM 1



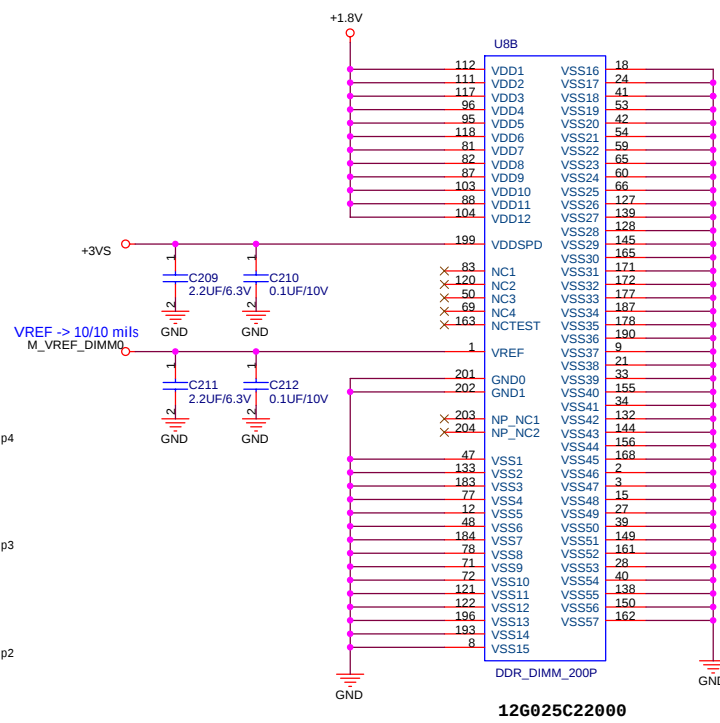
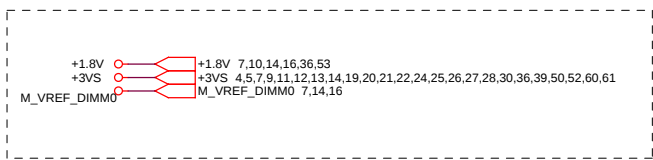
8,16 M_A_A[0..13] 
8 M_A_DM[0..7] 
8 M_A_DQS[0..7] 
8 M_A_DQS#[0..7] 



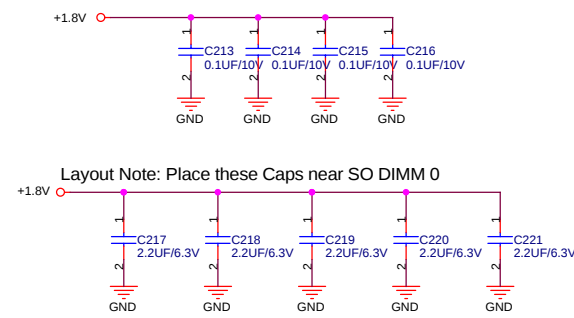
For Data Swap

12G025C22000

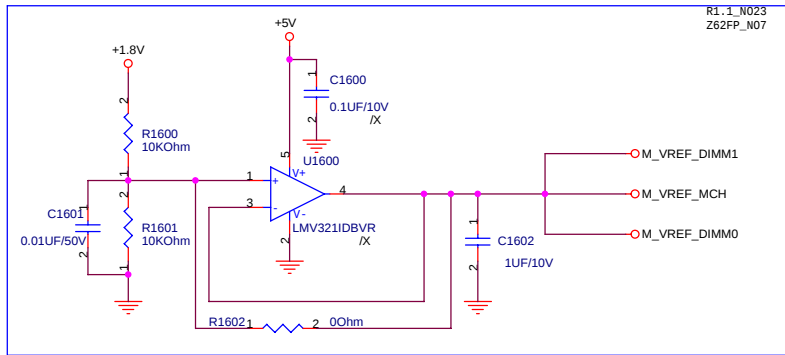
GMCH====>SODIMM1=>SODIMM0



Layout Note: Place these Caps near SO DIMM 0

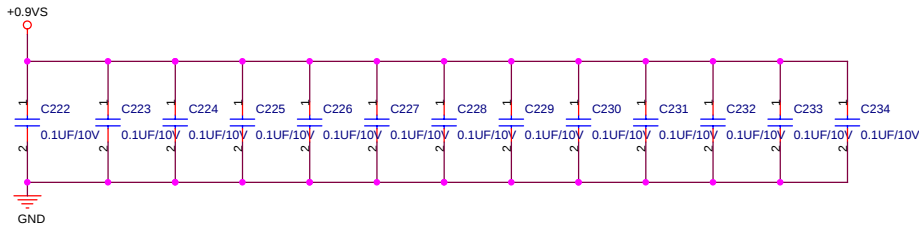


M_VREF_DIMM0 7,14,15
M_VREF_DIMM1 7,14,15
M_VREF_MCH 7,14,15
+0.9VS 36,53

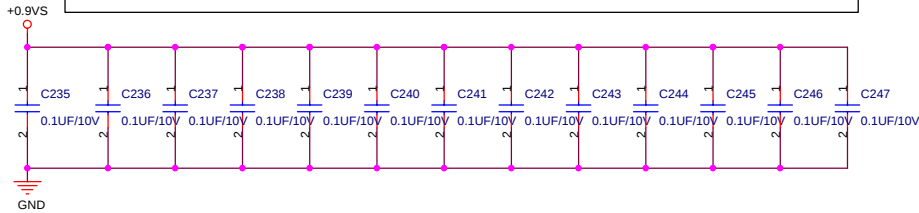


M_A_A[0..13] 8,15
M_A_BS#[0..2] 8,15
M_A_CAS# 8,15
M_A_RAS# 8,15
M_A_WE# 8,15

M_B_A[0..13] 8,14
M_B_BS#[0..2] 8,14
M_B_CAS# 8,14
M_B_RAS# 8,14
M_B_WE# 8,14



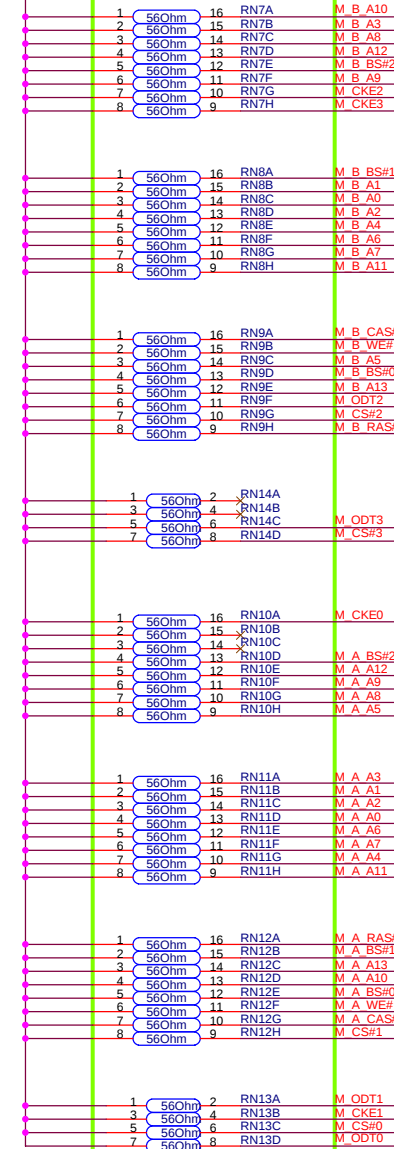
Layout note: Place one cap close to every 2 pullup resistors terminated to +0.9VS



M_CS#[0..3] 7,14,15
M_ODT[0..3] 7,14,15
M_CKE[0..3] 7,14,15

+0.9VS

NEED TO SWAP



Title : DDR2 TERM

ASUSTek COMPUTER INC

Engineer: Vincent VY Huang

Size

Project Name

Rev

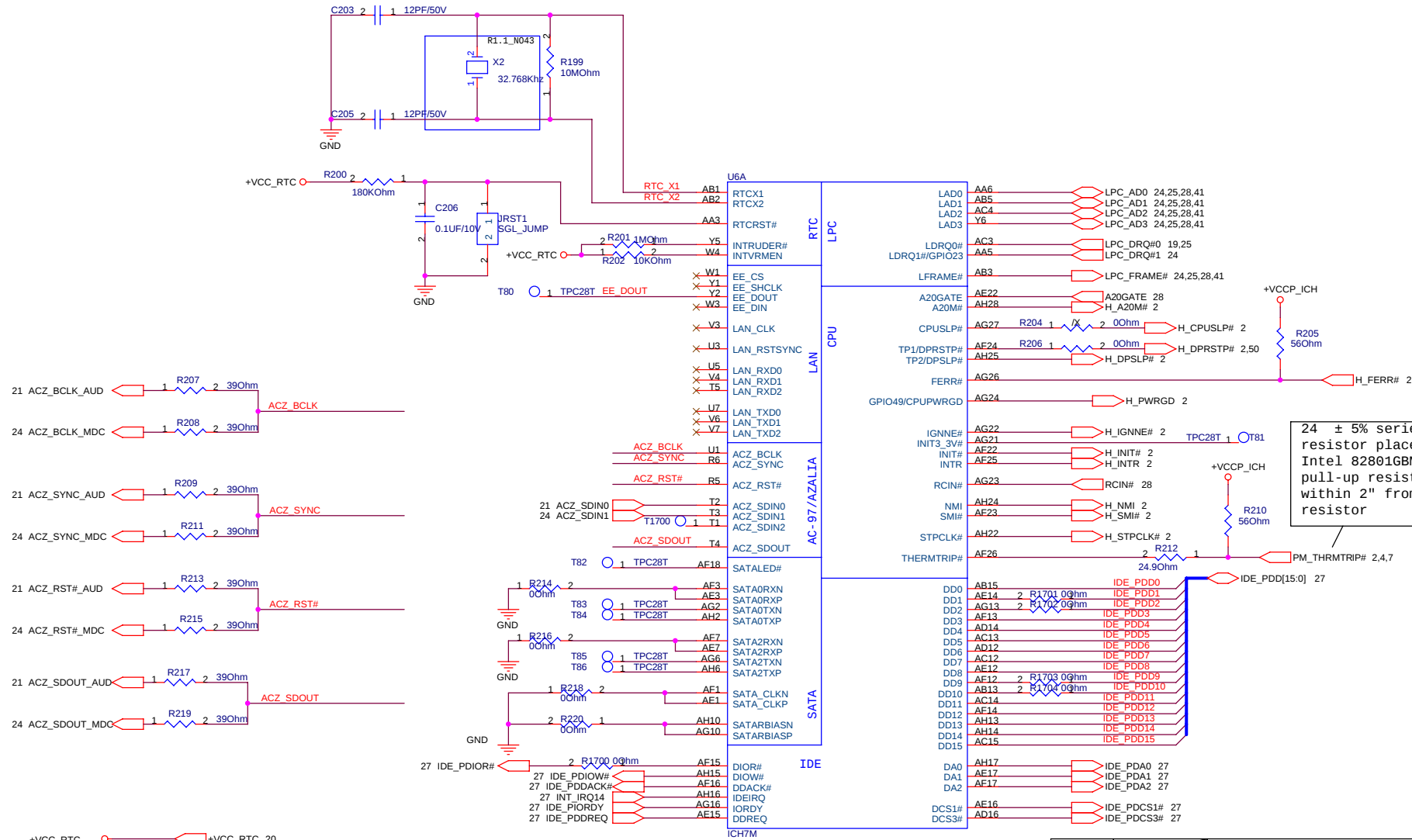
Custom

Z62Fp

1.0

Date: Wednesday, August 23, 2006

Sheet 16 of 69



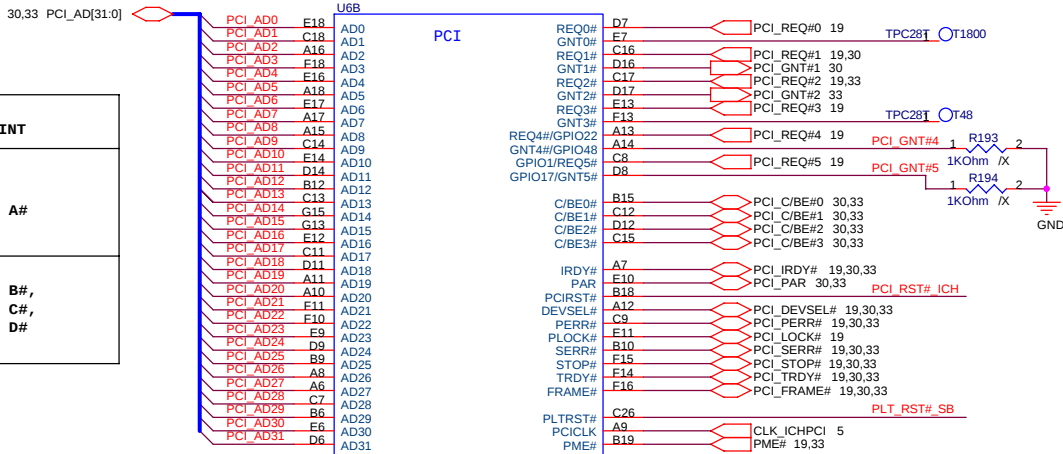
24 ± 5% series termination resistor placed within 2" from Intel 82801GBM, 56 ± 5% pull-up resistor has to be within 2" from the series resistor

ACZ_SDOUT	PWROK rising	TP3 pull low: allow entrance to XOR Chain testing TP3 not pull low: sets bit 0 of RPC.PC	PD
ACZ_SYNC	PWROK rising	sets bit 0 of RPC.PC	PD
EE_CS		should not be pulled high	PD
EE_DOUT		should not be pulled low	PU
GNT2#		should not be pulled low	PU
GNT3#	PWROK rising	low: "top-block swap" mode	PU
GNT5#/GPIO17# GNT4#/GPIO48	PWROK rising	GNT5# GNT4# 0 1 SPI 1 0 PCI 1 1 LPC	PU

GPIO16 /DRSLPVR		should not be pulled high	PD
GPIO25	RSMRST# rising	should not be pulled low	PU
INTVRMEN	ALWAYS	high: Enable integrated VccSusi_05 VRM	
LINKALERT#		REQUIRE an external pull-up R	Need
REQ[4:1]#	PWROK rising		PU
SATALED#		should not be pulled low	Conditional
SPKR	PWROK rising	high: "No reboot" mode	PD
TP3	PWROK rising	should not be pulled low unless using XOR Chain testing	PU

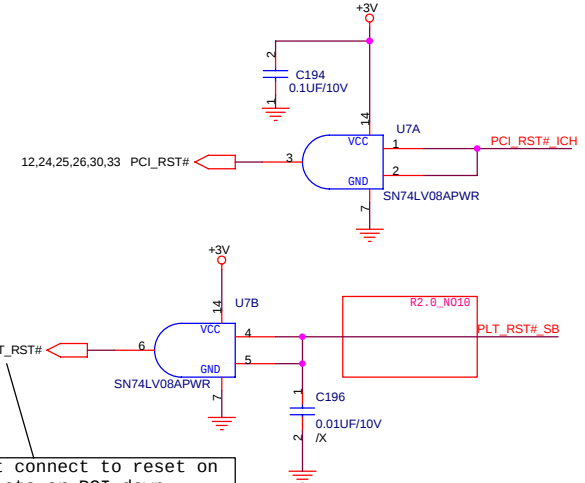
DEVICE	IDSEL	REQ/GNT	INT
LAN	AD23	REQ2#/GNT2#	INT A#
CARDBUS	AD17	REQ1#/GNT1#	INT B#, INT C#, INT D#

Internal					
SM Bus	INTB#	EIP	INTA#	PCIE6	INTB#
SATA	INTB#	U3P	INTD#	PCIE5	INTA#
PATA	INTA#	U2P	INTC#	PCIE4	INTD#
AC97 Modem	INTB#	U1P	INTB#	PCIE3	INTC#
AC97 Audio	INTA#	U0P	INTA#	PCIE2	INTB#
HD	INTA#		INTA#	PCIE1	INTA#
Audio			Audio		



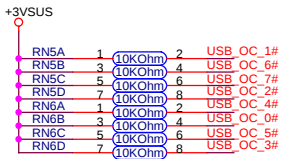
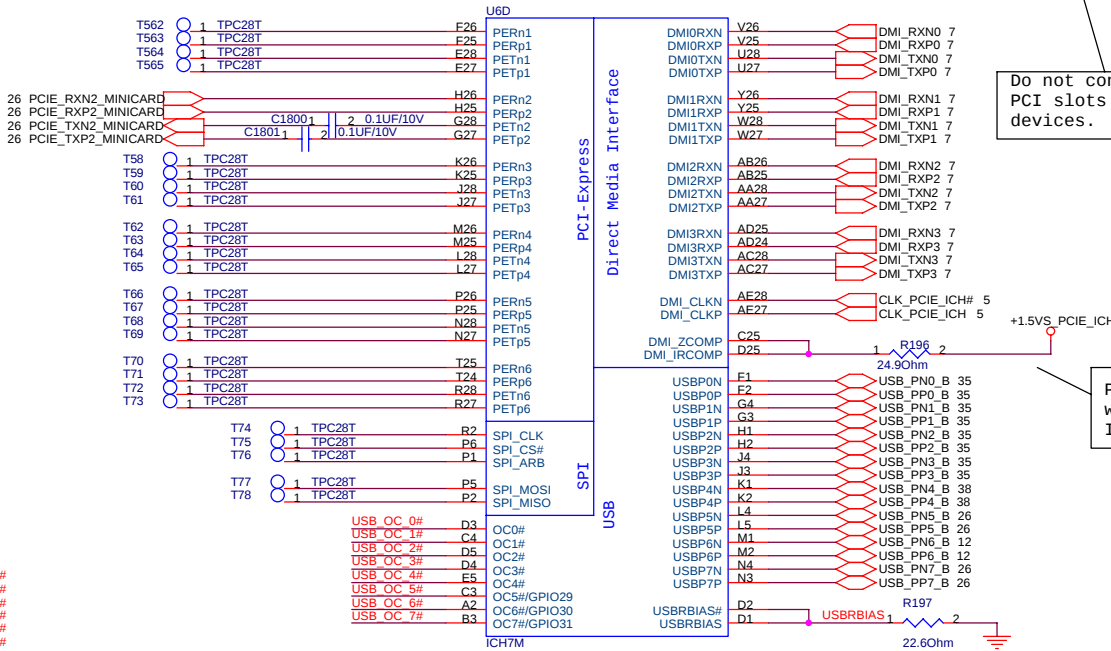
		GNT#5	GNT#4
LPC	11	1	1
PCI	10	1	0
SPI	01	0	1

(default)

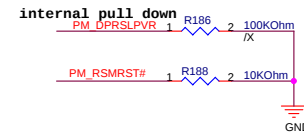
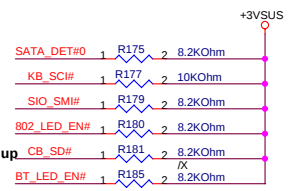
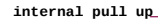
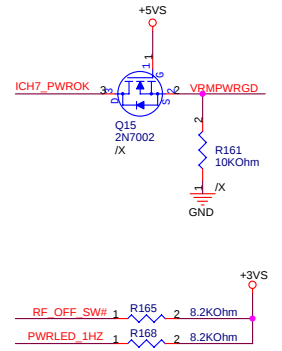
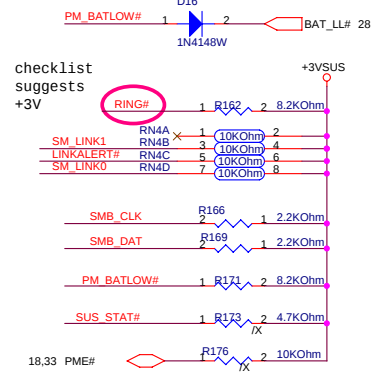
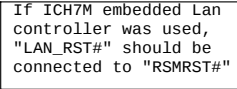


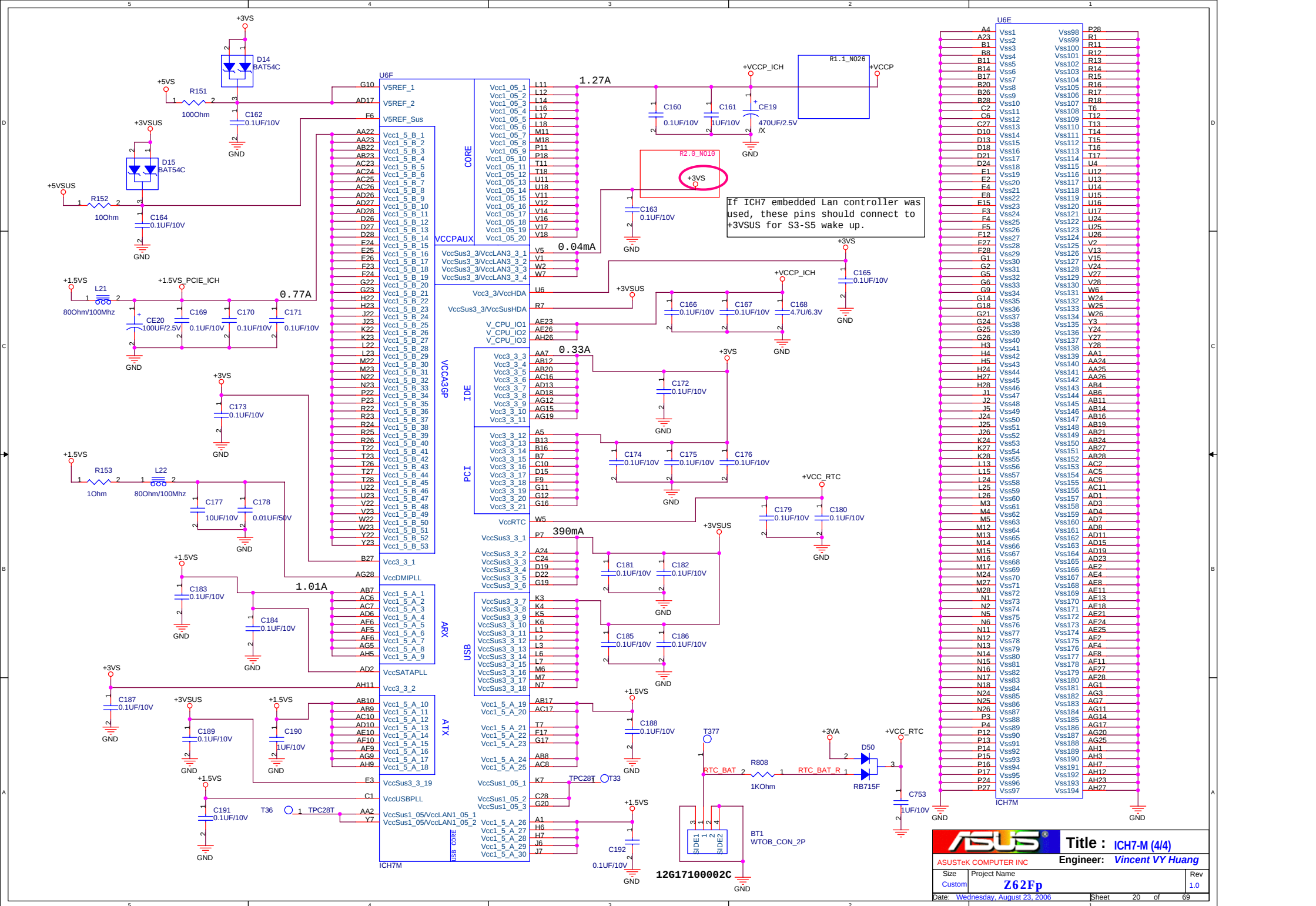
Do not connect to reset on PCI slots or PCI down devices.

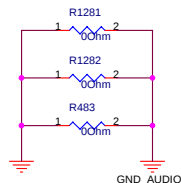
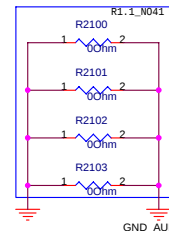
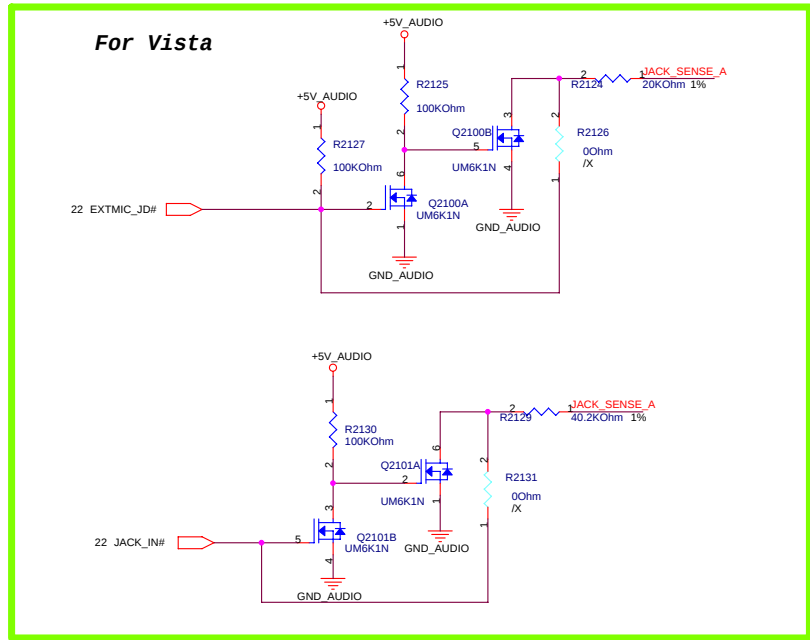
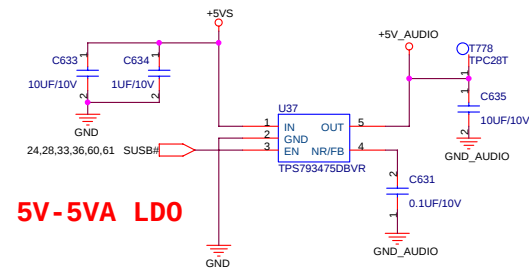
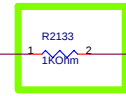
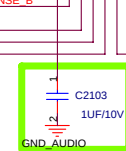
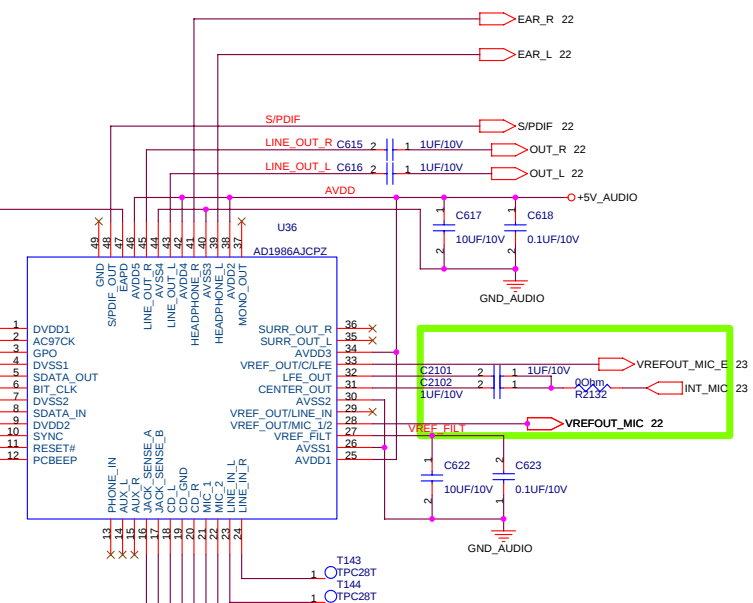
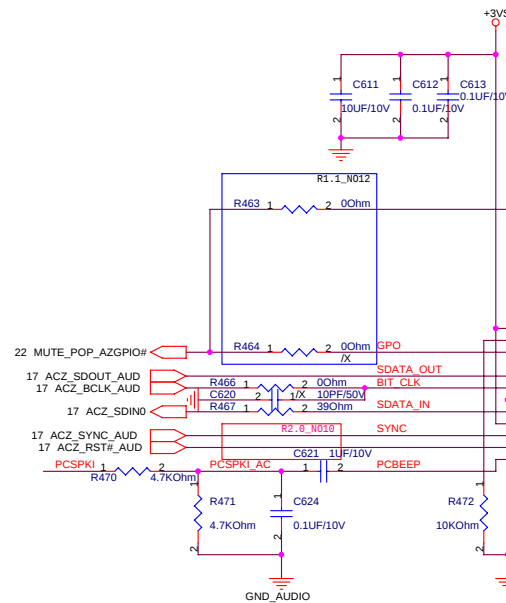
Pull-ups must be placed within 500 mills from Intel 82801GBM pins

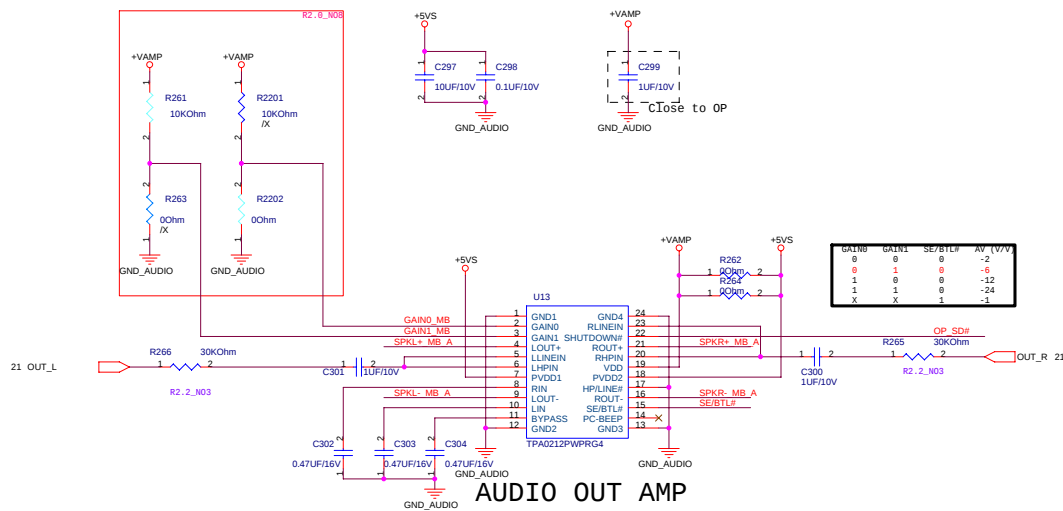


For PCI compliance, SMBus signals should be routed to either all or none of the PCI slots in a chassis. These signals should not be connected to SMLINK





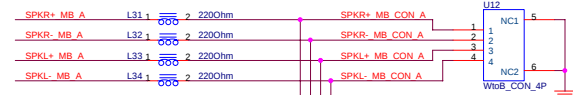




AUDIO OUT AMP

GAIN0	GAIN1	SE/BTL#	AV (V/V)
0	0	0	-2
0	1	0	-6
1	0	0	-12
1	1	0	-24
X	X	1	-3

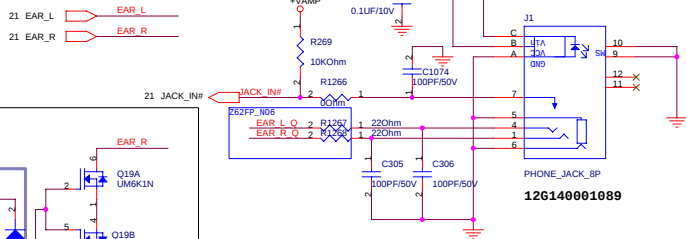
SPEAKER CONN.



12G171000047

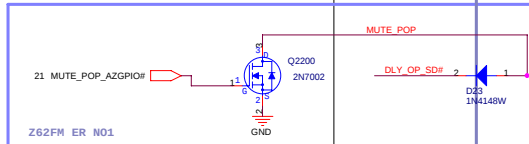
SPEAKER is 4 ohm +- 15% / 2W / 79 +- 3db (美星電子)
P/N:04-170003610

HEADPHONE JACK



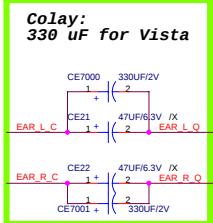
12G140001089

Pop noise can be heard via headphone when system boot, restart and resume from S3. Add OP_SD# to control the turn-on timing.



But when system resume from S3, pop noise is behind OP_SD# pull high. Add a delay circuit to prevent it.

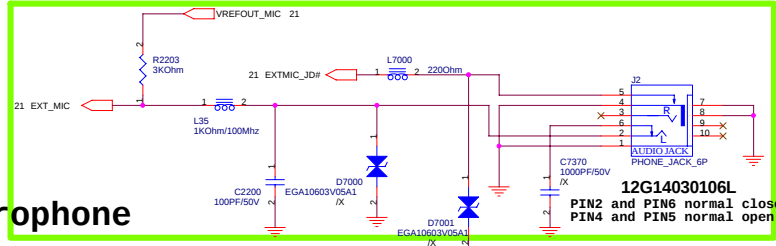
Solve pop noise



Colay: 330 uF for Vista

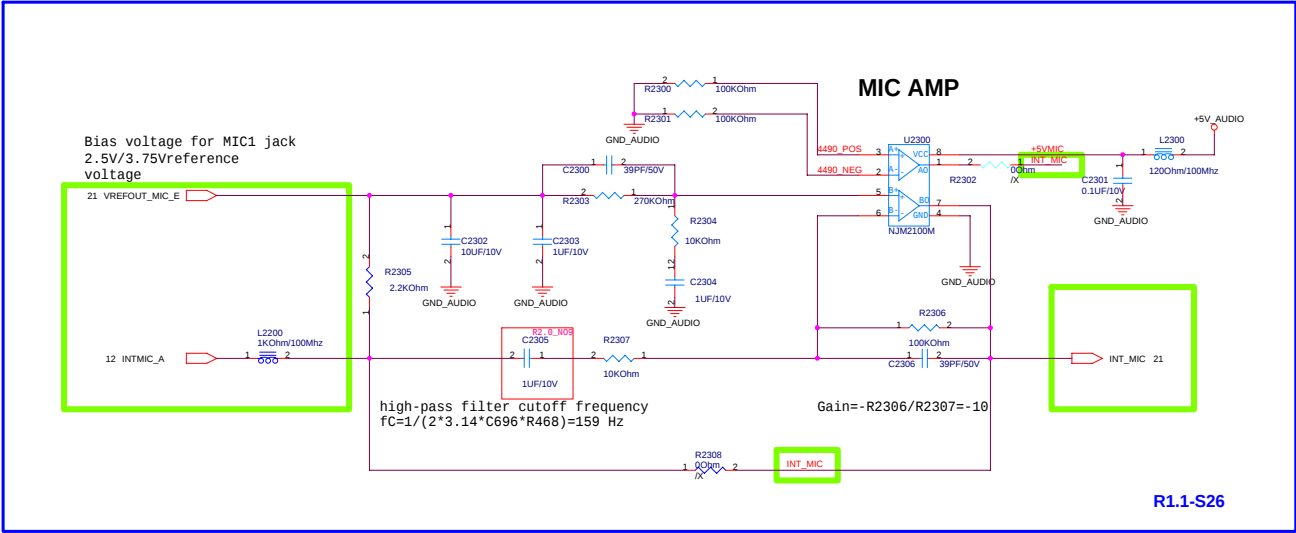
$f(\text{highpass}) = \frac{1}{2\pi \cdot 32 \cdot C} = 73$
R=32 Ohm for Headphone, so C=68uF
But in order to reduce component type, use 100uF/6.3V(11-041210721), but 100uF is too big for A3N, so change to 47uF.

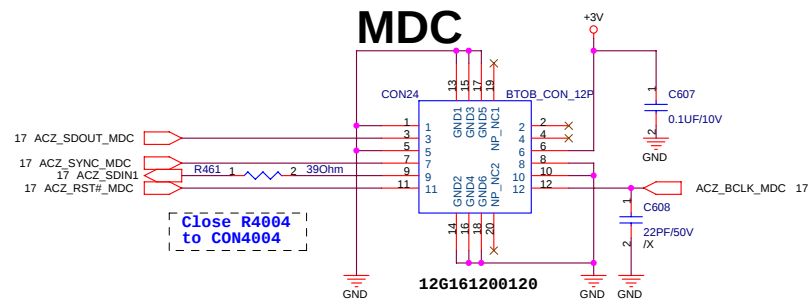
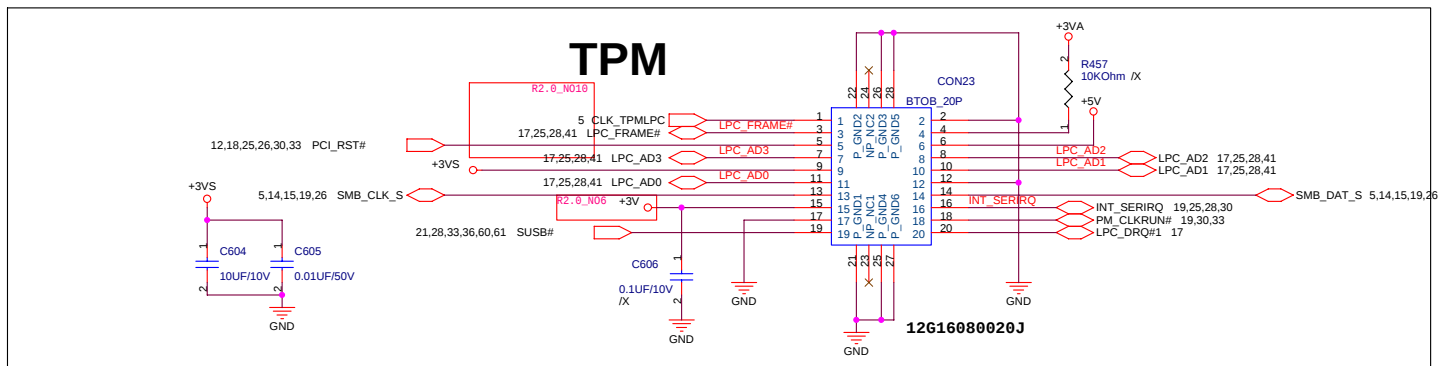
External Microphone



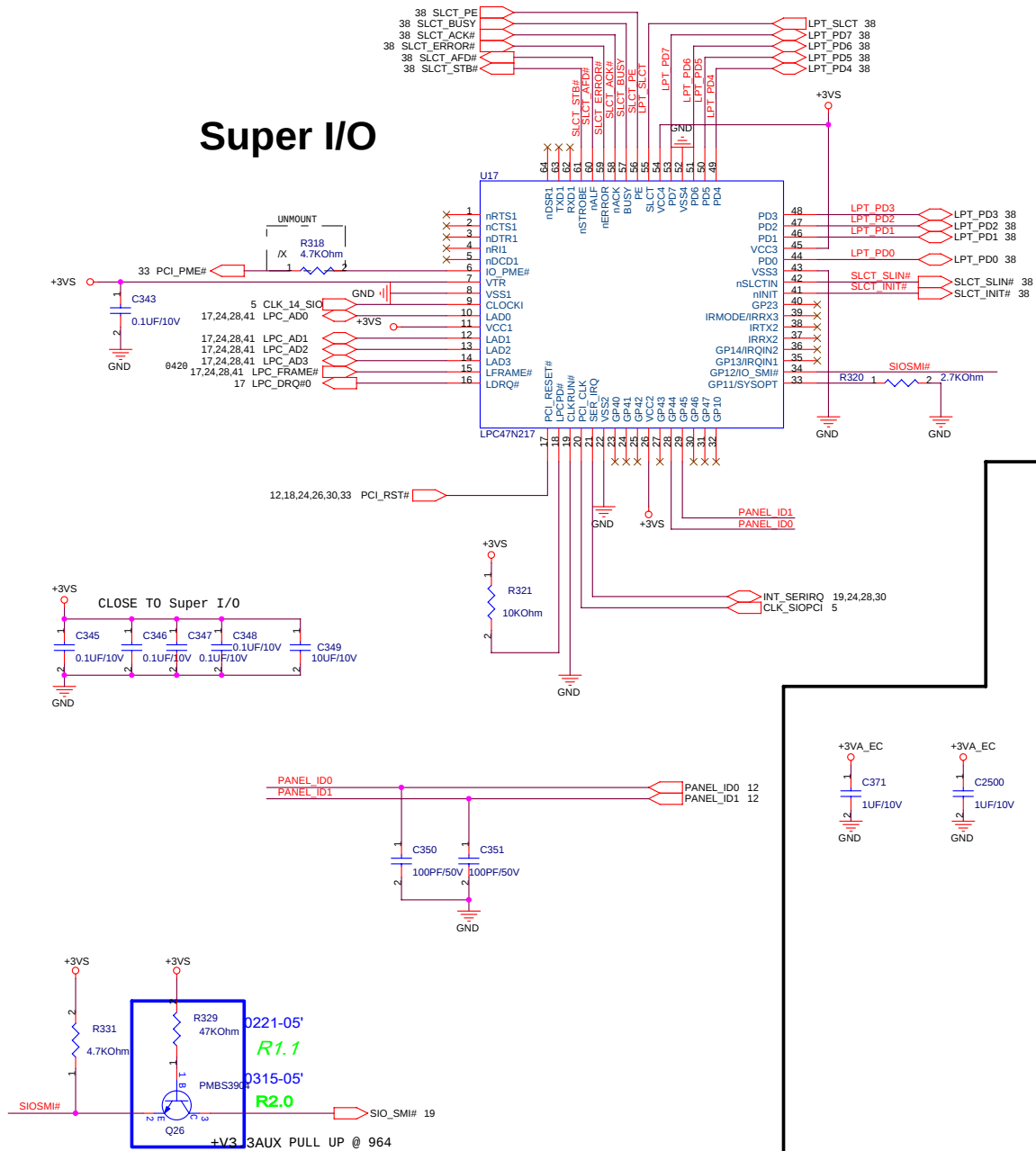
12G14030106L

PIN2 and PIN6 normal close
PIN4 and PIN5 normal open





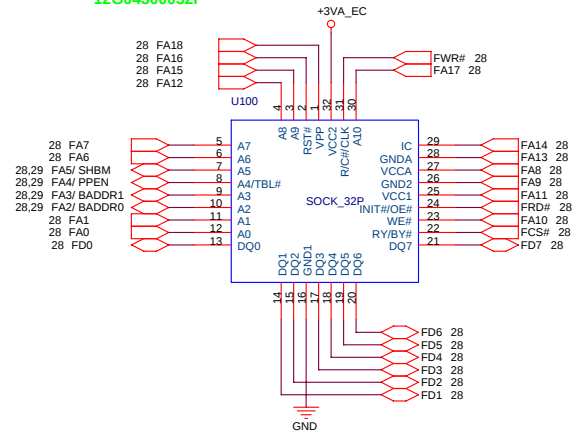
Super I/O



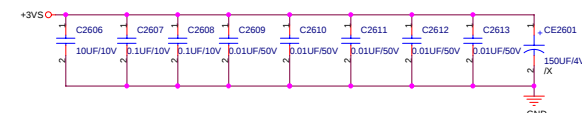
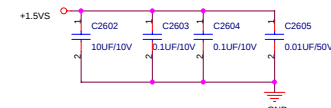
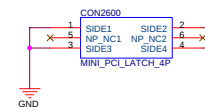
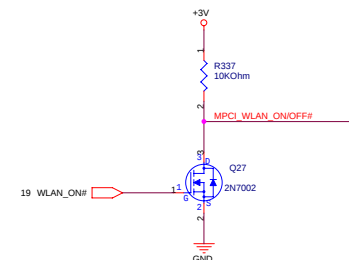
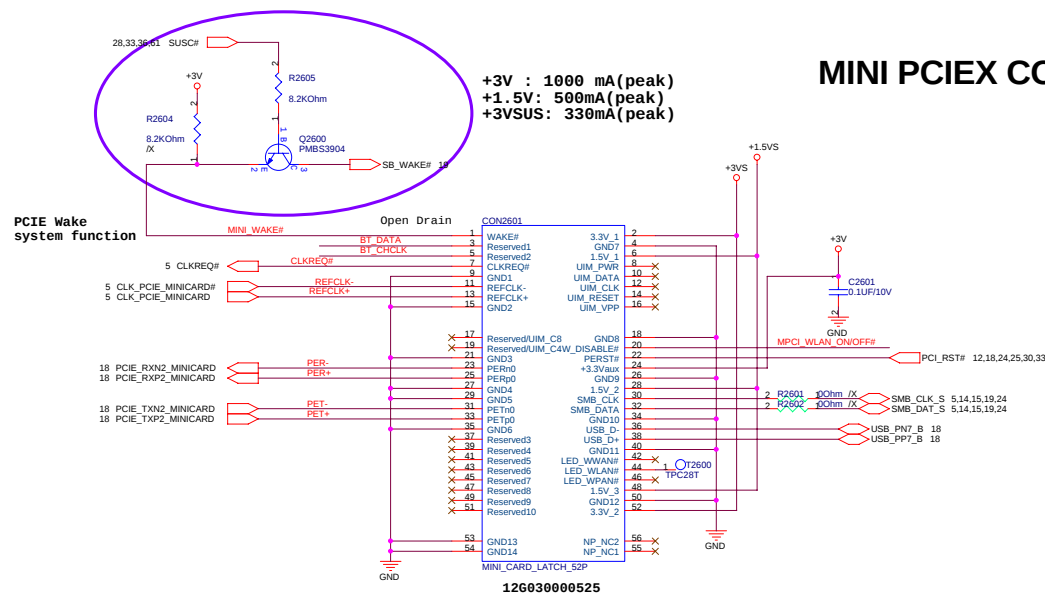
SST-PLCC32 4Mbits Flash ROM
PN:05G001014110(+3.3V)

ISA ROM

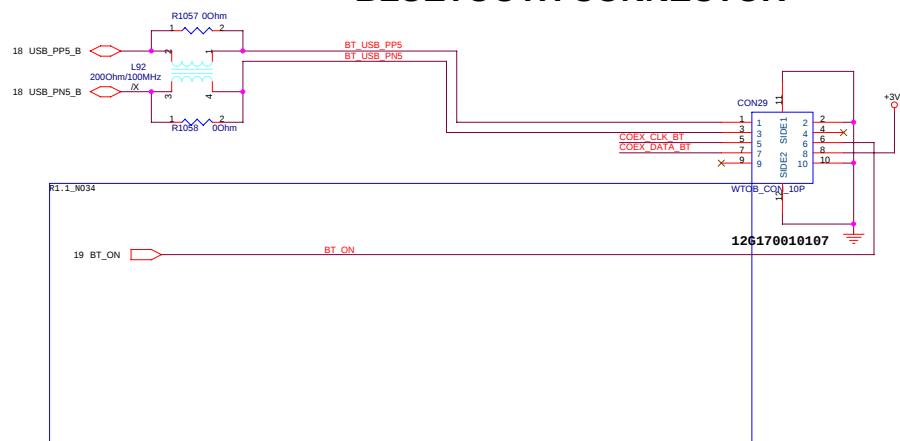
PLCC32 Socket PN:
12G04300032F



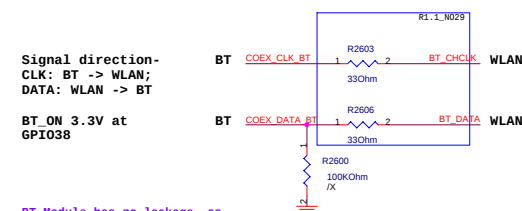
MINI PCIEX CONNECTOR



BLUETOOTH CONNECTOR



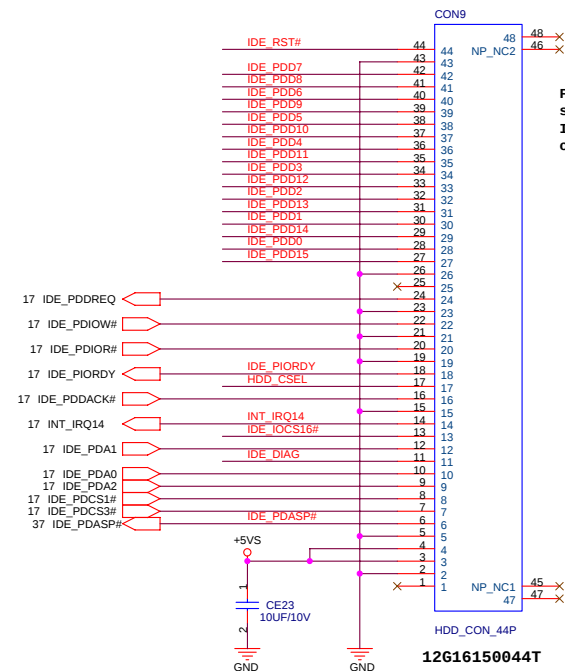
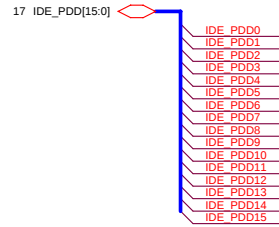
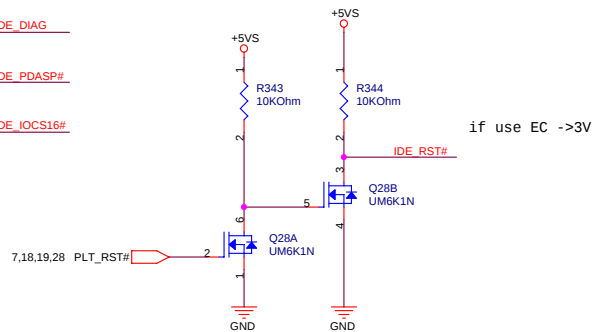
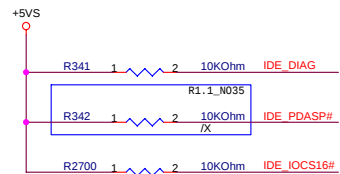
Check O/D output
or push pull



```
Signal direction-
CLK: BT -> WLAN;
DATA: WLAN -> BT
```

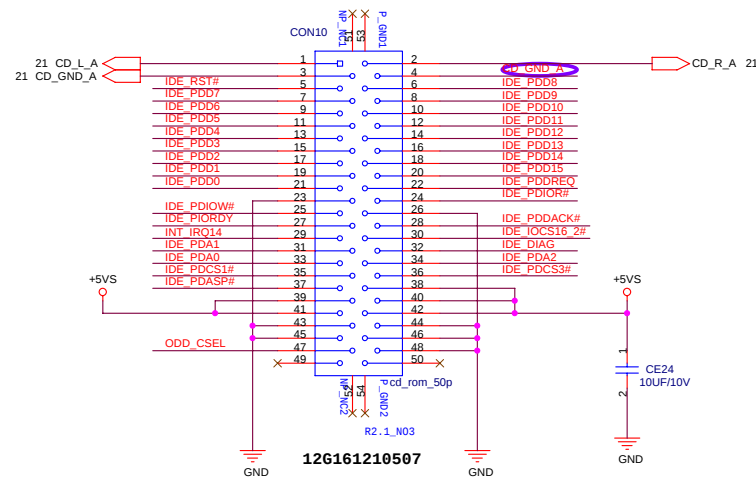
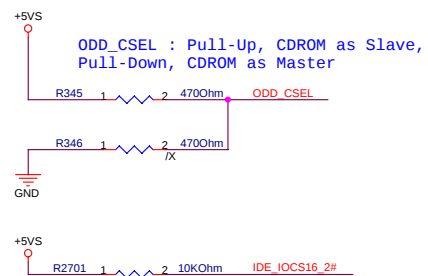
BT_ON 3.3V at
GPIO38

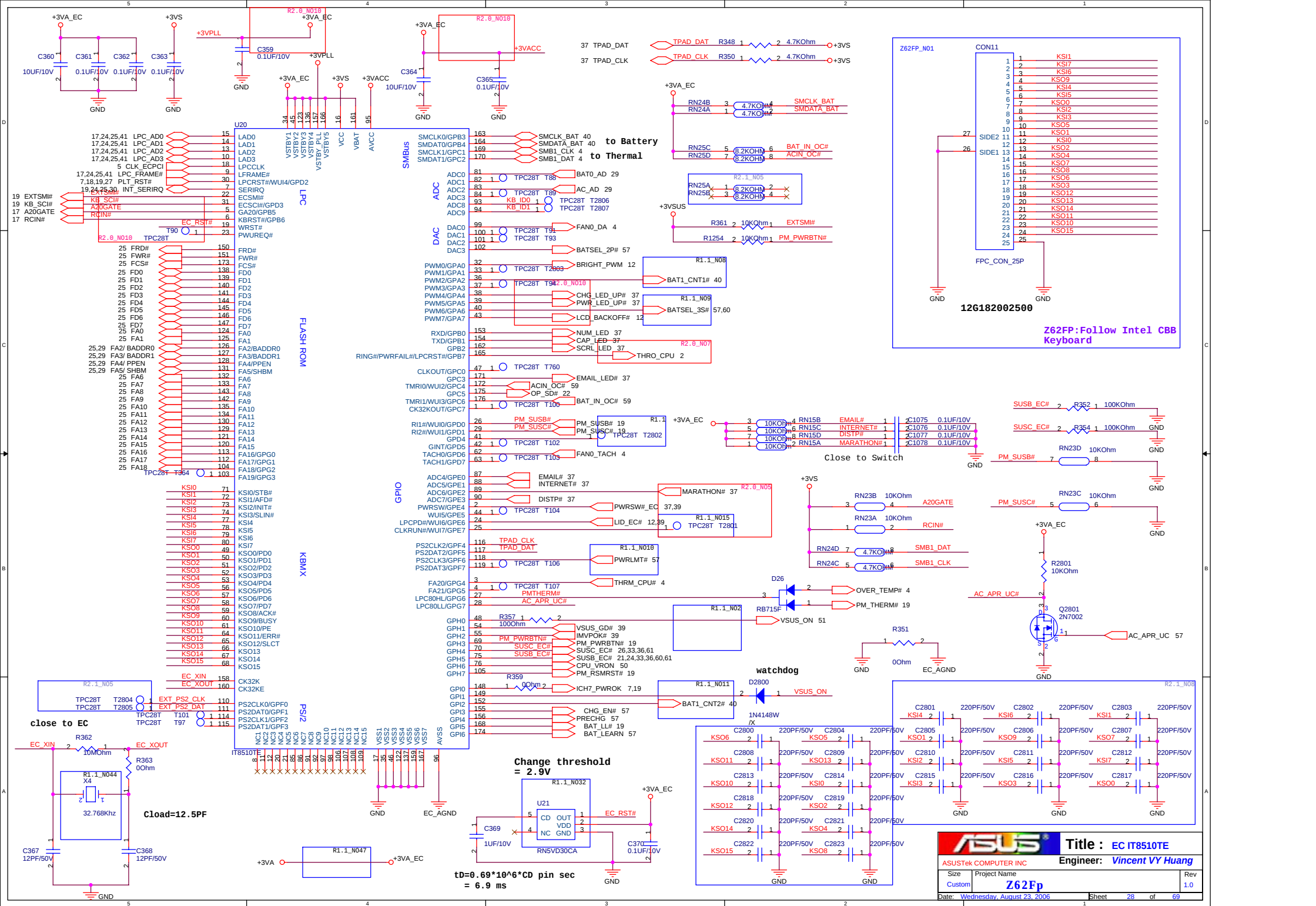
BT Module has no leakage, so
discard PMOS block circuits



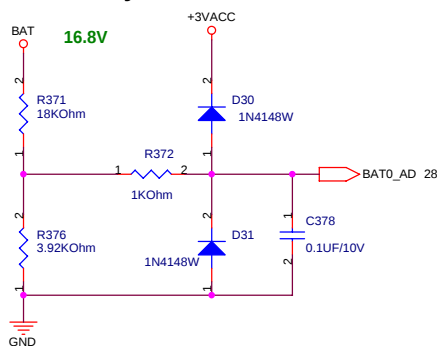
HDD

CD-ROM

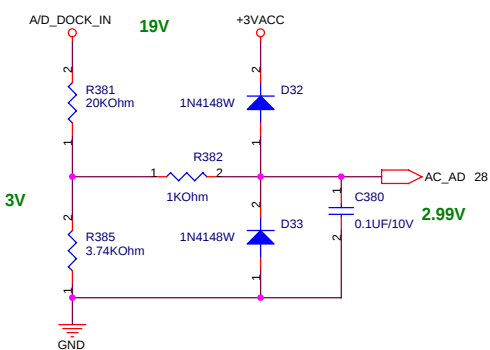




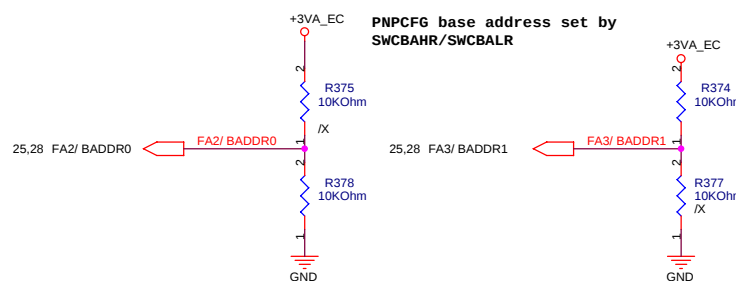
EC ADC Battery



Adaptor



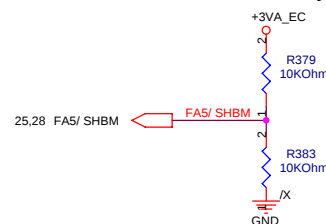
EC Hardware Strap



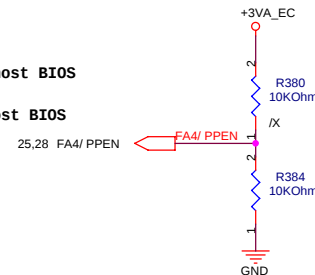
strap value sampled after
VSTBY power up reset

BADDR[1:0]
No pull up:
The register pair to access PNPCFG is
002Eh and 002Fh.
Ext 10K up on BADDR0:
The register pair to access PNPCFG is
004Eh and 004Fh.
Ext 10K up on BADDR1:
The register pair to access PNPCFG is
determined by EC domain registers
SWCBALR and SWCBAHR.

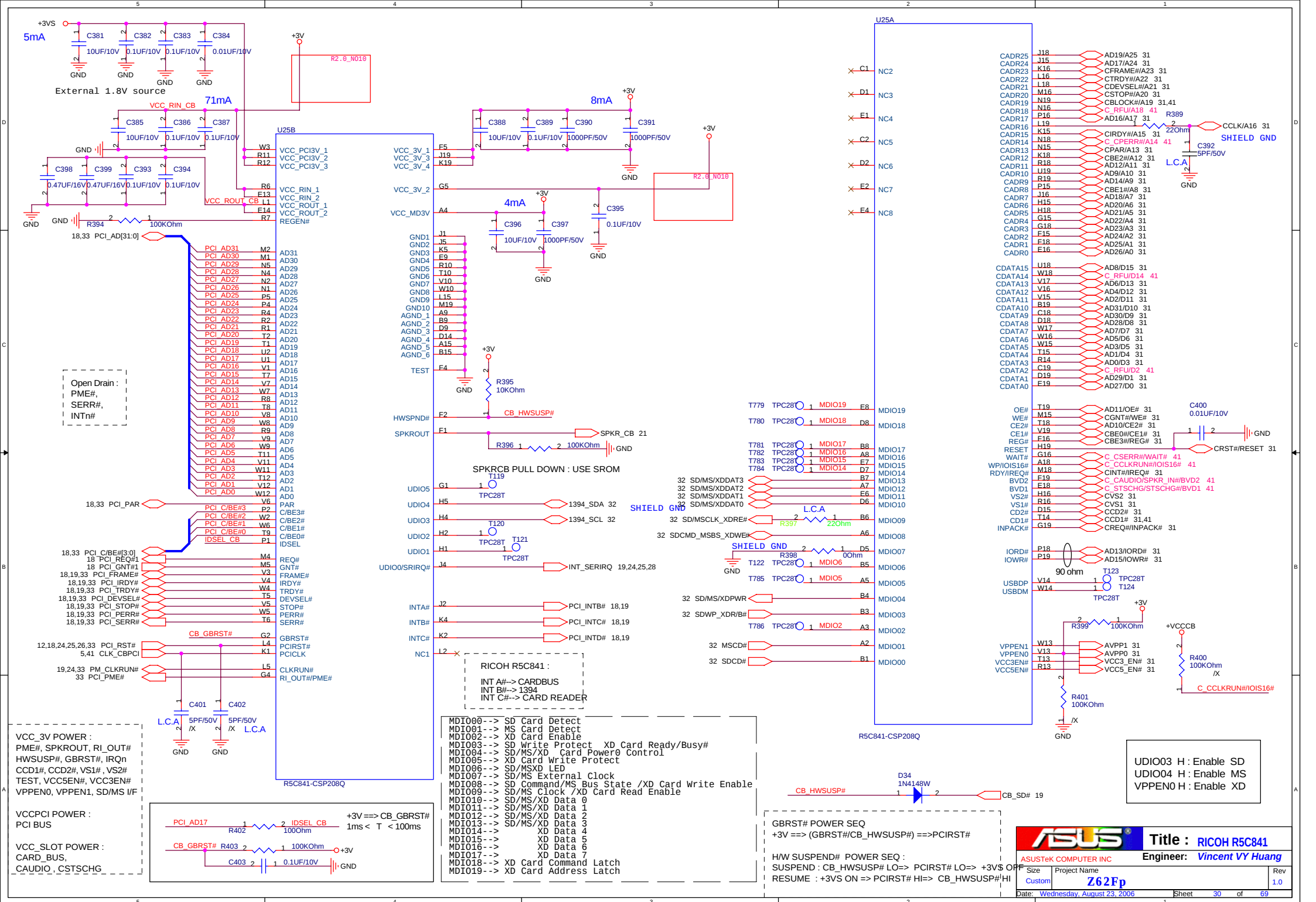
Share Memory

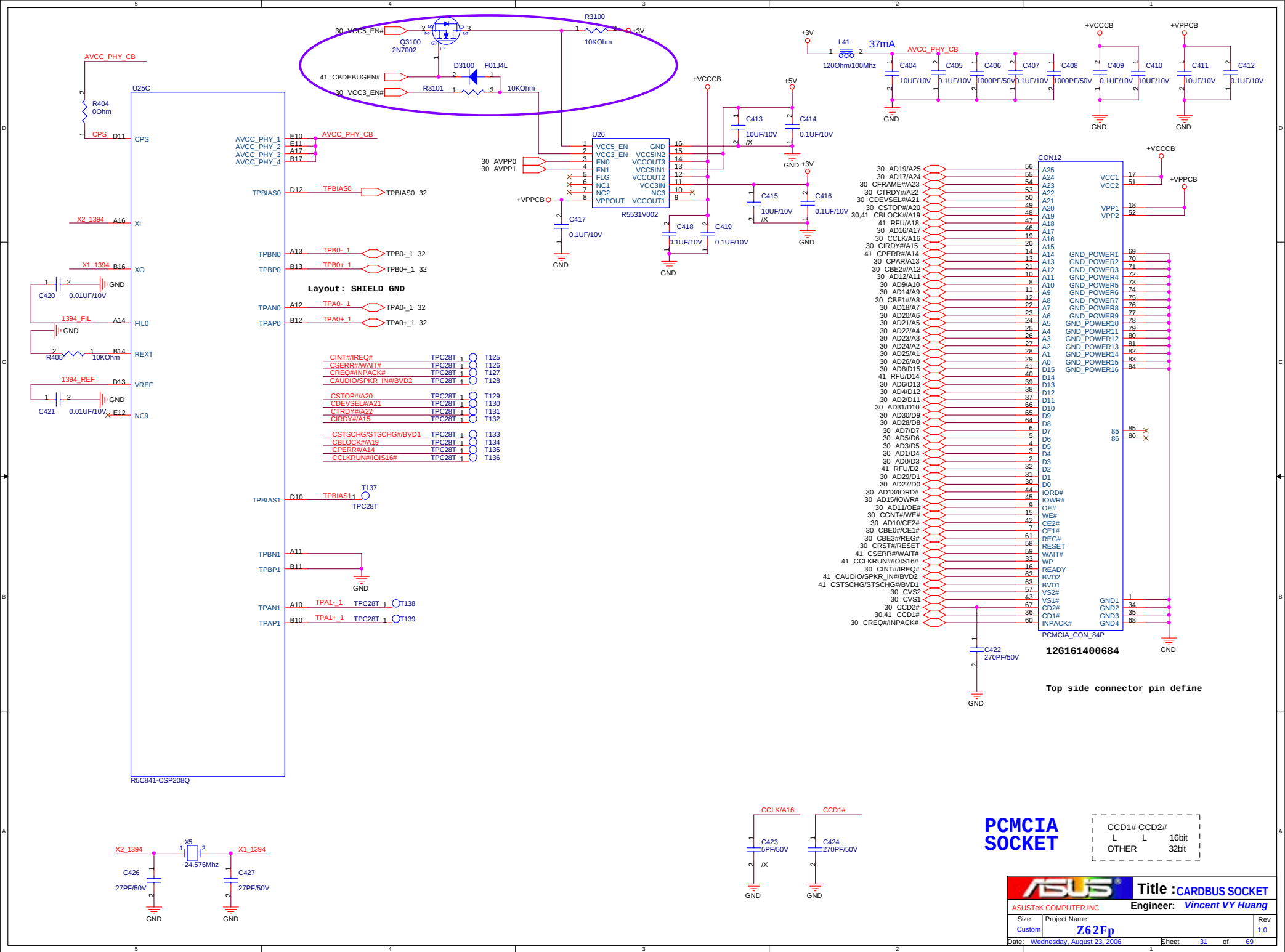


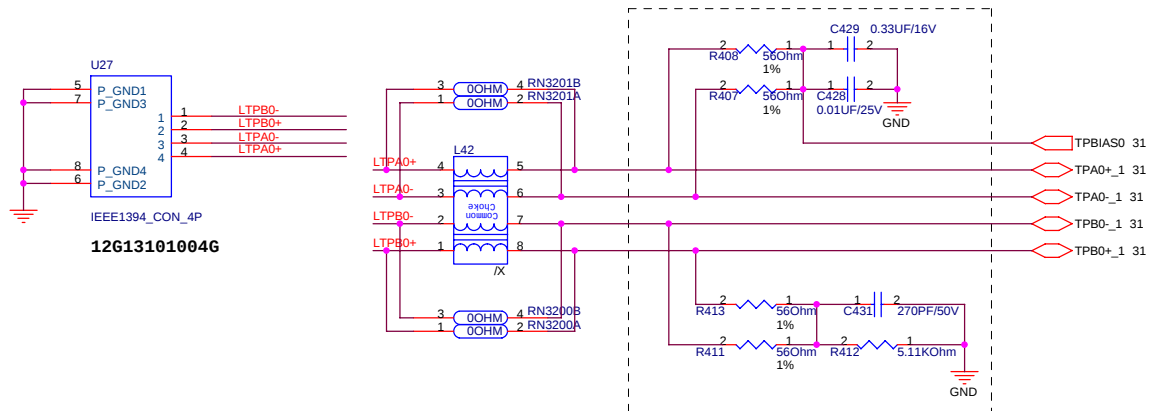
SHBM
No pull up:
disable shared memory with host BIOS
Ext 10K up:
enable shared memory with host BIOS



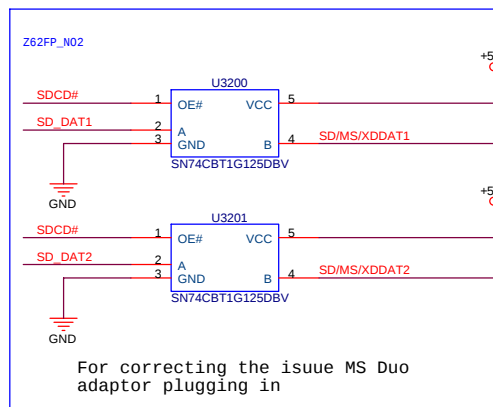
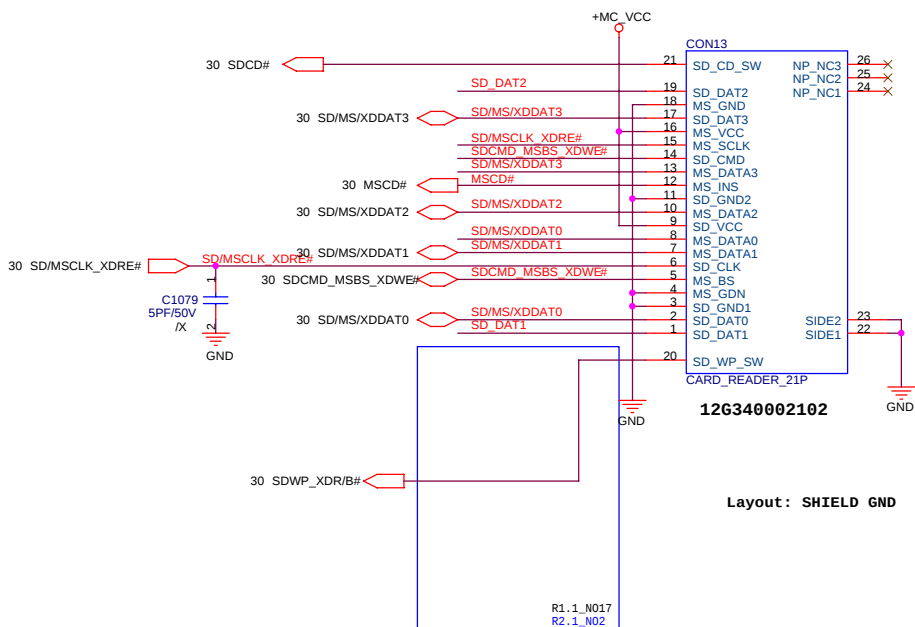
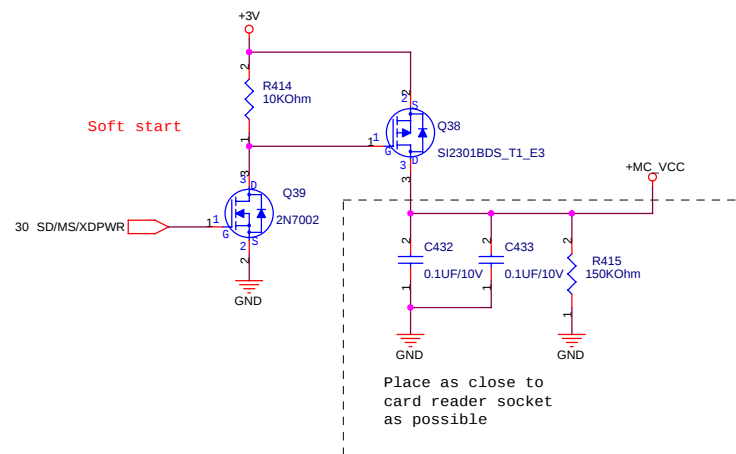
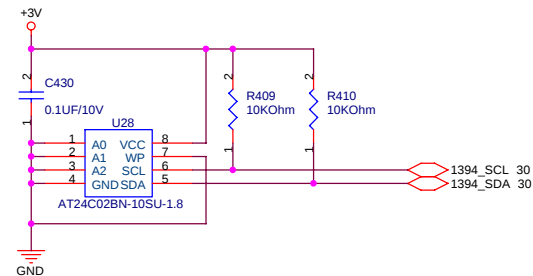
PPEN
No pull up:
Normal
Ext 10K up:
KBS interface pins are switched
to parallel port interface for
in-system programming.

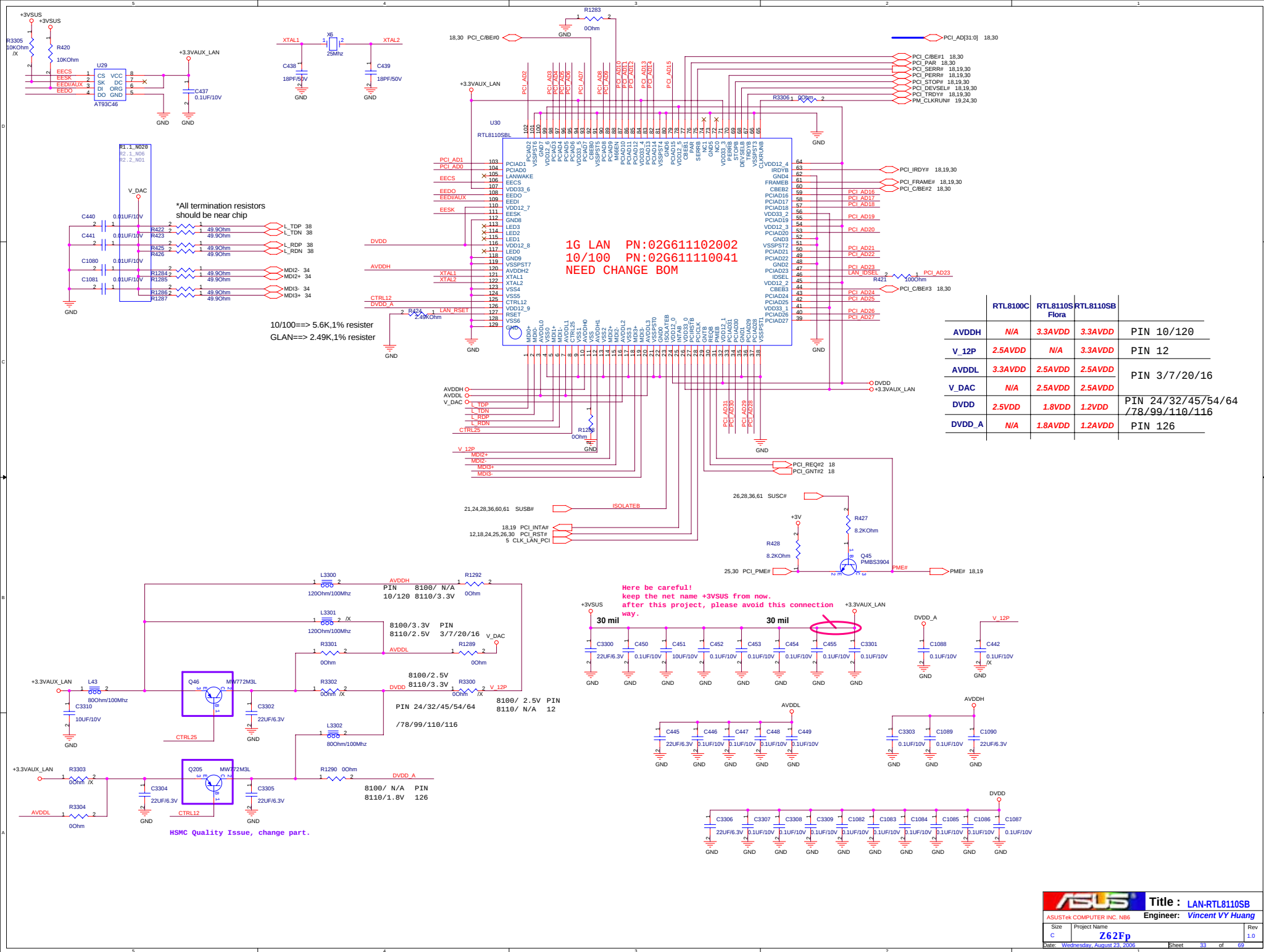




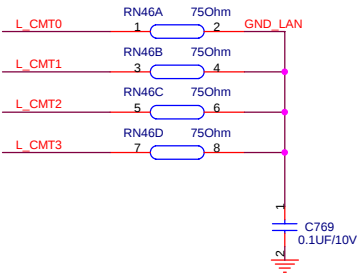
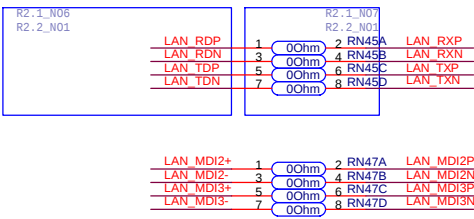
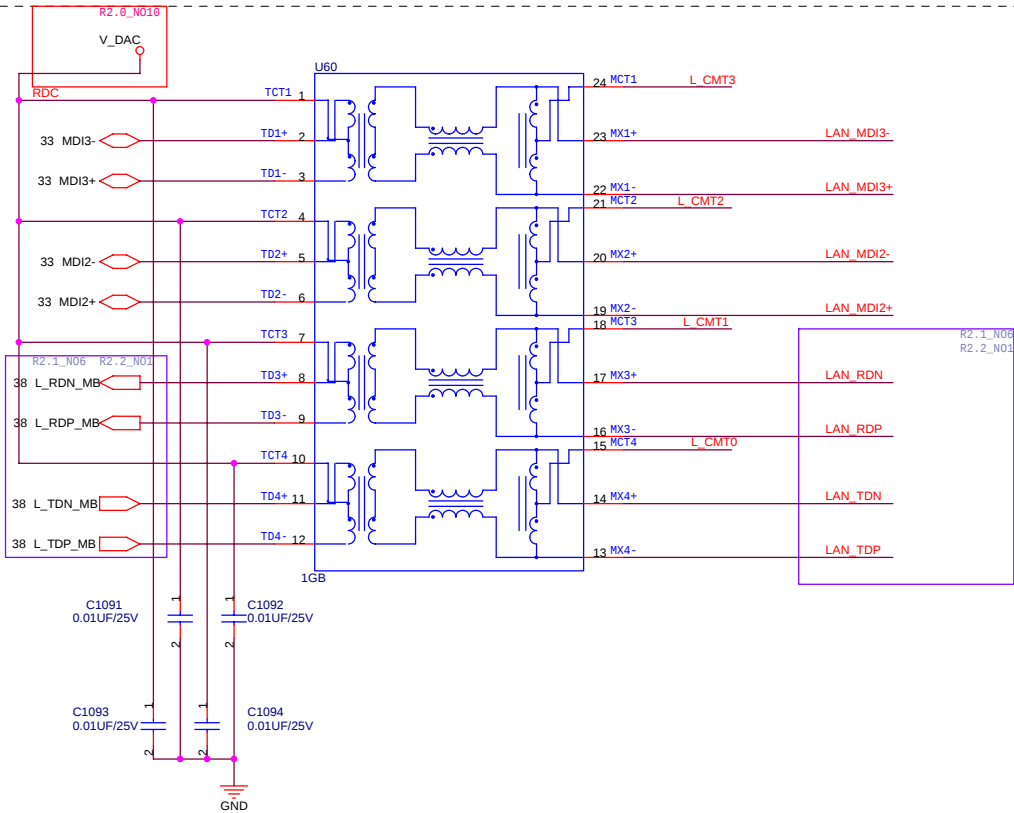
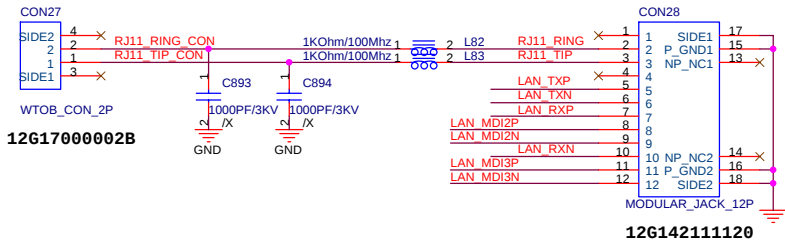
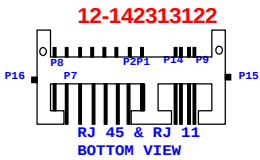


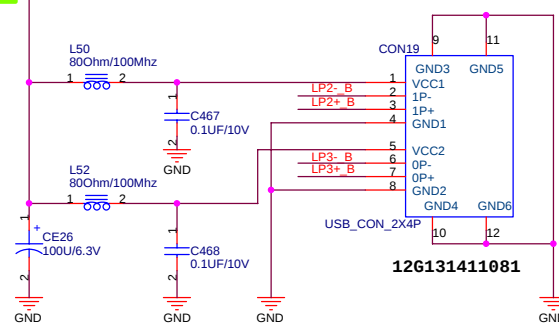
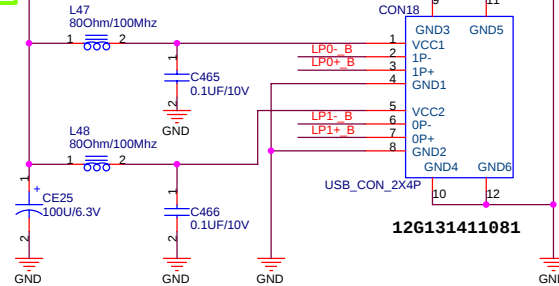
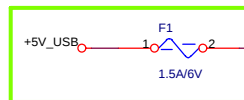
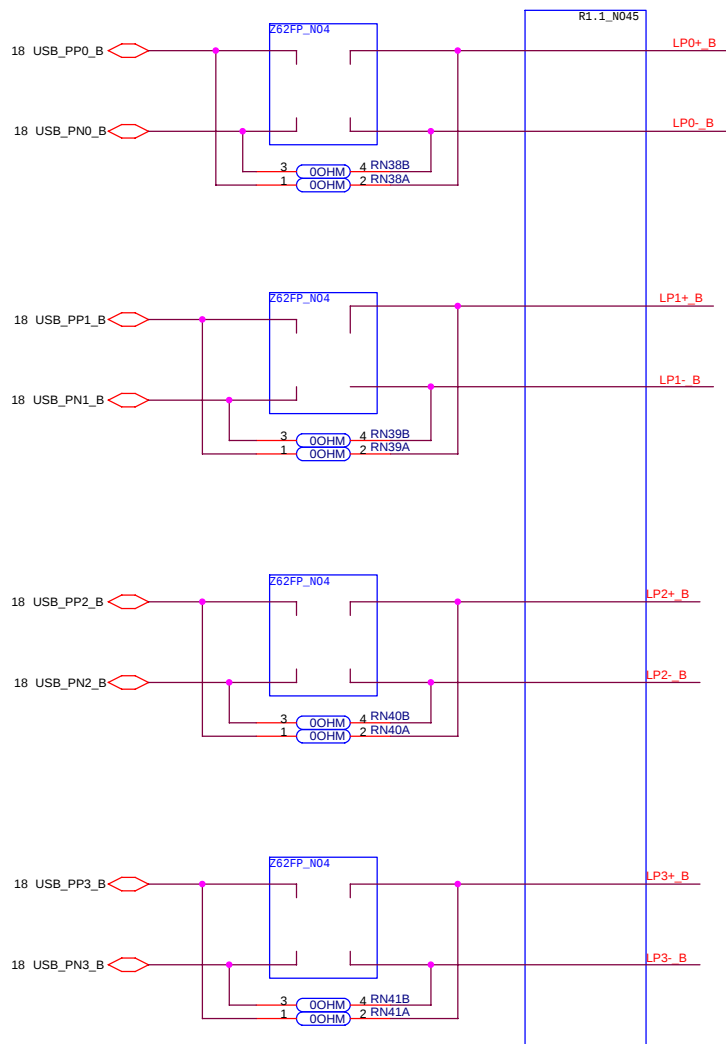
- 1.CLOSE TO R5C841
- 2.The area is as compact as possible,length < 10 mm
- 3.TPA Pair and TPB pair mismatch < 2.5mm
- 4.No via recommend , maximum is one.
- 5.Total length < 50 mm
- 6.Differential impedance is 110+/- 6 ohm
- 7.TPA Pair trace or TPB pair trace mismatch < 1.25mm





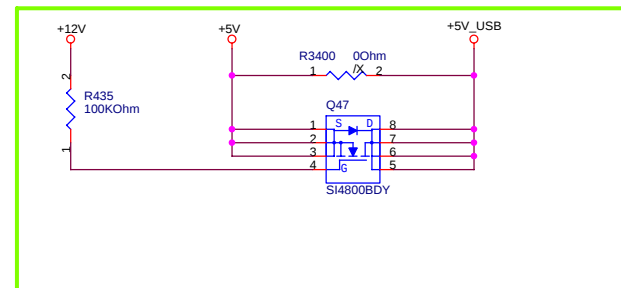
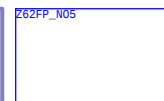
LAN PORT

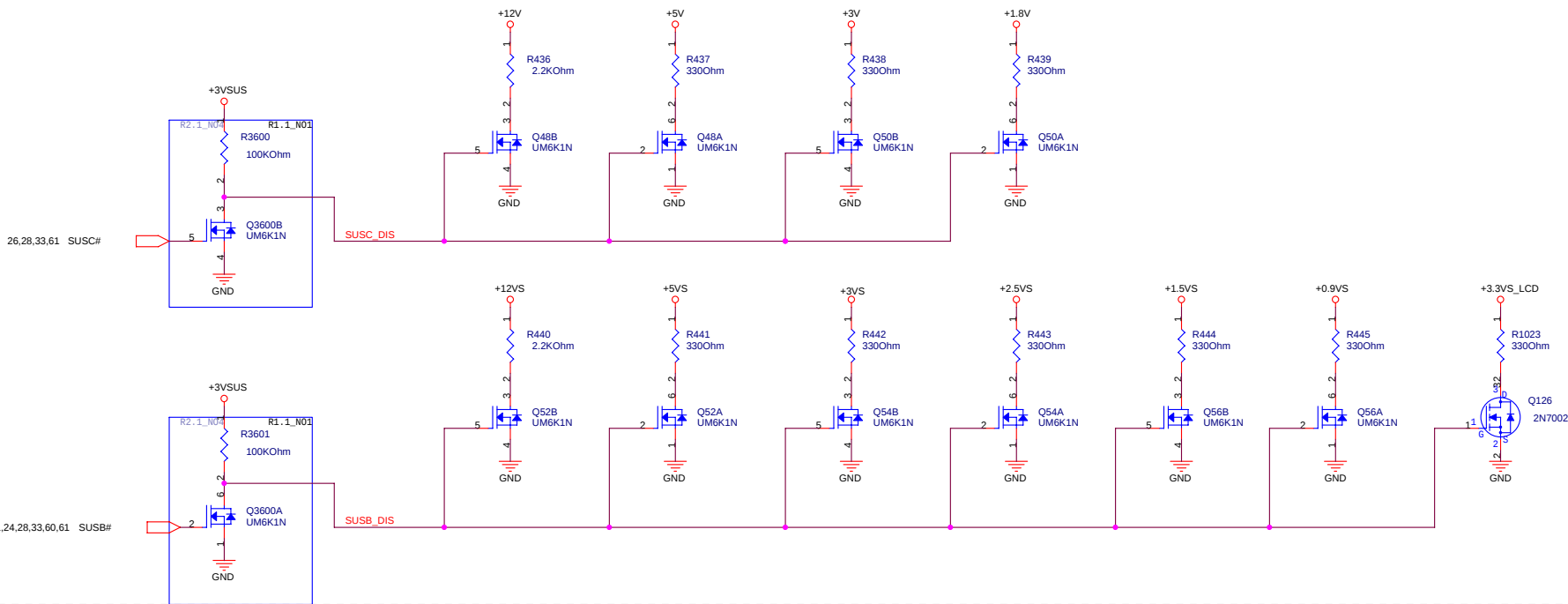


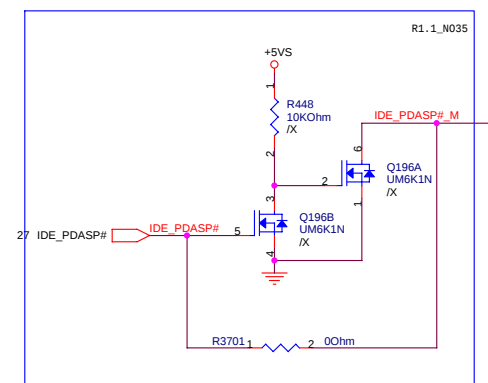
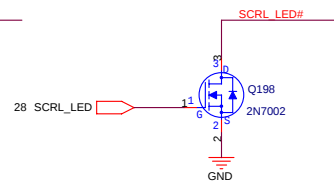
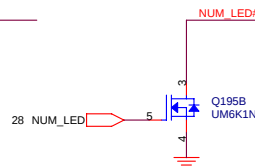
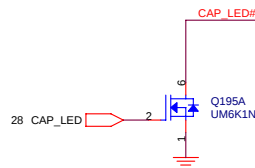
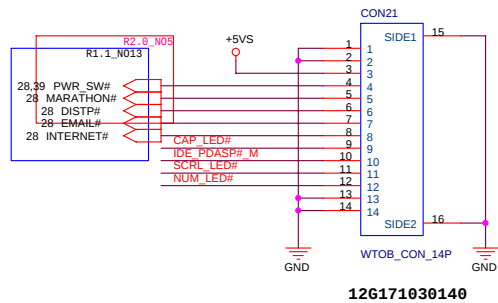


CAE modify: need check layout

Z62FM ER N03
add back MOS to solve USB power leakage

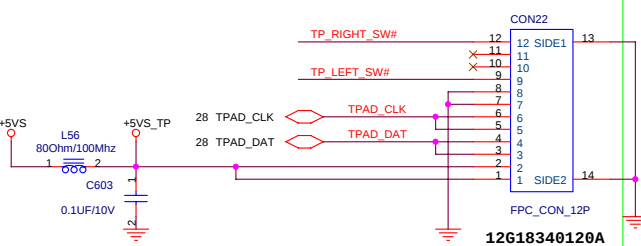
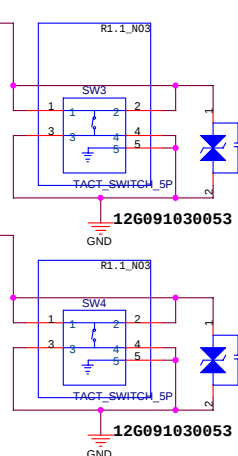






TOUCH PAD SWITCH

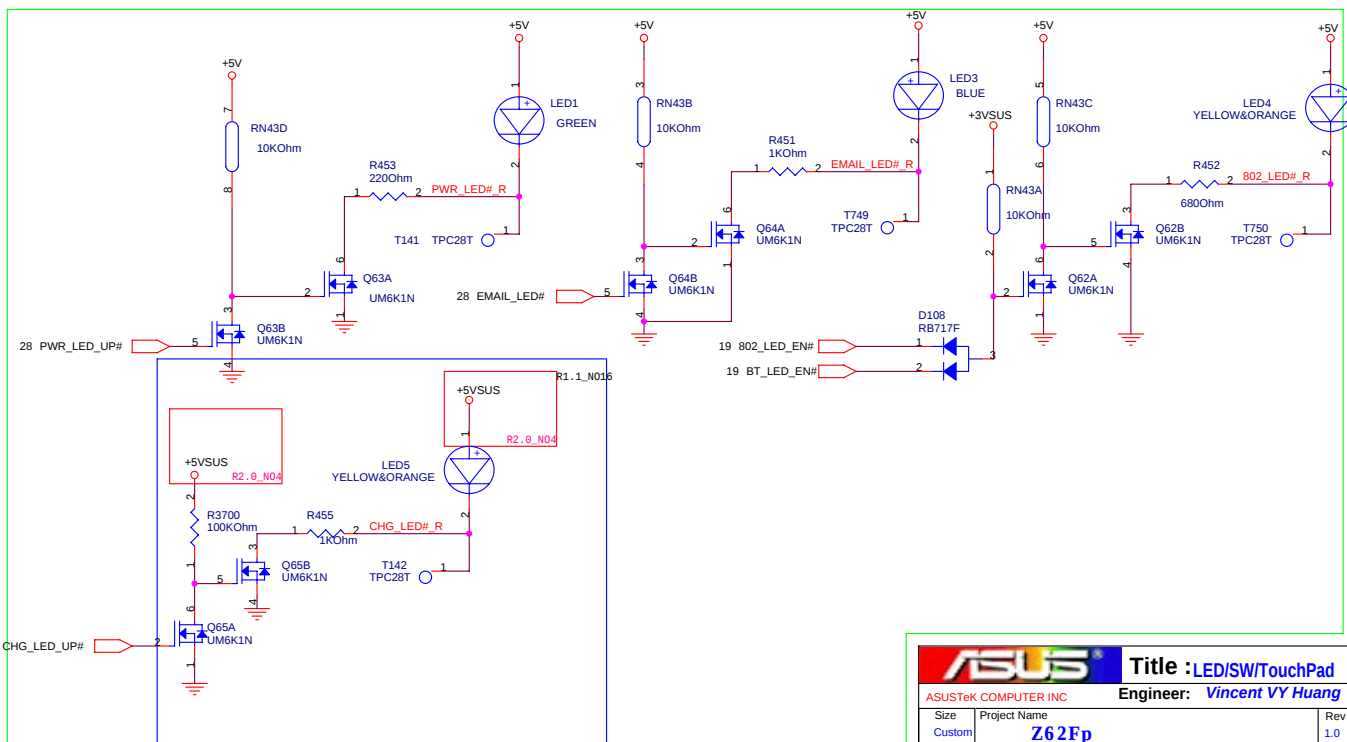
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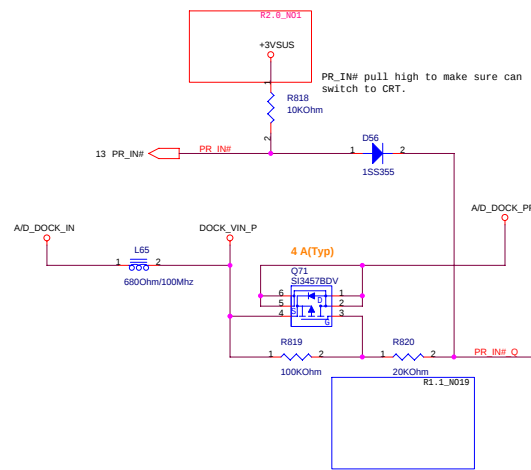


Touch pad Definition

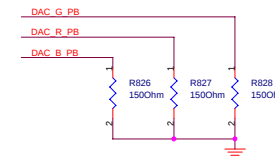
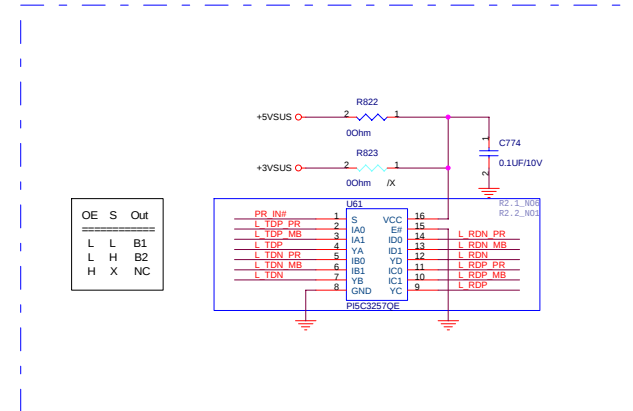
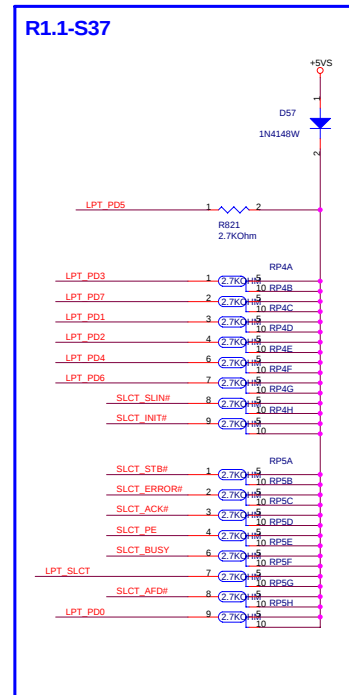
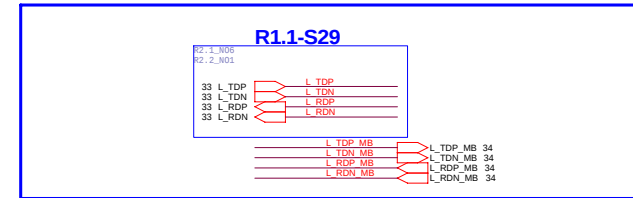
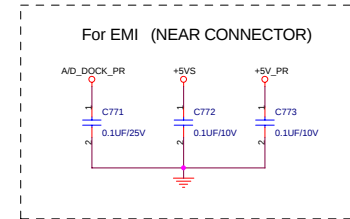
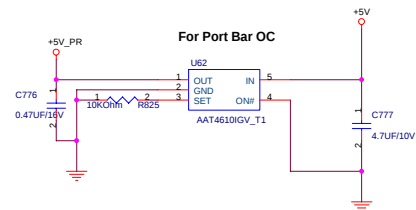
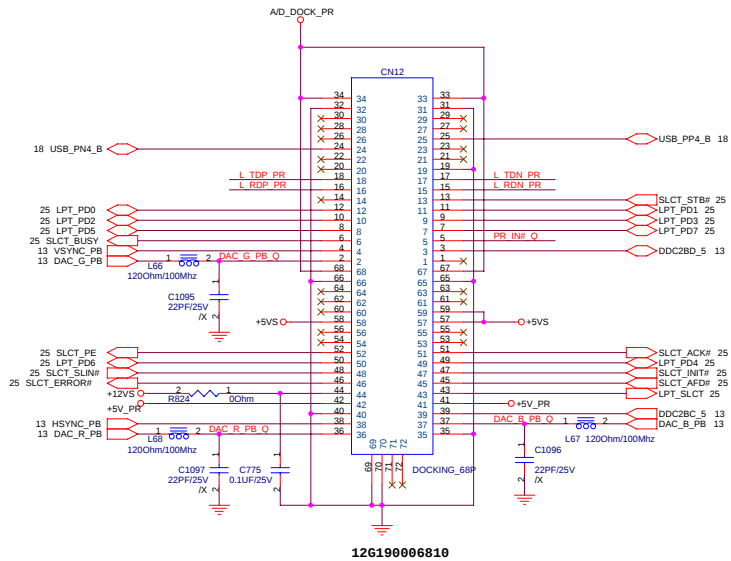
	1	2	3	4	5	6	7	8	9	10	11	12
R	x	x	L	GND	GND	CLK	CLK	DAT	DAT	VDD	VDD	

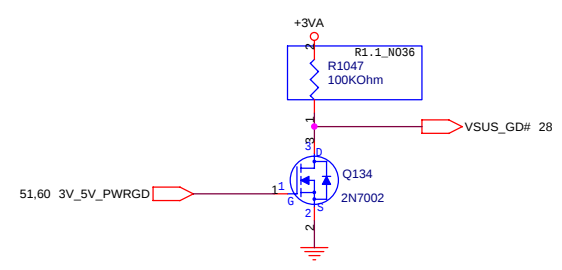
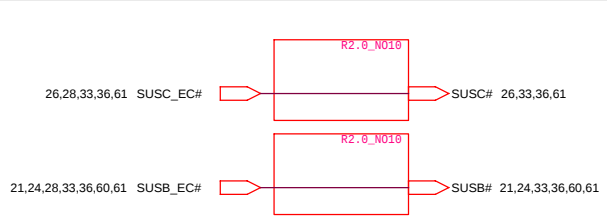
Z62F: pin1 reversal



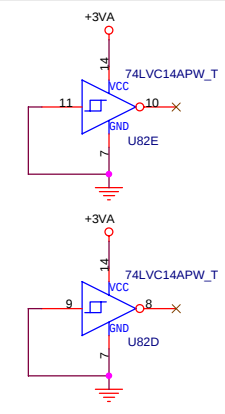
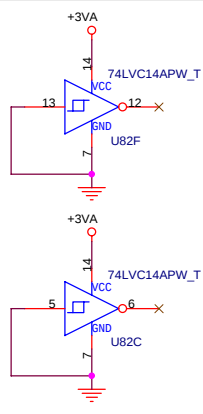
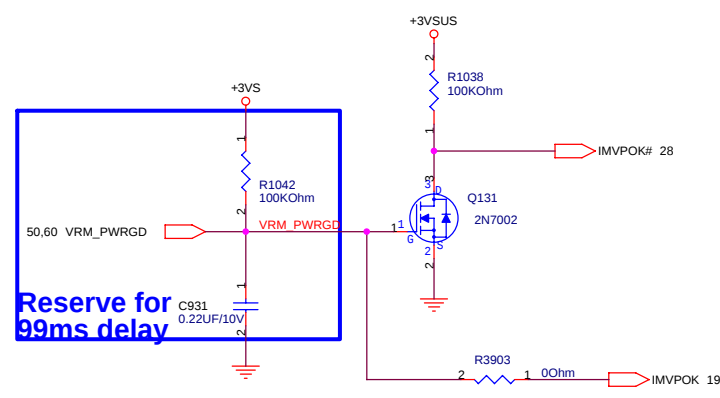


PORT BAR III CONN.

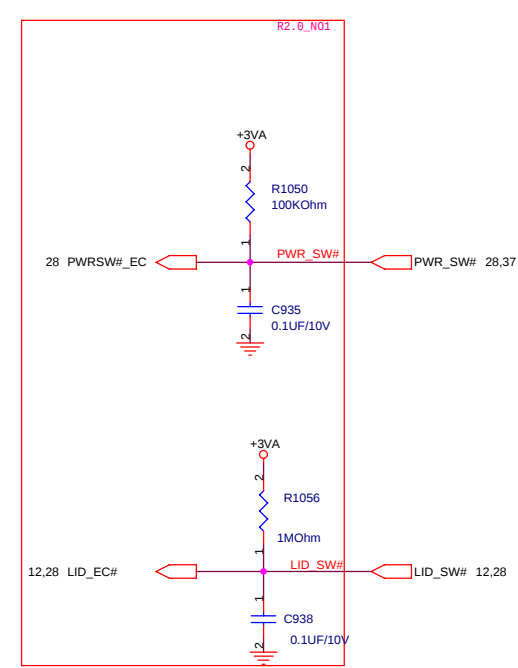


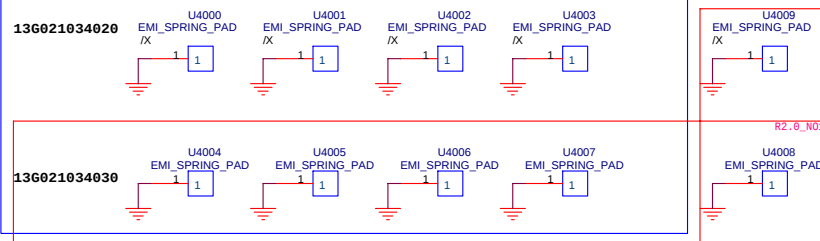
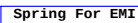
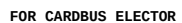
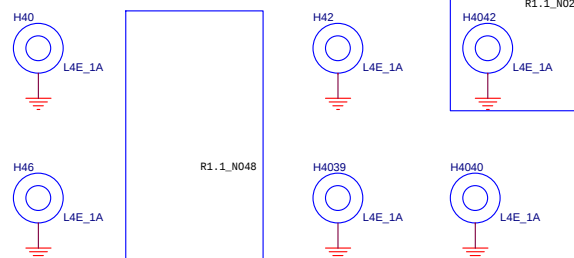
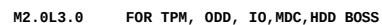
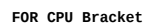


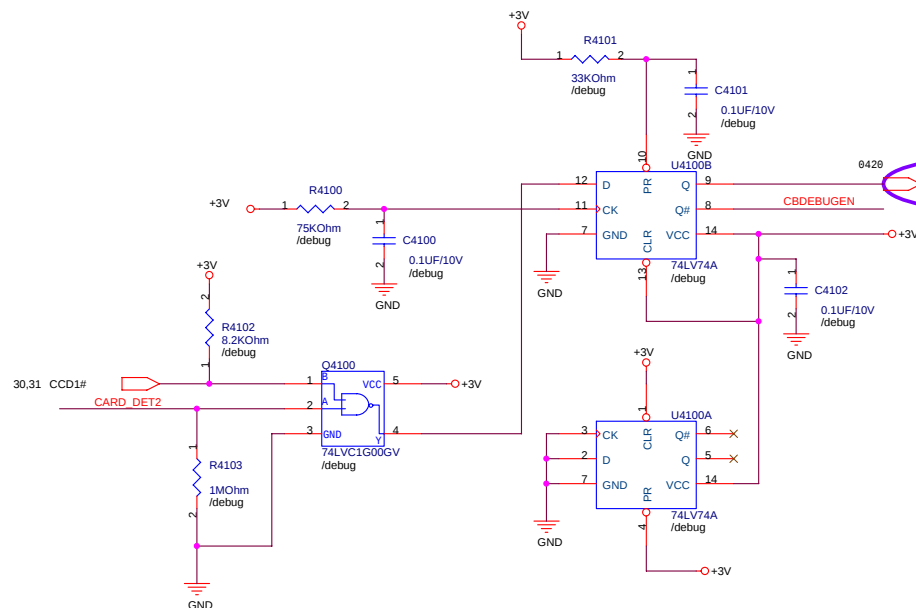
To Discharge circuits



POWER SWITCH

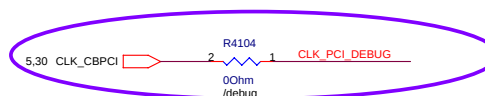






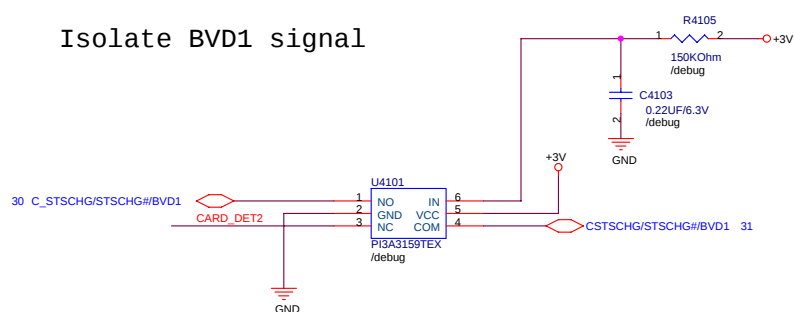
PCMCIA DEBUG PORT

Isolate card bus control and slot signal when debug card plug in

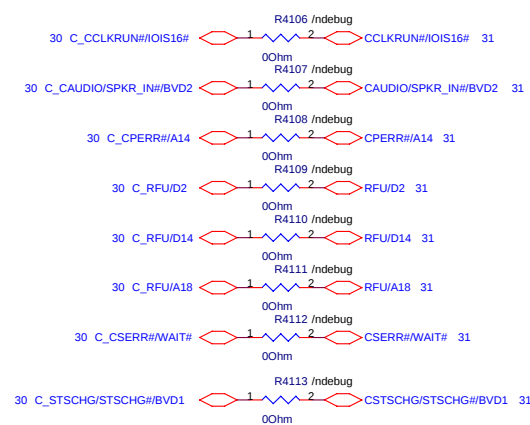
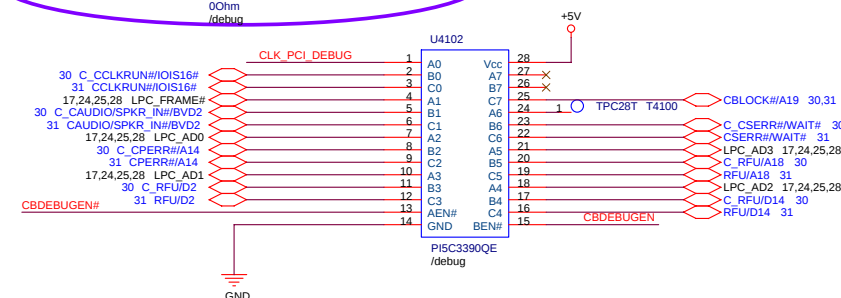


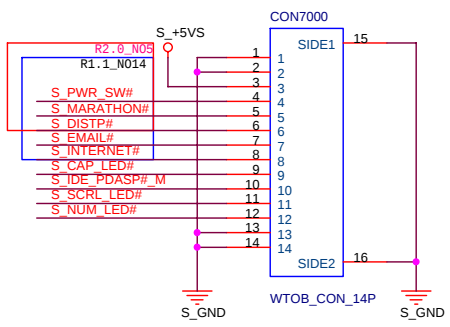
RC value may need to be tuned for each product.

Isolate BVD1 signal

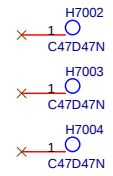
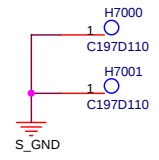
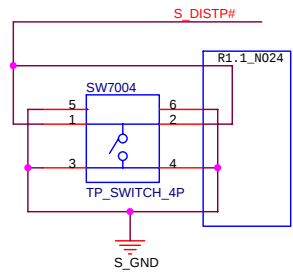
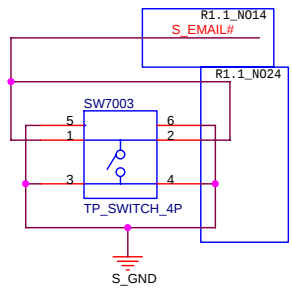
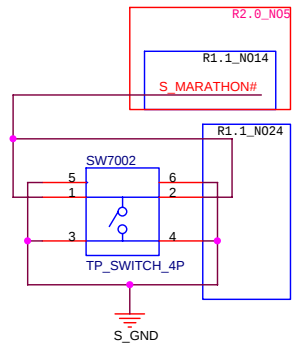
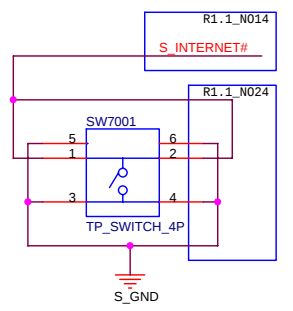
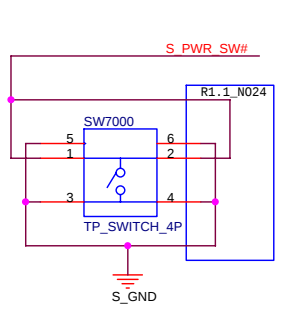
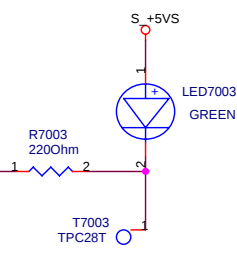
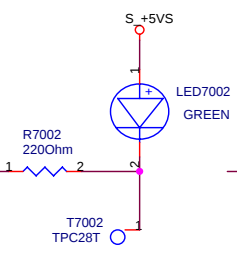
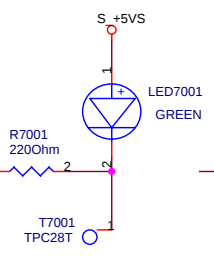
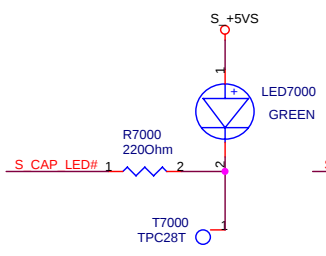


When +3V on, select BVD1 to CARD_DET2 for RC delay time

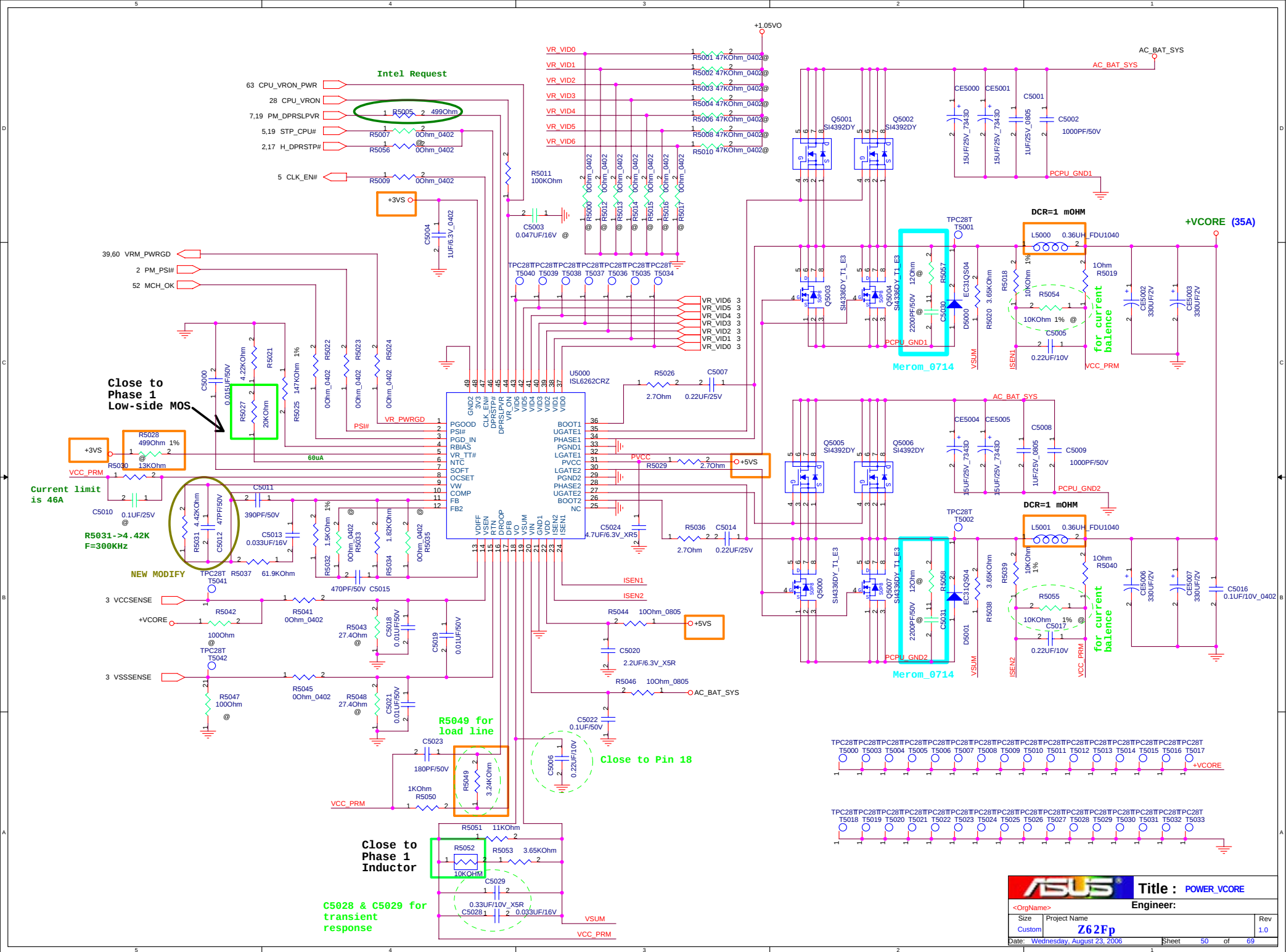


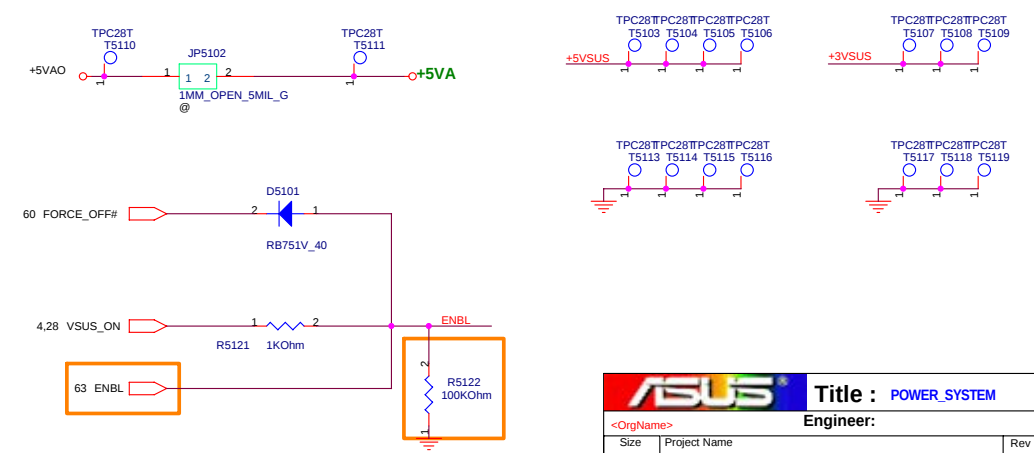
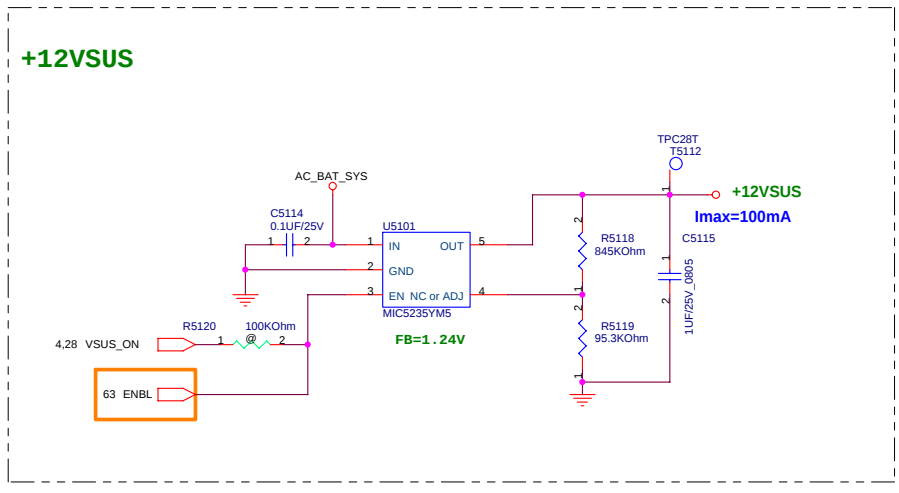
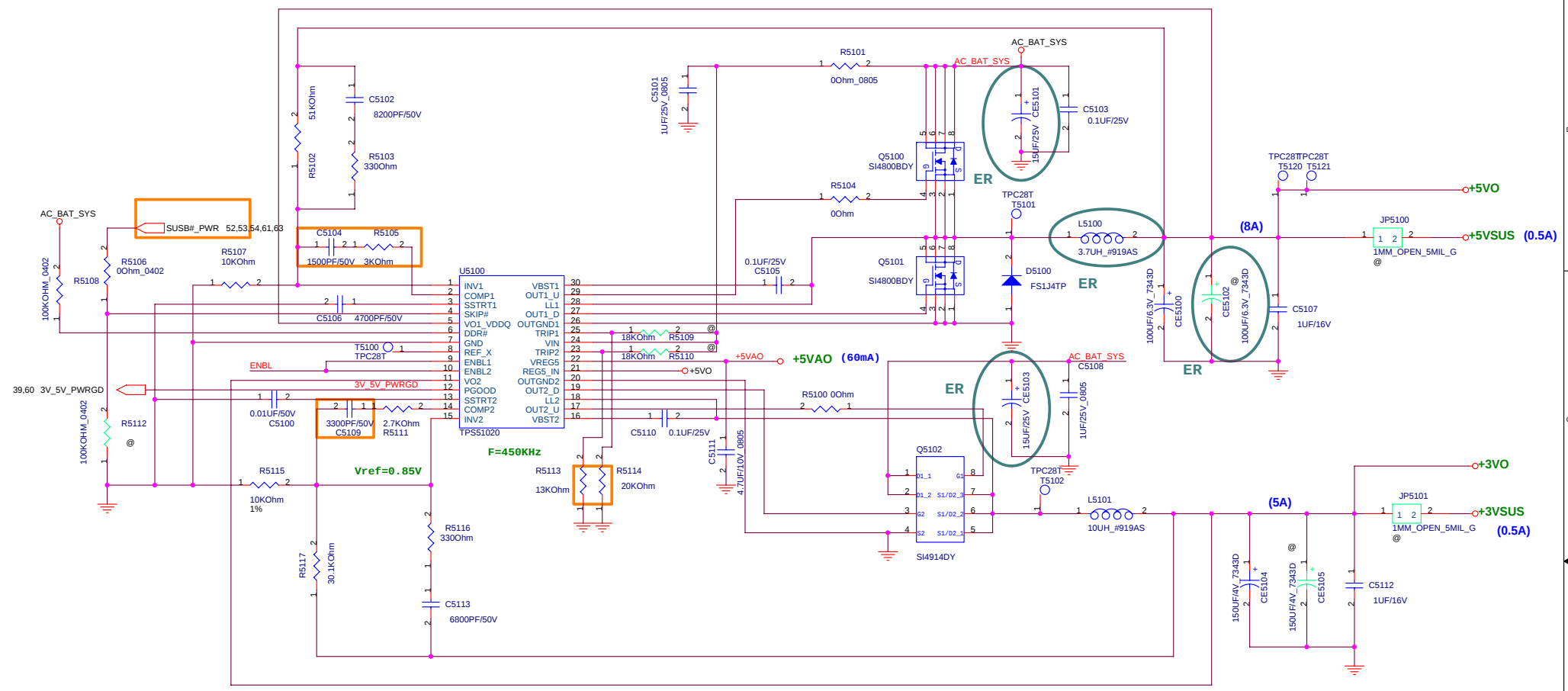


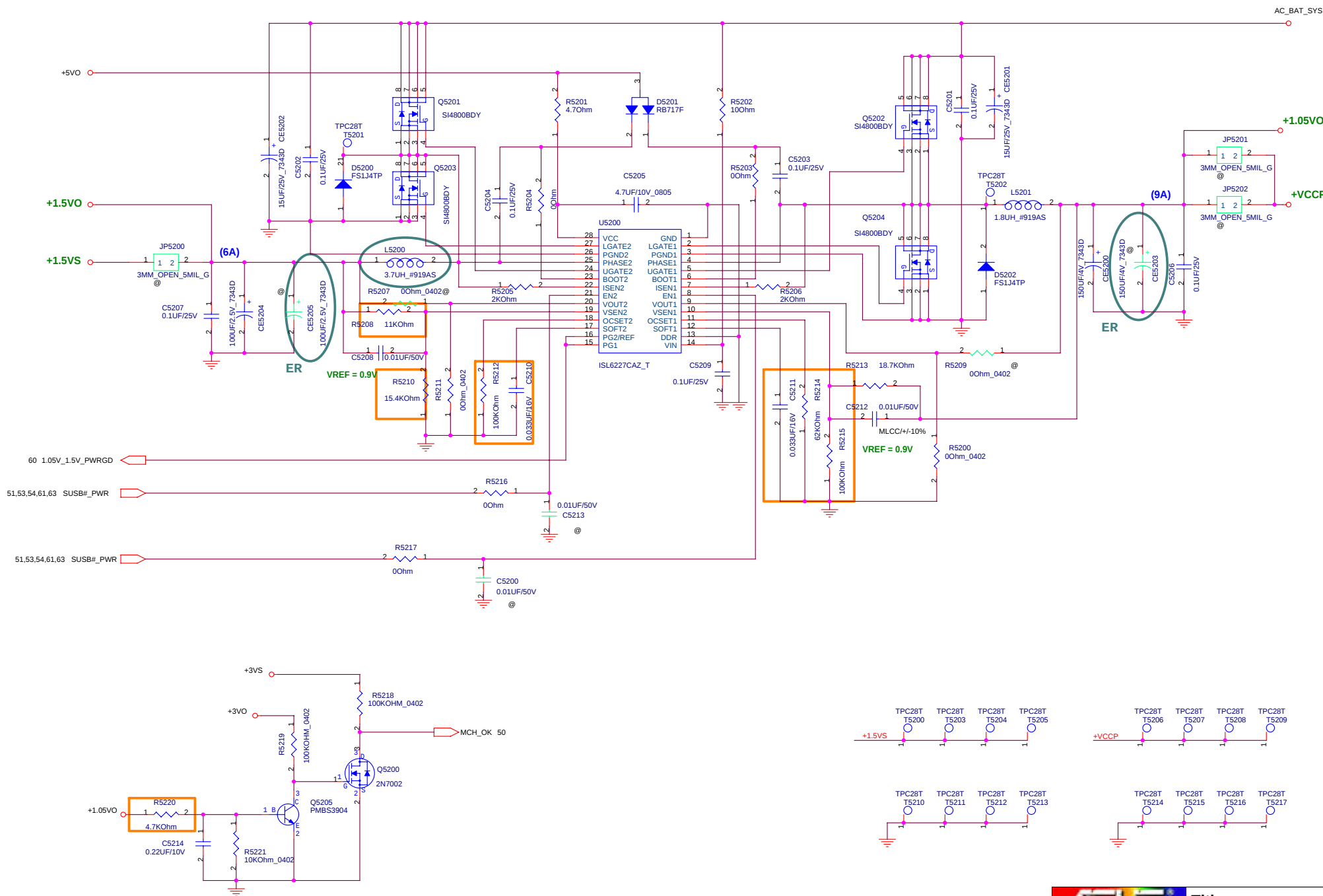
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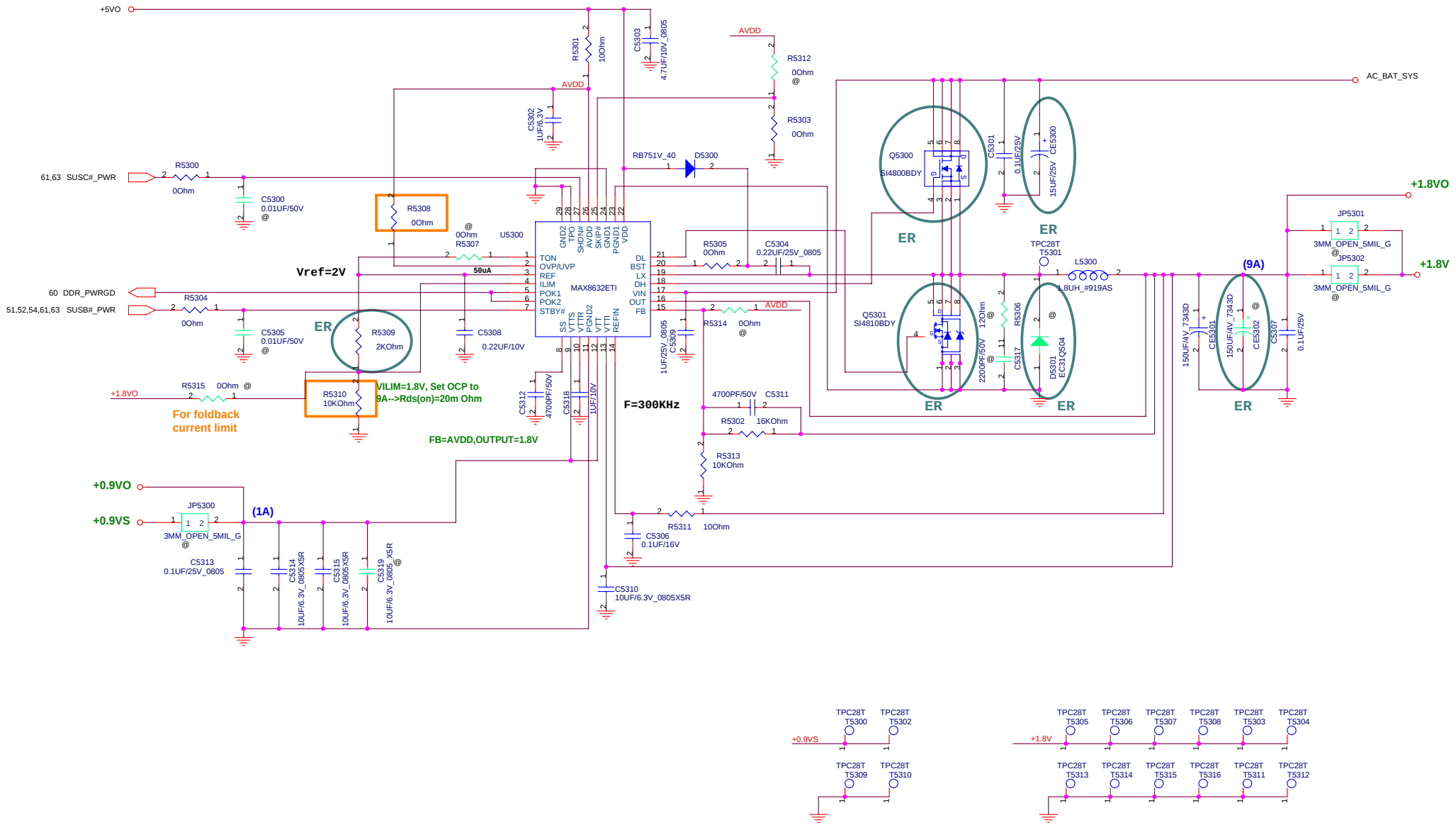




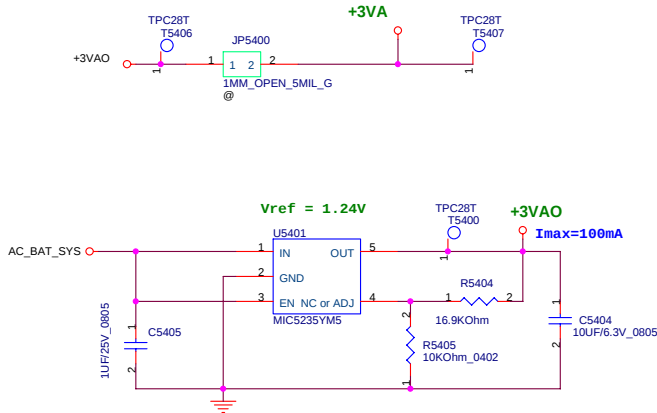




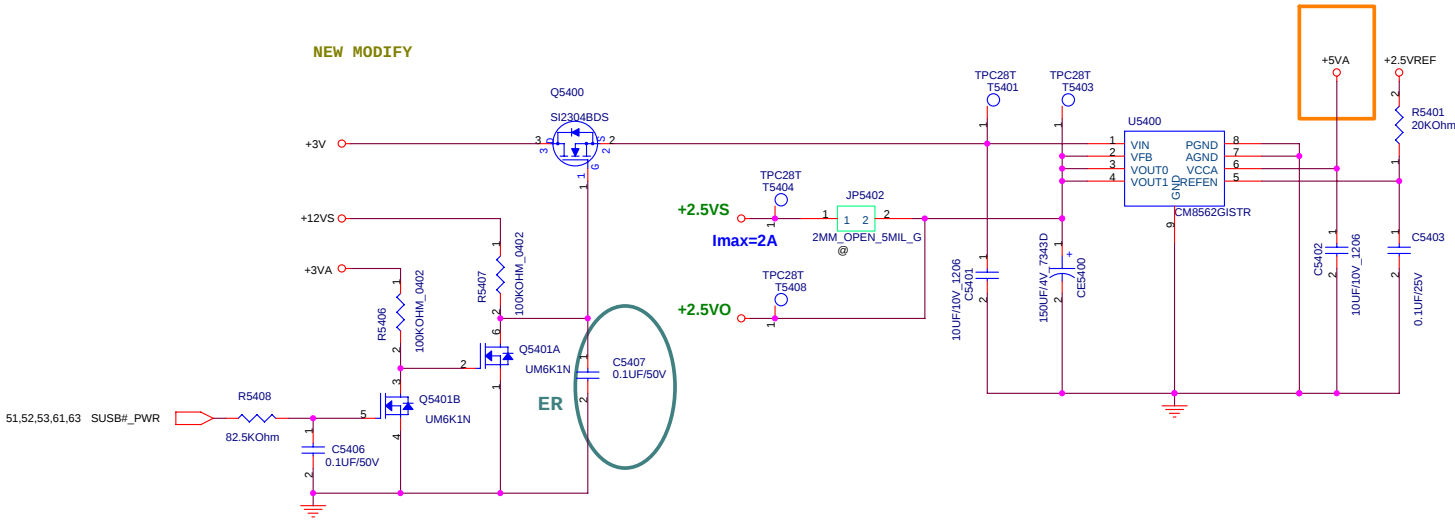


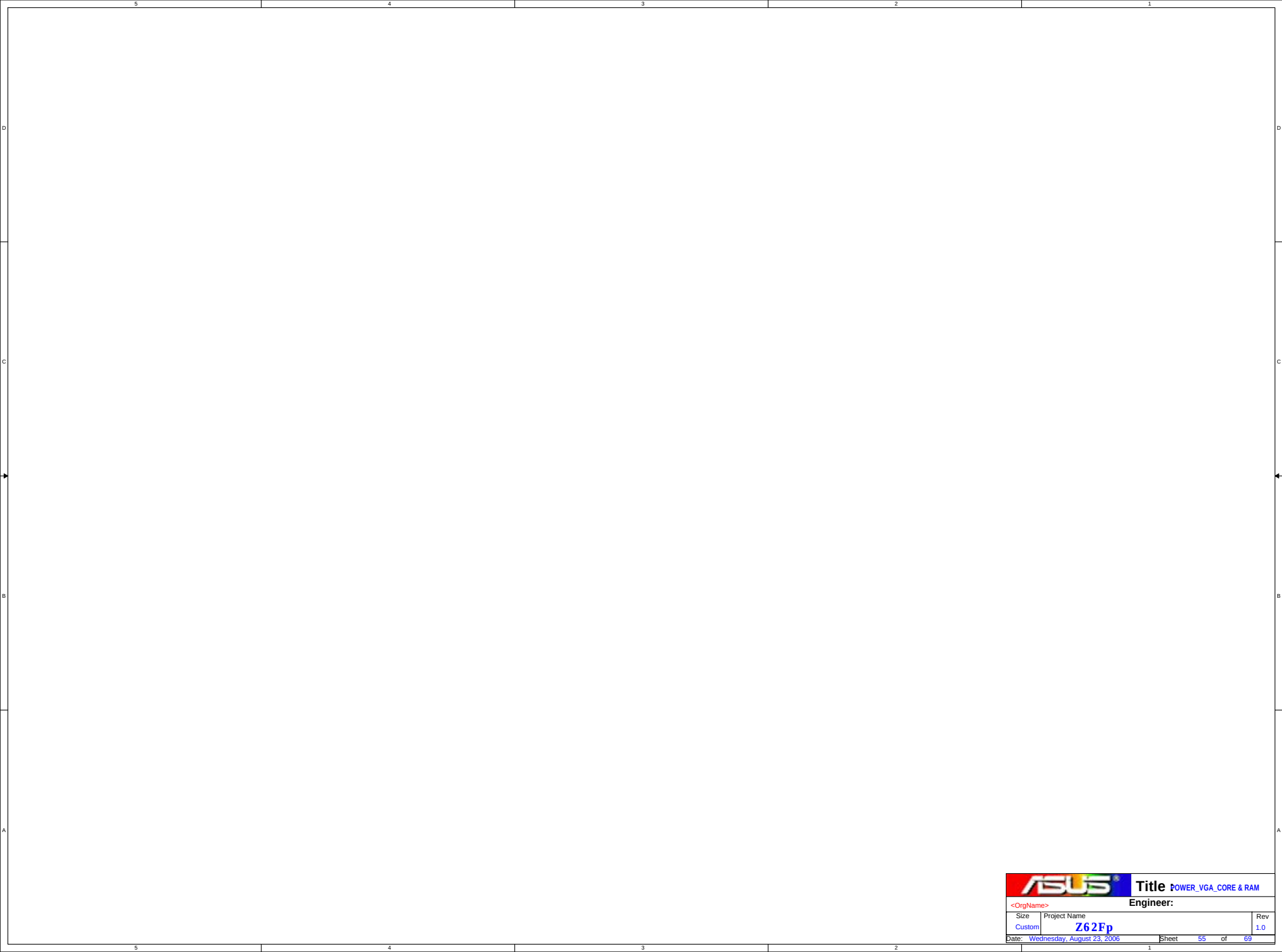


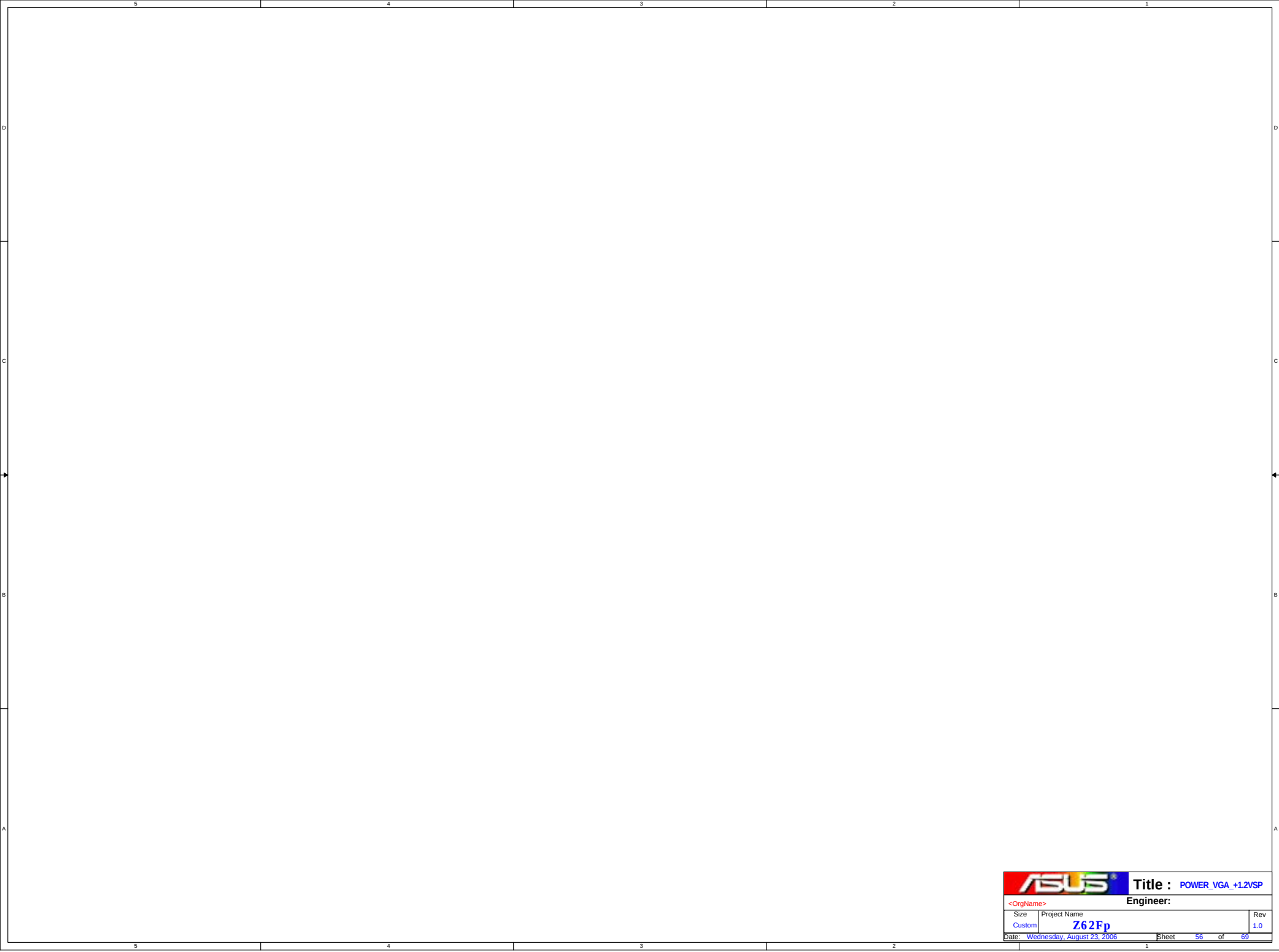
+3VA0



+2.5VS





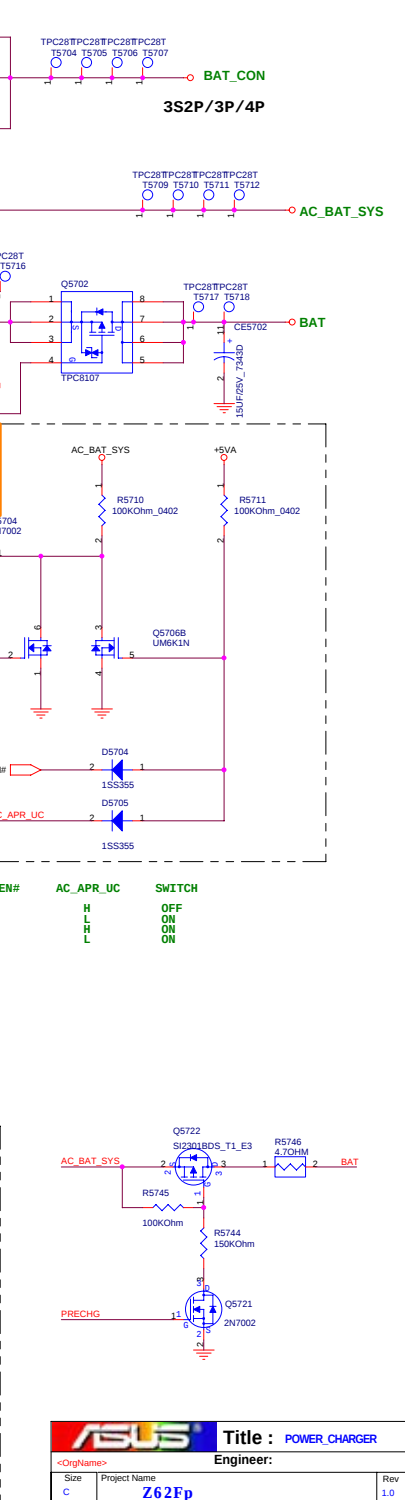
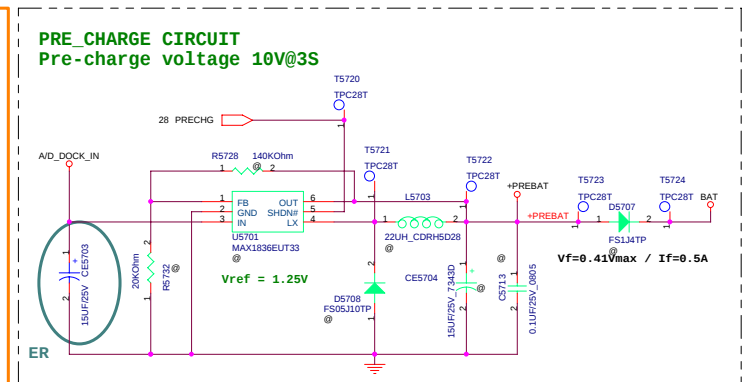
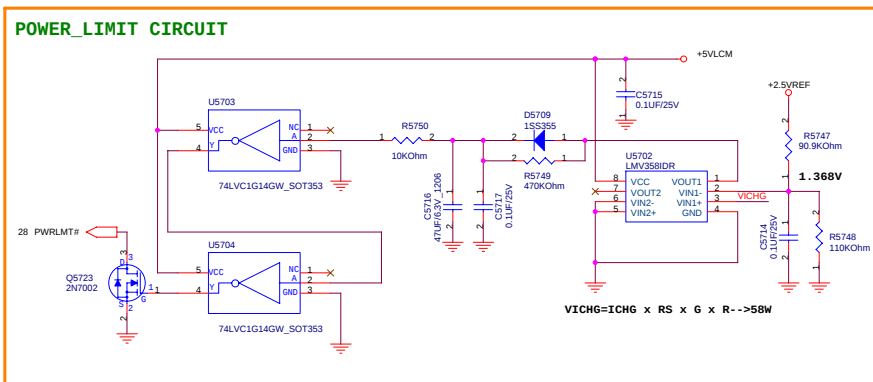
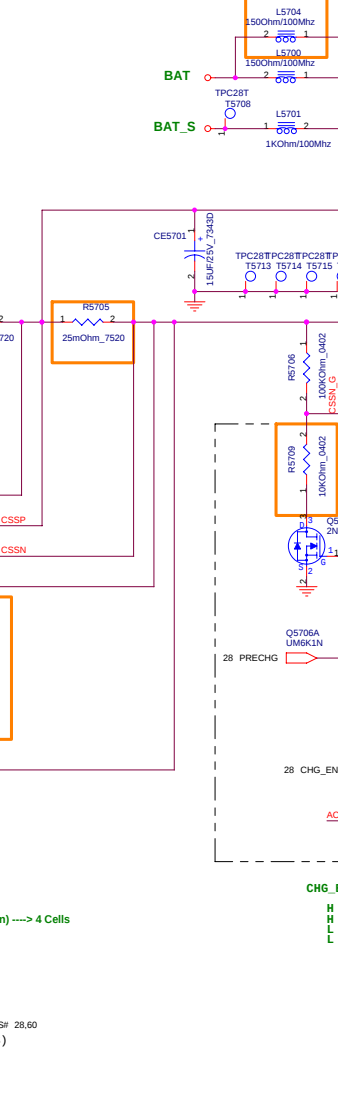
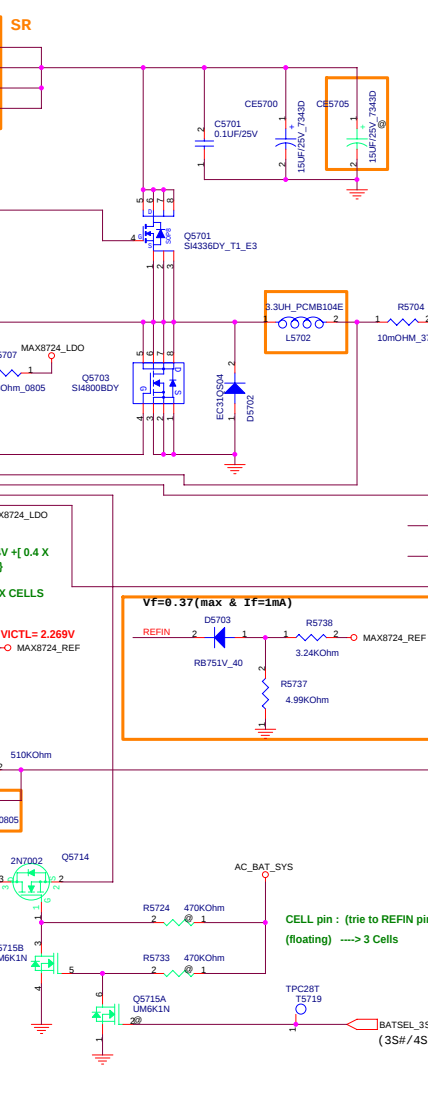
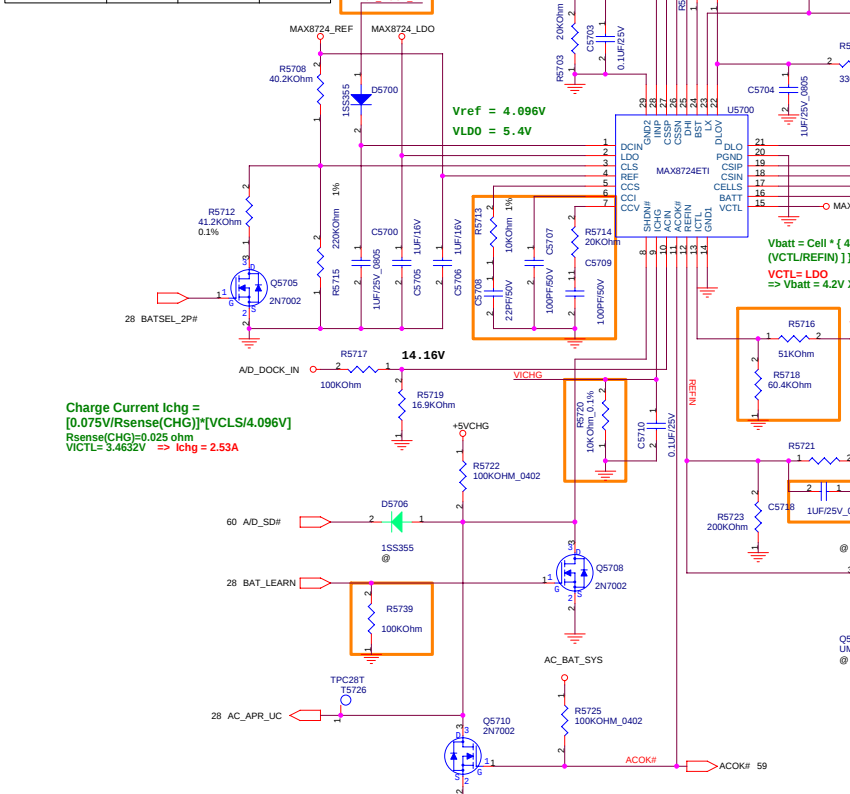


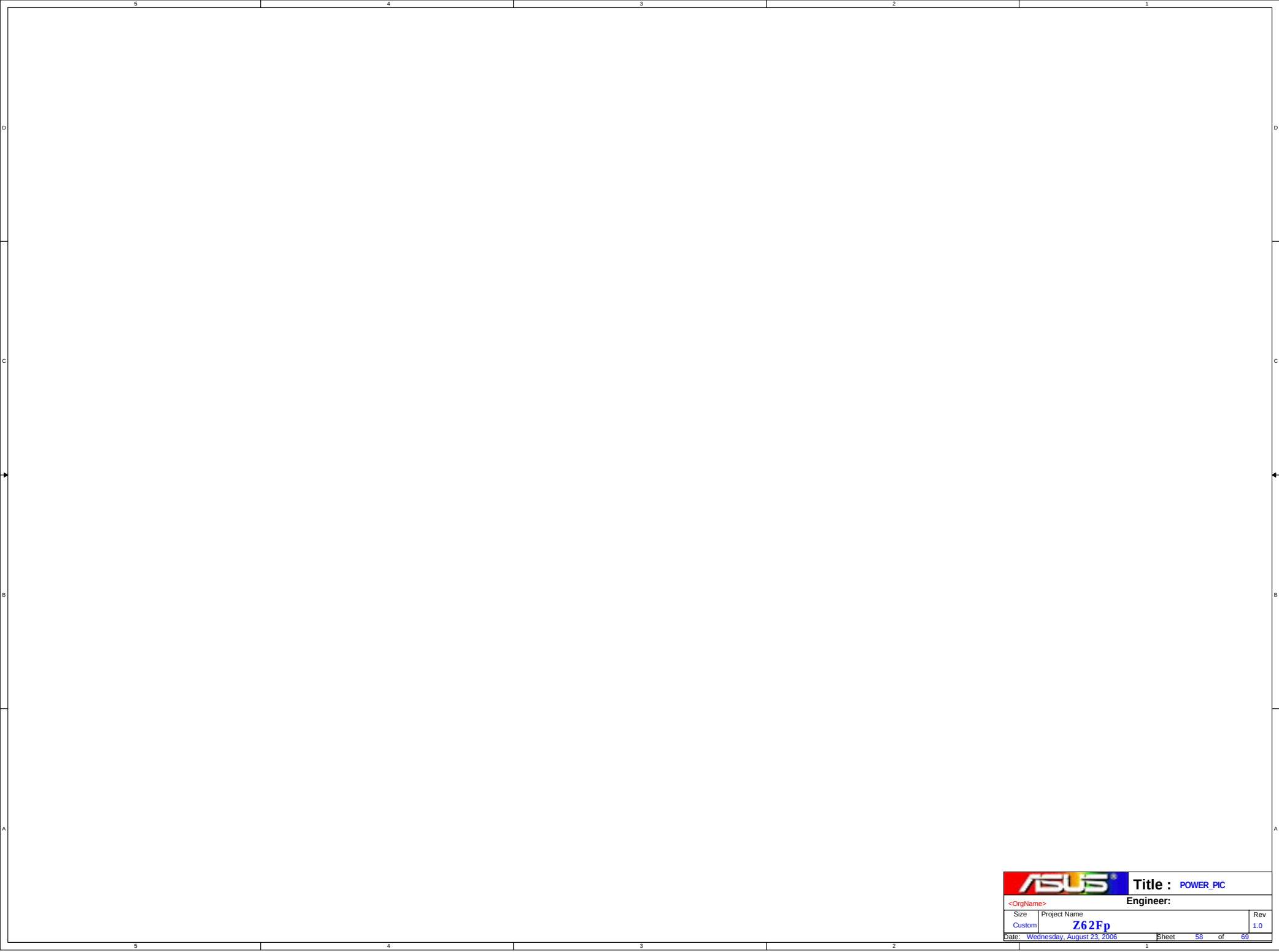
		Title : POWER_VGA_+12VSP	
<OrgName>		Engineer:	
Size	Project Name	Rev	
Custom	Z62Fp	1.0	
Date: Wednesday, August 23, 2006	Sheet 56 of 69		

TOTAL POWER=65W/19V -->3.42A

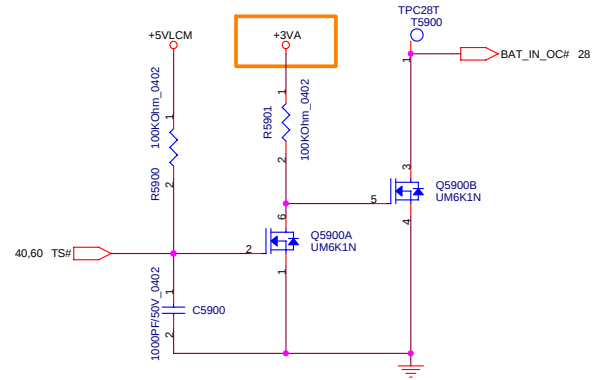
29.38,40.59,60 AID_DOCK_IN
AID_DOCK_IN

BATSEL_2P# = "H" (1P)				
BAT capacity	R5712	VICTL(V)	ICHG(A)	
2000MAH	41.2K	1.8976	1.39	
2200MAH	52.3K	2.0989	1.537	
2400MAH	66.5K	2.2918	1.679	
2600MAH	86.6K	2.4871	1.822	

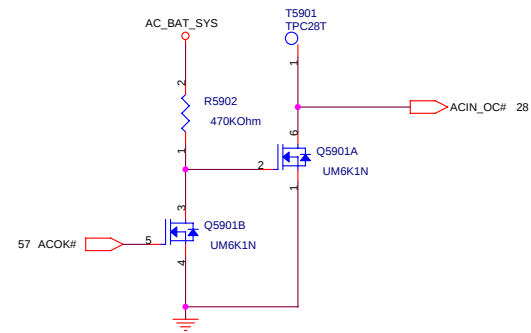




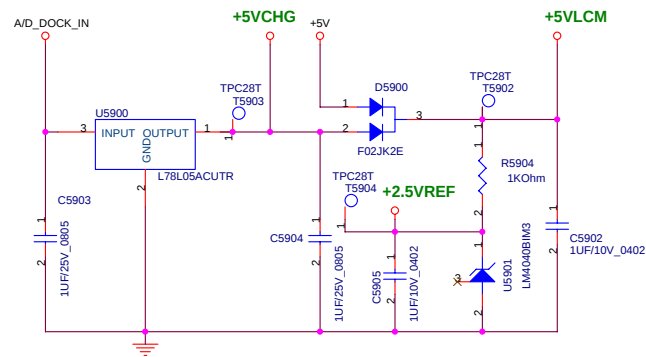
BATTERY IN DETECT



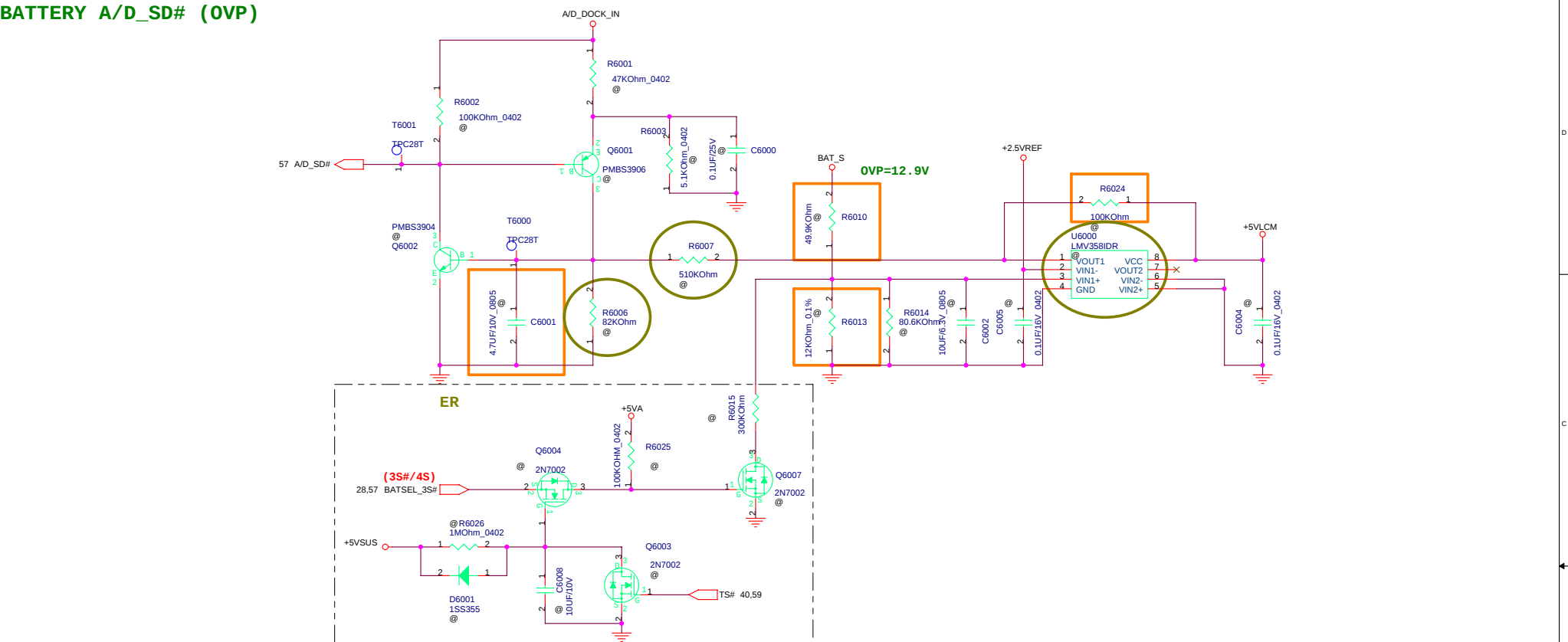
ADAPTER IN DETECT



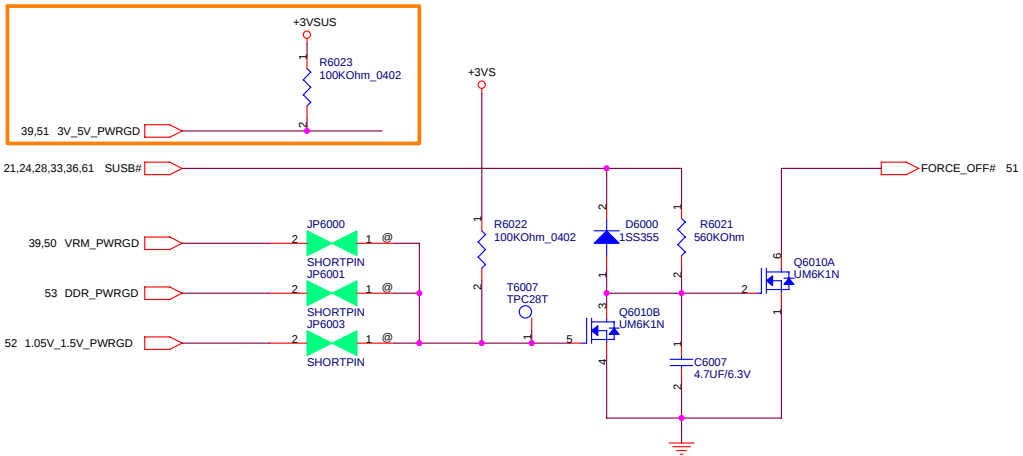
+5VLCM, +5VCHG & +2.5VREF



BATTERY A/D_SD# (OVP)

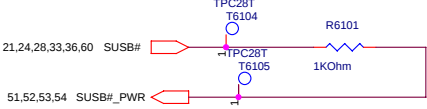
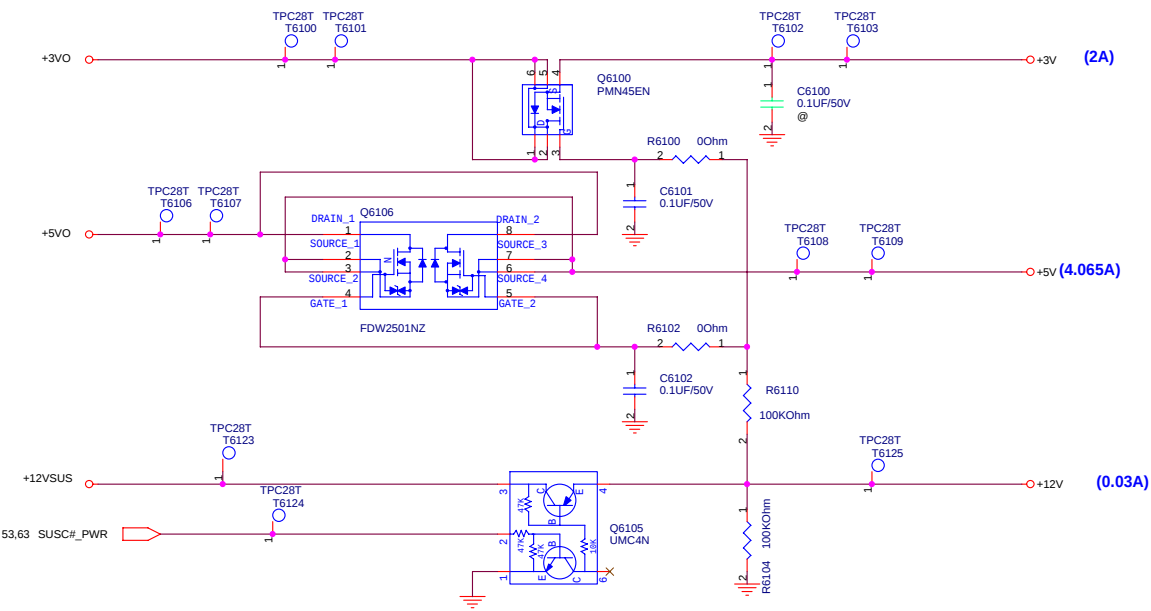


POWER GOOD DETECTOR

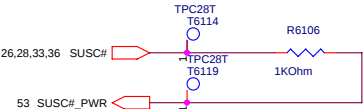
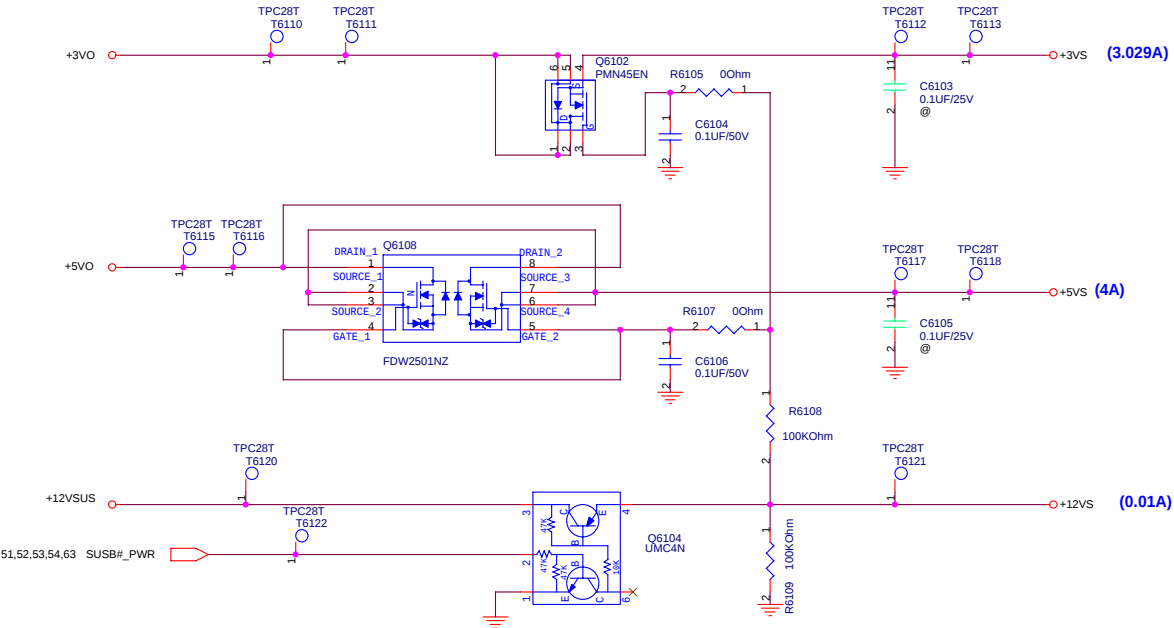


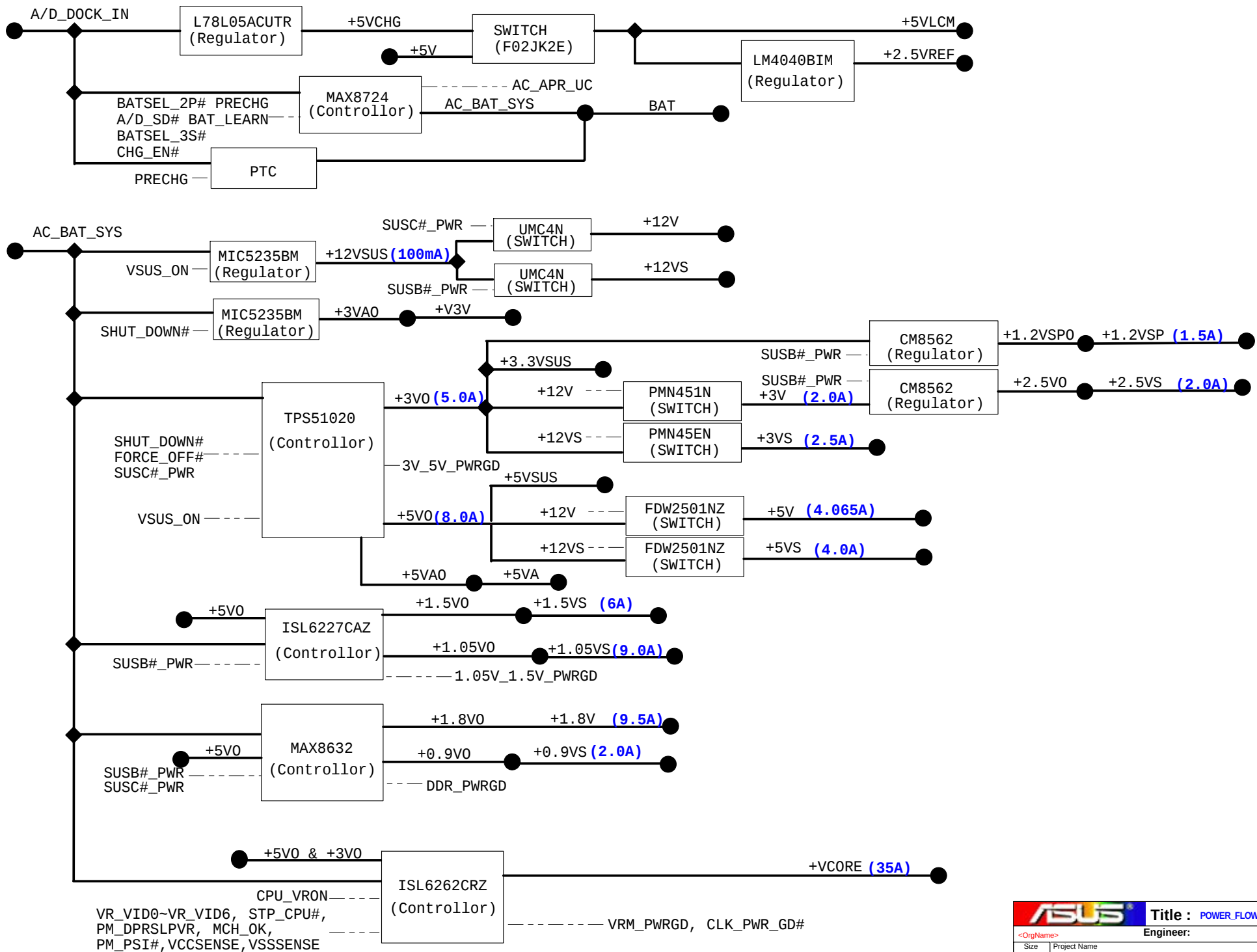
- TPC28T T6003 1 VRM_PWRGD
- TPC28T T6004 1 DDR_PWRGD
- TPC28T T6005 1 3V_5V_PWRGD
- TPC28T T6006 1 1.05V_1.5V_PWRGD

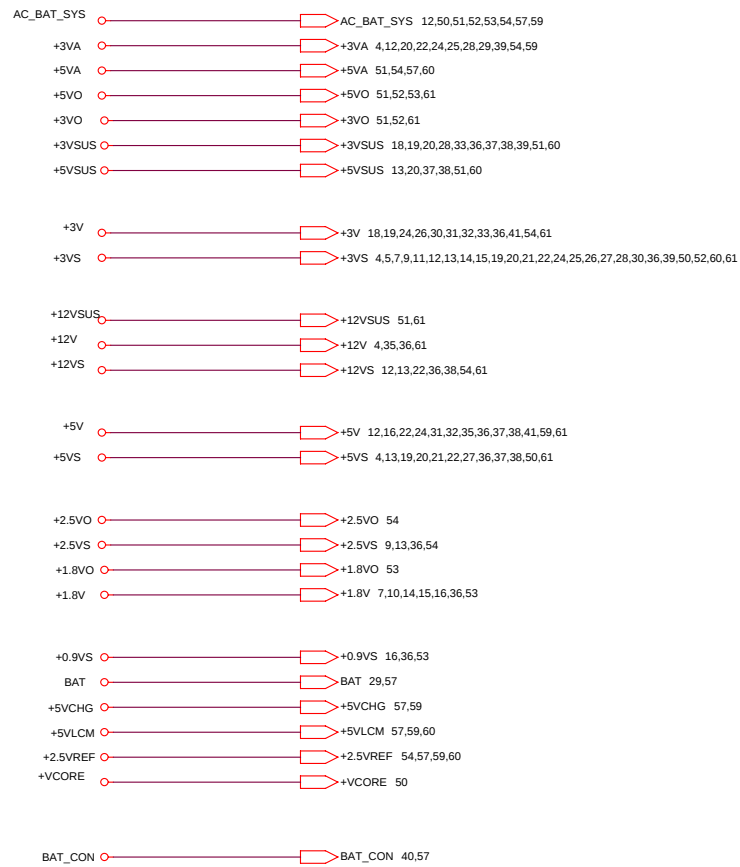
SUSC#_PWR POWER



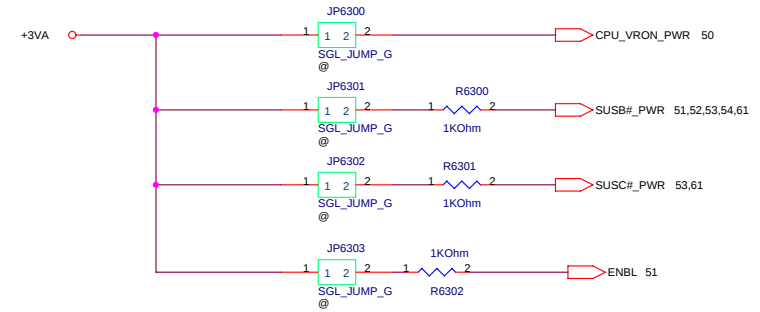
SUSB#_PWR POWER







FOR POWER TEST



R1.0

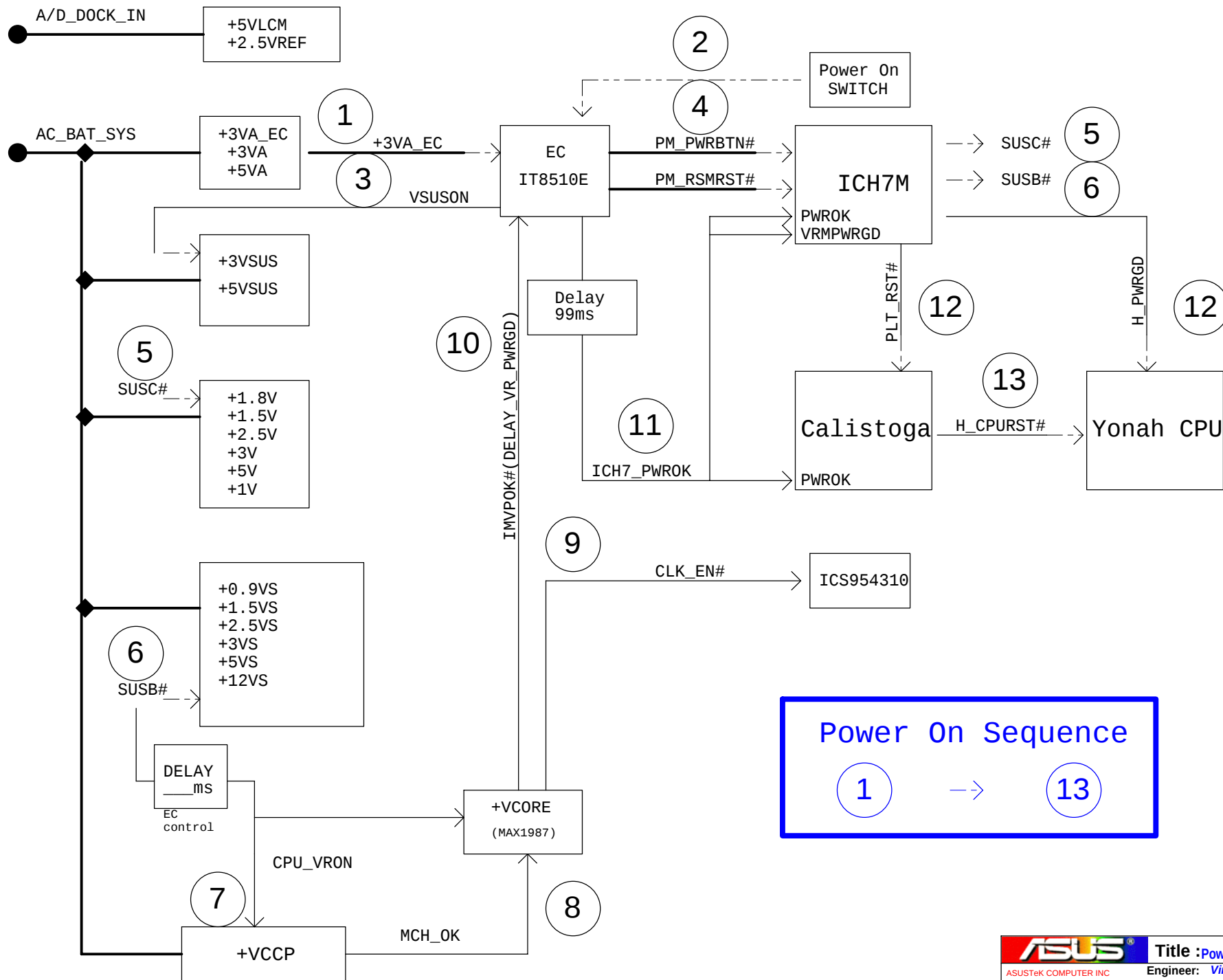
Item	Before	After	Reason	Owner	Date

R1.1

Item	Before	After	Reason	Owner	Date

R2.0

Item	Before	After	Reason	Owner	Date



Power On Sequence

1 → 13

REVISION LIST

R1.0 2005/08/23

R1.1 2005/09/23

NO1 Page36 : Add R3600,R3601,Q3600 to correct Discharge circuit logic
NO2 Page4 : Unmount R28, Page28 : Delete D2801 ==>to correct VSUS_ON power sequence
NO3 Page37: Exchange SW3 and SW4 for proper click function
NO4 Page22: Change Q22 nets to correct JACK_IN# to disable internal Speaker
NO5 Page9: Change JP29 nets to increase +VCCP supply to GMCH
NO6 Page11: Set R126 to unmount component for correct strapping
NO7 Page28: Connect CHG_FULL_LED# to GPA1 for LED indication
NO8 Page28: Connect BAT1_CNT1# to GPA2 for LIBP battery control
NO9 Page28: Move BATSEL_3S# from GPI2 to GPA6 for default pull-up pin requirement
NO10 Page28: Add PWR_LMT# at GPF6 for power team requirement
NO11 Page28: Connect BAT1_CNT2# to GPI2 for LIBP battery control
NO12 Page21: Unmount R464 and Mount R463 for proper driver setting to control mute
NO13 Page37: Re-assign Launch board connector pin define for correct function button
NO14 Page42: Re-assign Launch board pin define for correct function button
NO15 Page28: Add EXPLORER# instant key due to SPEC change

NO16 Page37: Delete Q3700,R1255, Change LED5 to single color to remove charge full LED function. Connect power to +5VCHG avoid faulty GPIO control.
NO17 Page32: Add Q3200 and R3200 to invert SD_WP signal
NO18 Page22: Delete U34, and use U82 parts to instead. And also connect the power to +3VA
NO19 Page38: Delete R1258, D105 for redundant component
NO20 Page33: Connect V_DAC bias to GLAN terminator RC
NO21 Page40: Add EMI Springs x 8, Drill196 hole x 1, Stand off x1
NO22 Page4: Delete unmount component R1025, mount C46, C47, Q5, R35, U3
NO23 Page16: Delete L23, Add R1600,R1601,C1600,C1601,C1602,U1600, Reserve R1602 for bypass VREF
NO24 Page42: Delete Unmount component D7000,D7001,D7002,D7003,D7004
NO25 Page7: Add C778,C779 to stable memory VREF on GMCH side
NO26 Page20, Page2: Delete JP4, JP1
NO27 Page10 : CE15 change to 470uF low ESR cap, CE16 change to unmount component
NO28 Page28 : Change CON11 to up-contact component for ME part change.
NO29 Page26 : Change R2603,R2606 to 33 ohm 0603 part to avoid overshoot/undershoot
NO30 Page10 : Change CE51,CE52,CE53 to 470uF for height limitation by ME.
NO31 Page : Change U1, U4, U6's PCB footprint to meet Lead free BGA PAD rules
NO32 Page28 : Change U21 to 3.0V threshold reset IC for sourcer synchronize
NO33 Page14,15 : Change M_ODT[0..3]# to make correct rank ODT function
NO34 Page26 : Delete R1059,R1060,R1061,Q141,Q142,C939,C940,L93 for BT part reduce
NO35 Page27,37 : Change R342,R448,Q196 to unmount component, Add R3701 to bypass the circuits
NO36 Page39 : Change R1047,R1269 to 100K ohm to reduced power consumption
NO37 Page9 : Delete L91, Change CE50 to 10uF 0805 capacitor
NO38 Page7 : Add R703 to support C4E Fast exist latency
NO39 Page22: Change the HP mute circuits to behind decoupling capacitors
NO40 Page9: Change the CE8 to Common 330uF part use
NO41 Pag21: Add R2100,R2101,R2102,R2103 ohm resistor for EMI solution
NO42 Pag40: Add R4000,R4001 unmount part to reserve pull low
NO43 Pag17: Change X2 to ROHS compliant parts
NO44 Pag28: Change X4 to ROHS compliant parts
NO45 Pag35: Delete D37,D38,D39,D40,D41,D42,D43,D44 for Moat fine tune requested by EMI
NO46 Pag5: Change R70,R77,R79,R83 to 39ohm for fine tune clocks
NO47 Pag28: Delete JP7 and short +3VA_EC to +3VA
NO48 Pag40: Delete H41, H47 to sync ME drawing

NO49 Pag22: Change J2 connector by ID/ME's request

R2.0 2005/11/29

NO1 Page38 : R818 pin1 connect to +3VSUS to solve S4 WOL fail issue
Page13 : U80 pin16 connect to +5VSUS to solve S4 WOL fail issue
NO2 Page39 : Delete Q135, R1051, R1054, D82, D84, C934 for reduce component
NO3 Page19 : R156 pin1 change to +3V to meet Check list
NO4 Page37 : R3700 and LED5 change to connect +5VSUS to solve Battery low blinking indication no function issue.
NO5 Page28,37,42 : Delete EXPLORER# key and add back P4G instant key for PM's request
NO6 Page24 : Change TPM's power supply to +3V to avoid S5 leakage current
NO7 Page2, 28 : Add Q200 to support THRO_CPU function on to PROCHOT#.
NO8 Page22 : Add R2201, R2202 to reserve set high gain of AMP
NO9 Page23 : Change C2305 to 1uF for cutoff frequency fine tune
NO10 Reduce 0ohm resister=>R703, R1263, R195, R1900, R1901, R2000, R462, R469, R458, R2800, R347, R349, R387, R391, R1293, R3900, R3901
NO11 Page40 : Change U4004,U4005,U4006,U4007 and add U4008 and U4009 to match EMI Spring modify requirement
NO12 Page9: Add C956, C957, C958, C959 for EMI's request
NO13 Page7: Set R108 to unmount component
Page28: Set D2800 to unmount component

R2.1 2005/12/20

NO1 Page40 : Mount R4000 and R4001 to make CNT1 and CNT2 have pull down source
NO2 Page32 : Delete R3200 and Q3200 for SD_WP proper functionality
NO3 Page27 : Disconnect CON10's pin53 and pin54 from GND connection(NPTH)
NO4 Page36 : Change R3600 and R3601 to 100Kohm for power saving
NO5 Page28 : Disconnect RN25 part A & B for internal Pull up enabled and Add TP2804,TP2805
NO6 Page33 : Remove V_DAC connection of termination resistor
Page34 : Change Ethernet Switch connection to behind Transformer
Page38 : Change Ethernet Switch connection to behind Transformer
NO7 Page34 : Swap RN45's Pin 1 and Pin3 for layout
NO8 Page28 : Add C2800~2823 for EMI solution
NO9 Page40 : Change J5 connector requested by power team for burning issue.
NO10 Page22 : Change U82 to 06G004267010 to avoid use IBM's specified material.

R2.2 2006/01/16

NO1 Page33 : Recover V_DAC connection of termination resistor
Page34 : Change Ethernet Switch connection to before Transformer
Page38 : Change Ethernet Switch connection to before Transformer
NO2 Page17 : Add R1700~R1704 for EMI reserve
NO3 Page22 : Change R265,R266 to 30Kohm to meet Speaker's SPEC

Z62FP 2006/02/21

NO1
Page28: Delete R353,R355
Page28: Change CON11 to Intel CBB keyboard
NO2
Page32: Add U3200,U3201 to isolate 3 in 1 card signals
NO3
Page22: Delete CN1, instead by C2201~C2204
NO4
Page12,35: Delete Colay component: L1203, L46, L49, L51, L53

PCI INTERFACE

PCI_REQ#

MINIPCI PCI_REQ#3
10/100 PCI_REQ#2
CB&1394 PCI_REQ#1
MINIPCI(TV) PCI_REQ#0

IDSEL

MINIPCI PCI_AD19
CB&1394 PCI_AD17
10/100 PCI_AD16
MINIPCI(TV) PCI_AD18



Title : Revision List

Engineer: Vincent VY Huang

Size	Project Name	Rev
Custom	Z62Fp	1.0
Date: Wednesday, August 23, 2006	Sheet	67 of 69

REVISION LIST

- R2.02006/03/29
- 1

NO5

Page35

: Add JP3500 for Cost down USB power swtich
- NO6

Page22

: Change R1267, R1268 to 22ohm to avoid micro sound
- NO7

Page16

: Change C1600, U1600 to unmount component, R1602 to mounted component
- NO8

Page32

: Add RN3200, RN3201 to 1394 co-lay and set L42 to unmount component
- NO9

Page3

: Cost down 22uF to 10uF MLCCs, unmount CE1, CE4
CE54 change to use 100uF
- NO10

Page9

: Unmount CE8 for cost down
- NO11

Page10

: Change CE15, CE16, CE51, CE52, CE53 to 100uF for cost down
- NO12

Page20

: Unmount CE19, Change CE20 to 100uF for cost down
- NO13

Page26

: Unmount CE2601 for cost down
- 2

NO14

Page22

: Mount C1074 to enhance ESD protection
- NO15

Page

: Change Jumpers symbol which have 潤濕點
- NO16

Page17

: Change R1700, R1701, R1702, R1703, R1704 component size 0402 to 0603
- NO16

Page35

: Change Q47 component optional "/x"

REVISION LIST

R2.1 2006/07/19 (for vista)

- NO1 Page21 : Add C2101,C2102,C2103
Add R2124,R2125,R2127,R2129,R2130,R2132,R2133
Add Q2100(Q2100A,Q2100B),Q2101(Q2101A,Q2101B)
Change R474,R475 (2.2KOhm) to (2.49KOhm)
Add R2126,R2131 (unmount)
NO2 Page22 : Add Dual-lay mount CE7000,CE7001(CE21,CE22 unmount)
Change MIC JACK J2 (12G14030105N to 12G14030106L)
Add R2203,L7000
Add D7000,D7001,C7370 (unmount)
Move location to bottom side L35,C2200 (original top side)
NO3 Page23 : Move location to top side L2200 (original bottom side)
NO4 Page37 : Move location to bottom side D106 (original top side--unmount)
NO5 Page50 : Add C5030,C5031,R5057,R5058(Power circuit--unmount)
NO5 Page57 : Rotate R5704 90-degree(Power circuit)
Z62FM R2.0 2006/08/16
ER NO1: Page22 mute circuits inverted for vista default driver (Add Q2200)
ER NO2: Page22 solve external pop noise, +12VS delay, add C2205 and D2200, and change R270 to 1M ohm
ER NO3: Page35, solve external USB power leakage (Add Q47 mount)
JP3500 (unmount) change to R3400 (unmount)
ER NO4: Page22 solve internal pop noise, Change R271 to 470K Ohm, Add C2206=2.2uF

for Vista Jack sense feature

Meet Vista Audio Bandwidth requirement

For EMI solution

Avoid assembly short problem